

# 8-Bit CMOS Microcontrollers with A/D Converter

## Devices included in this data sheet:

- PIC16C710
- PIC16C71
- PIC16C711
- PIC16C715

## PIC16C71X Microcontroller Core Features:

- High-performance RISC CPU
- Only 35 single word instructions to learn
- All single cycle instructions except for program branches which are two cycle
- Operating speed: DC 20 MHz clock input DC - 200 ns instruction cycle
- Up to 2K x 14 words of Program Memory, up to 128 x 8 bytes of Data Memory (RAM)
- · Interrupt capability
- · Eight level deep hardware stack
- · Direct, indirect, and relative addressing modes
- Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- · Programmable code-protection
- · Power saving SLEEP mode
- · Selectable oscillator options
- Low-power, high-speed CMOS EPROM technology
- · Fully static design
- Wide operating voltage range: 2.5V to 6.0V
- High Sink/Source Current 25/25 mA
- Commercial, Industrial and Extended temperature ranges
- Program Memory Parity Error Checking Circuitry with Parity Error Reset (PER) (PIC16C715)
- Low-power consumption:
  - < 2 mA @ 5V, 4 MHz
  - 15 μA typical @ 3V, 32 kHz
  - < 1 μA typical standby current

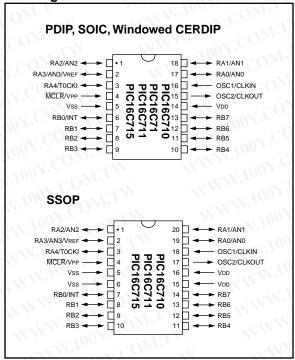
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# **PIC16C71X Peripheral Features:**

- Timer0: 8-bit timer/counter with 8-bit prescaler
- 8-bit multichannel analog-to-digital converter
- Brown-out detection circuitry for Brown-out Reset (BOR)
- 13 I/O Pins with Individual Direction Control

PIC16C7X Features	710	71	711	715
Program Memory (EPROM) x 14	512	1K	1K	2K
Data Memory (Bytes) x 8	36	36	68	128
I/O Pins	13	13	13	13
Timer Modules	1	1.	1	1
A/D Channels	4	4	4	4
In-Circuit Serial Programming	Yes	Yes	Yes	Yes
Brown-out Reset	Yes	$\mathbb{C}\overline{\mathbf{O}}_{L}$	Yes	Yes
Interrupt Sources	4	4	4	4

# **Pin Diagrams**



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# To Our Valued Customers

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# 1.0 GENERAL DESCRIPTION

The PIC16C71X is a family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers with integrated analog-to-digital (A/D) converters, in the PIC16CXX mid-range family.

All PIC16/17 microcontrollers employ an advanced RISC architecture. The PIC16CXX microcontroller family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with the separate 8-bit wide data. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches which require two cycles. A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16C710/71 devices have 36 bytes of RAM, the PIC16C711 has 68 bytes of RAM and the PIC16C715 has 128 bytes of RAM. Each device has 13 I/O pins. In addition a timer/counter is available. Also a 4-channel high-speed 8-bit A/D is provided. The 8-bit resolution is ideally suited for applications requiring low-cost analog interface, e.g. thermostat control, pressure sensing, etc.

The PIC16C71X family has special features to reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) feature provides a power saving mode. The user can wake up the chip from SLEEP through several external and internal interrupts and resets.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lockup.

A UV erasable CERDIP packaged version is ideal for code development while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC16C71X family fits perfectly in applications ranging from security and remote sensors to appliance control and automotive. The EPROM technology makes customization of application programs (transmitter codes, motor speeds, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low cost, low power, high performance, ease of use and I/O flexibility make the PIC16C71X very versatile even in areas where no microcontroller use has been considered before (e.g. timer functions, serial communication, capture and compare, PWM functions and coprocessor applications).

# 1.1 Family and Upward Compatibility

Users familiar with the PIC16C5X microcontroller family will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for the PIC16C5X can be easily ported to the PIC16CXX family of devices (Appendix B).

# 1.2 <u>Development Support</u>

PIC16C71X devices are supported by the complete line of Microchip Development tools.

Please refer to Section 10.0 for more details about Microchip's development tools.

TABLE 1-1: PIC16C71X FAMILY OF DEVICES

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72 <sup>(</sup>
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
	EPROM Program Memory (x14 words)	512	1K	1K	2K	2K	_
lemory	ROM Program Memory (14K words)	COMITY	_	WWI	ON.COM		2K
	Data Memory (bytes)	36	36	68	128	128	128
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/PWM Module(s)	ON CON	TW	- WW	4.100X.	1011	1
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	1001'CO	WI.W	- 111	TW.1007	SPI/I <sup>2</sup> C	SPI/I <sup>2</sup> C
	Parallel Slave Port	-100 X.C.	- 1711	- 1	Y 100	T.O.	<u> </u>
	A/D Converter (8-bit) Channels	4	4	4	4	5	5
	Interrupt Sources	4	4	4	4	8	8
	I/O Pins	13	13	13	13	22	22
	Voltage Range (Volts)	2.5-6.0	3.0-6.0	2.5-6.0	2.5-5.5	2.5-6.0	3.0-5.5
eatures	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
cataros	Brown-out Reset	Yes	- con	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP SOIC, SSOF

		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77	
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20 CON	
Memory	EPROM Program Memory (x14 words)	4K	4K	8K	8K	
	Data Memory (bytes)	192	192	376	376	
	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	
Peripherals	Capture/Compare/PWM Module(s)	2	2 N.100 Y.CO	2	2	
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	
	Parallel Slave Port	-(1)	Yes	TIME	Yes	
	A/D Converter (8-bit) Channels	5	8	5	8	
	Interrupt Sources	11	12	110	12	
	I/O Pins	22	33	22	33	
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0	
eatures	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	
oatui 00	Brown-out Reset	Yes	Yes	Yes	Yes	
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local Microchip sales office for availability of these devices.

# 2.0 PIC16C71X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C71X Product Identification System section at the end of this data sheet. When placing orders, please use that page of the data sheet to specify the correct part number.

For the PIC16C71X family, there are two device "types" as indicated in the device number:

- C, as in PIC16C71. These devices have EPROM type memory and operate over the standard voltage range.
- LC, as in PIC16LC71. These devices have EPROM type memory and operate over an extended voltage range.

## 2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the oscillator modes.

Microchip's PICSTART® Plus and PRO MATE® II programmers both support programming of the PIC16C71X.

# 2.2 <u>One-Time-Programmable (OTP)</u> Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

# 2.3 Quick-Turnaround-Production (QTP) <u>Devices</u>

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

# 2.4 <u>Serialized Quick-Turnaround</u> Production (SQTP<sup>SM</sup>) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random, or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password, or ID number.

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# 3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16CXX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16CXX uses a Harvard architecture, in which, program and data are accessed from separate memories using separate buses. This improves bandwidth over traditional von Neumann architecture in which program and data are fetched from the same memory using the same bus. Separating program and data buses further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A twostage pipeline overlaps fetch and execution of instructions (Example 3-1). Consequently, all instructions (35) execute in a single cycle (200 ns @ 20 MHz) except for program branches.

The table below lists program memory (EPROM) and data memory (RAM) for each PIC16C71X device.

Device	Program Memory	Data Memory
PIC16C710	512 x 14	36 x 8
PIC16C71	1K x 14	36 x 8
PIC16C711	1K x 14	68 x 8
PIC16C715	2K x 14	128 x 8

The PIC16CXX can directly or indirectly address its register files or data memory. All special function registers, including the program counter, are mapped in the data memory. The PIC16CXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC16CXX simple yet efficient. In addition, the learning curve is reduced significantly.

PIC16CXX devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between the data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register). The other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a  $\overline{\text{borrow}}$  bit and a  $\overline{\text{digit}}$   $\overline{\text{borrow}}$  out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

FIGURE 3-1: PIC16C71X BLOCK DIAGRAM

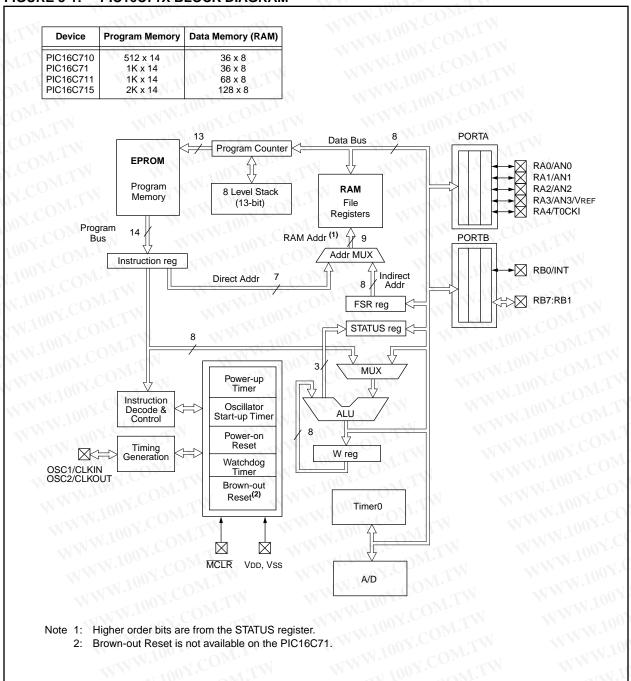


TABLE 3-1: PIC16C710/71/711/715 PINOUT DESCRIPTION

Pin Name	DIP Pin#	SSOP Pin# <sup>(4)</sup>	SOIC Pin#	I/O/P Type	Buffer Type	Description			
OSC1/CLKIN	16	18	16	OM.	ST/CMOS <sup>(3)</sup>	Oscillator crystal input/external clock source input.			
OSC2/CLKOUT	15	17	100 X	0	TAN -	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.			
MCLR/VPP	4	4	4	I/P	ST	Master clear (reset) input or programming voltage input. This pin is an active low reset to the device.			
WILL		MA.	×1 100	1	W.I.M	PORTA is a bi-directional I/O port.			
RA0/AN0	17	19	17	1/0	TTL	RA0 can also be analog input0			
RA1/AN1	18	20	18	I/O	TTL	RA1 can also be analog input1			
RA2/AN2	1	1	1	1/0	TTL	RA2 can also be analog input2			
RA3/AN3/VREF	2	2	2	I/O	TTL	RA3 can also be analog input3 or analog reference voltage			
RA4/T0CKI	3	3	3	I/O	ST	RA4 can also be the clock input to the Timer0 module. Output is open drain type.			
OA'COMP	W		WW	10	N.CO	PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.			
RB0/INT	6	7	6	1/0	TTL/ST <sup>(1)</sup>	RB0 can also be the external interrupt pin.			
RB1	7	8	7	1/0	TTL	NBO carr also be the external interrupt pin.			
RB2	8	9	8	1/0	100 TTL	MITH WY 100X. OM.TW			
RB3	9	N 10	9 🕥	1/0	TTLCC	TW WWW. CON. CO.			
RB4	10	11	10	1/0	TTL: C	Interrupt on change pin.			
RB5	11	12	11	1/0	ATTL	Interrupt on change pin.			
RB6	12	13	12	1/0	TTL/ST <sup>(2)</sup>	Interrupt on change pin.  Interrupt on change pin. Serial programming clock.			
RB7	13	14	13	1/0	TTL/ST <sup>(2)</sup>	Interrupt on change pin. Serial programming clock.  Interrupt on change pin. Serial programming data.			
Vss	5	4, 6	5	I/O	111/310	Ground reference for logic and I/O pins.			
VDD	14	15, 16	14	P	WW-	Positive supply for logic and I/O pins.			
עטע	14	15, 16	14	FW	100	Fusitive supply for logic and I/O pins.			

Legend: I = input

O = output

I/O = input/output

P = power

- = Not used

TTL = TTL input

ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

- 2: This buffer is a Schmitt Trigger input when used in serial programming mode.
- 3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.
- 4: The PIC16C71 is not available in SSOP package.

# 3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

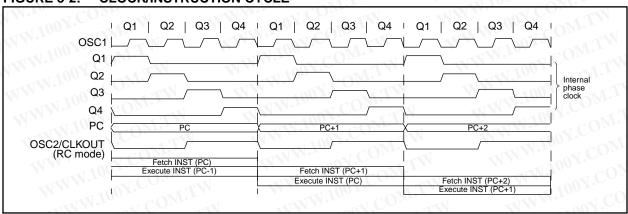
# 3.2 <u>Instruction Flow/Pipelining</u>

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. GOTO) then two cycles are required to complete the instruction (Example 3-1).

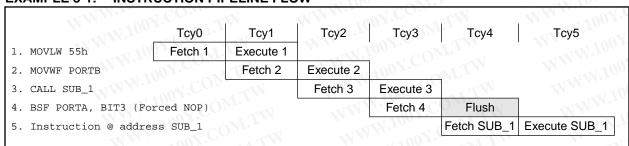
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register" (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).





# **EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW**



All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline while the new instruction is being fetched and then executed.

# 4.0 MEMORY ORGANIZATION

# 4.1 Program Memory Organization

The PIC16C71X family has a 13-bit program counter capable of addressing an 8K x 14 program memory space. The amount of program memory available to each device is listed below:

Device	Program Memory	Address Range
PIC16C710	512 x 14	0000h-01FFh
PIC16C71	1K x 14	0000h-03FFh
PIC16C711	1K x 14	0000h-03FFh
PIC16C715	2K x 14	0000h-07FFh

For those devices with less than 8K program memory, accessing a location above the physically implemented address will cause a wraparound.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 4-1: PIC16C710 PROGRAM MEMORY MAP AND STACK

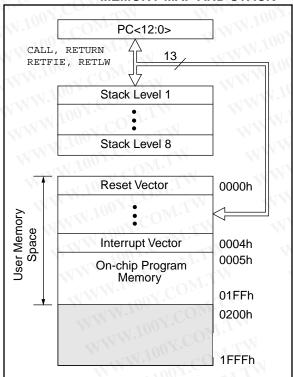


FIGURE 4-2: PIC16C71/711 PROGRAM MEMORY MAP AND STACK

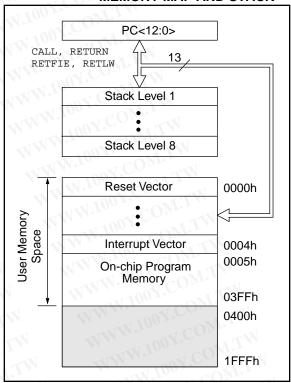
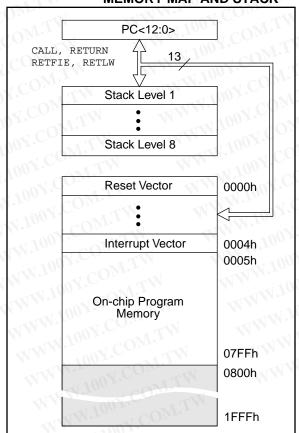


FIGURE 4-3: PIC16C715 PROGRAM MEMORY MAP AND STACK



# 4.2 <u>Data Memory Organization</u>

The data memory is partitioned into two Banks which contain the General Purpose Registers and the Special Function Registers. Bit RP0 is the bank select bit.

RP0 (STATUS<5>) =  $1 \rightarrow Bank 1$ 

RP0 (STATUS<5>) =  $0 \rightarrow Bank 0$ 

Each Bank extends up to 7Fh (128 bytes). The lower locations of each Bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers implemented as static RAM. Both Bank 0 and Bank 1 contain special function registers. Some "high use" special function registers from Bank 0 are mirrored in Bank 1 for code reduction and quicker access.

# 4.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR (Section 4.5).

FIGURE 4-4: PIC16C710/71 REGISTER FILE MAP

0h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	V	PCON <sup>(2)</sup>	87h
08h	ADCON0	ADCON1	88h
09h	ADRES	ADRES	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	General Purpose	General Purpose Register	8Ch
TW	Register	Mapped in Bank 0 <sup>(3)</sup>	M.TW
2Fh		M. DOX.C	AFh
03 03 04 04 04	M.T.W.	MM 710	
7Fh	OM.TV	TANAN	FFh
97.6	Bank 0	Bank 1	N.1007.
ote 1: 2: 3:	as '0'.  Not a physical re The PCON regis PIC16C71. These locations a	ter is not impleme are unimplemente ese locations will a	nted on the

FIGURE 4-5: PIC16C711 REGISTER FILE

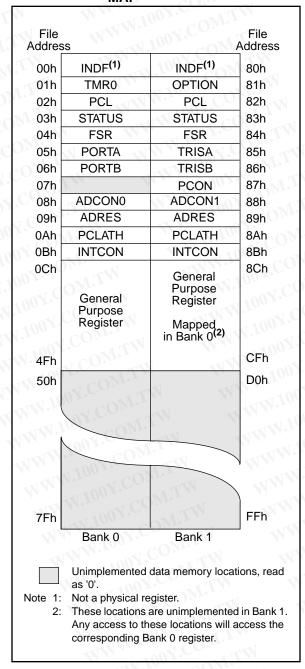


FIGURE 4-6: PIC16C715 REGISTER FILE MAP

	IVIAP		
File Address	CONT.IA		File Address
00h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	1007.60	WILL	87h
08h	N. CO	TIN	88h
09h	W.100 .	M. I	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh	100 x	OMITY	8Dh
0Eh	WW 100	PCON	8Eh
oFh	TWW.	A COM	8Fh
10h	W 10	COM	90h
11h	WW	107.C	91h
12h	MAN	ON COM	92h
13h	WINT.	TOO TOOM	93h
14h	W. W.	100,7.	94h
15h	MAN	OUN.CO.	95h
16h	TW	M. T. CC	96h
17h	7/1	W.100 -	97h
18h	W	1007.0	98h
19h	N N	WW.	99h
1Ah	-7	M. Joo	9Ah
1Bh	IN A	1003	9Bh
1Ch	TW	WWW.	9Ch
1Dh	. 1	TINN.IO	9Dh
1Eh	ADRES	111.10	9Eh
1Fh	ADCON0	ADCON1	9Fh
20h	General Purpose	General Purpose	A0h
1007.4	Register	Register	DEh
TOOY!	TW	M.V.	BFh
W.100	COM		C0h
1/1/100	COM		Min
MM.100	NY.COM.	N N	MMI
7Fh L	Bank 0	Bank 1	⊔ FFh
			WWW
a	nimplemented dat s '0'.	WTI	ns, read
Note 1: N	ot a physical regis	ter.	

### 4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral Modules for controlling the desired operation of the device. These registers are implemented as static RAM. The special function registers can be classified into two sets (core and peripheral). Those registers associated with the "core" functions are described in this section, and those related to the operation of the peripheral features are described in the section of that peripheral feature.

TABLE 4-1: PIC16C710/71/711 SPECIAL FUNCTION REGISTER SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets (1)
Bank 0	Mil	1		100	COM	-XX	NV.	111.100	V.CO	NI-	
00h <sup>(3)</sup>	INDF	Addressing	this location	uses conte	register)	0000 0000	0000 0000				
01h	TMR0	Timer0 mod	dule's register	xxxx xxxx	uuuu uuuu						
02h <sup>(3)</sup>	PCL	Program Co	ounter's (PC)	Least Sign	ificant Byte	1.TW		N VV	100 X.C	0000 0000	0000 0000
03h <sup>(3)</sup>	STATUS	IRP <sup>(5)</sup>	RP1 <sup>(5)</sup>	RP0	TO	PD	Z	DC	C	0001 1xxx	000q quuu
04h <sup>(3)</sup>	FSR	Indirect data	a memory ad	dress poin	ter	) III	N	MIN	100	xxxx xxxx	uuuu uuuu
05h	PORTA		_	WHV.	PORTA Dat	a Latch whe	en written: PO	RTA pins wh	nen read	x 0000	u 0000
06h	PORTB	PORTB Da	ta Latch wher	n written: P	ORTB pins w	nen read		-311	MAITO	xxxx xxxx	uuuu uuuu
07h	007	Unimpleme	nted	M 4.	W.100 1.	MOD	In		M.W.	TCO1	1.1
08h	ADCON0	ADCS1	ADCS0	(6)	CHS1	CHS0	GO/DONE	ADIF	ADON	00-0 0000	00-0 0000
09h <sup>(3)</sup>	ADRES	A/D Result	Register		1111	Y.Co.	WILL	1	MM	xxxx xxxx	uuuu uuuu
0Ah <sup>(2,3)</sup>	PCLATH	$CO_{Z_{I}}$	cvi <del>-</del>	-01	Write Buffe	for the upp	er 5 bits of the	e Program C	Counter	0 0000	0 0000
0Bh <sup>(3)</sup>	INTCON	GIE	ADIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
Bank 1	W.100	CON	1.1		TININ.	- ×1 (	OM	(X)	VIV	M.In	COM
80h <sup>(3)</sup>	INDF	Addressing	this location	uses conte	ents of FSR to	address da	ta memory (no	ot a physical	register)	0000 0000	0000 0000
81h	OPTION	RBPU	INTEDG	T0CS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h <sup>(3)</sup>	PCL	Program Co	ounter's (PC)	Least Sign	ificant Byte	100	Y.Co	TW	V	0000 0000	0000 0000
83h <sup>(3)</sup>	STATUS	IRP <sup>(5)</sup>	RP1 <sup>(5)</sup>	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
84h <sup>(3)</sup>	FSR	Indirect data	a memory ad	dress poin	ter	MAN	ON.CO	WT	•	xxxx xxxx	uuuu uuuu
85h	TRISA	11.700	COM	3	PORTA Dat	a Direction	Register	Mr.	N	1 1111	1 1111
86h	TRISB	PORTB Da	ta Direction C	ontrol Reg	ister	W.	100 3.	OM	- 1	1111 1111	1111 1111
87h <sup>(4)</sup>	PCON	<del>-1</del> 10	7	V.IN	_		11001	POR	BOR	qq	uu
88h	ADCON1	1117	NO Y-CO	177	N —	MA,	1007	PCFG1	PCFG0	00	00
89h <sup>(3)</sup>	ADRES	A/D Result	Register	) INT.	W	WW	1003	CO.	WT	xxxx xxxx	uuuu uuuu
8Ah <sup>(2,3)</sup>	PCLATH	WW.	100 V.Q	$O_{\overline{M}}$ .	Write Buffe	for the upp	er 5 bits of the	e Program C	Counter	0 0000	0 0000
8Bh <sup>(3)</sup>	INTCON	GIE	ADIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented read as '0'. Shaded locations are unimplemented, read as '0'.

- Note 1: Other (non power-up) resets include external reset through MCLR and Watchdog Timer Reset.
  - 2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.
  - 3: These registers can be addressed from either bank.
  - 4: The PCON register is not physically implemented in the PIC16C71, read as '0'.
  - 5: The IRP and RP1 bits are reserved on the PIC16C710/71/711, always maintain these bits clear.
  - 6: Bit5 of ADCON0 is a General Purpose R/W bit for the PIC16C710/711 only. For the PIC16C71, this bit is unimplemented, read as '0'.

TABLE 4-2: PIC16C715 SPECIAL FUNCTION REGISTER SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR, PER	Value on all other resets (3)
Bank 0	4	-XVI.10	103	$M_{JJ}$		TANK Y	N.100	COM.	1		
00h <sup>(1)</sup>	INDF	Addressing	this location	uses conte	nts of FSR to	address data	a memory (no	ot a physica	l register)	0000 0000	0000 0000
01h	TMR0	Timer0 mod	ule's registe	r		MAN	100		N.T.W	xxxx xxxx	uuuu uuuu
02h <sup>(1)</sup>	PCL	Program Co	unter's (PC)	TW	0000 0000	0000 0000					
03h <sup>(1)</sup>	STATUS	IRP <sup>(4)</sup>	RP1 <sup>(4)</sup>	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
04h <sup>(1)</sup>	FSR	Indirect data	memory ac	ldress point	er		L.WW.	100 ×	$O_{M^{*}r}$	xxxx xxxx	uuuu uuuu
05h	PORTA	4111		nen read	x 0000	u 0000					
06h	PORTB	PORTB Data Latch when written: PORTB pins when read									uuuu uuuu
07h	- <del> </del>	Unimplemen	nted	('Coh	TV	_					
08h	U.T.	Unimplemen	nted	100	OM		-TIN	M.Ing	CON	V . V	_
09h	W.I.W	Unimplemen	nted	700 x.	COM.		44	W.100	, c0	11.1	_
0Ah <sup>(1,2)</sup>	PCLATH	_	MAI	1007	Write Buffe	r for the uppe	er 5 bits of the	Program C	Counter	0 0000	0 0000
0Bh <sup>(1)</sup>	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1		ADIF	41 700	of GON	-TN	- 4	NATA.	~~\ <del>~</del> \.	-0	-0
0Dh	Mo	Unimplemen	nted	Jun	$CO_{\overline{M}}$	- I					
0Eh		Unimplemen	nted	CO#1.7	_						
0Fh	(CD)	Unimplemen	Unimplemented								$\mathcal{C}_{M}$
10h	√ €0	Unimplemen	nted	WWW	.V.o	Obs	W	WV	14.5	N.CO	417
11h	<del>-</del> c(	Unimplemen	nted	TINY	N. Ton	$CO_{M_{I}}$ ,		-317	MMila	~ €ON	~ <del>\</del>
12h	00.7	Unimplemen	nted	11	W.100 x	MOD	7.7.		WW.1	70	M. L
13h	1007.0	Unimplemen	nted	MA	100	I.U.	LTN.	V	N N	1007	$T_{M}$
14h	· VITO	Unimplemen	nted	W	N A	M.Co.	WTI	4	MM	100¥.C	
15h	1.700	Unimplemen	nted	**	MAIN	ON CO	WIT		WWW	1 0TT V.C	- W
16h	N.MO	Unimplemen	nted		T.WW.	-1 C.	OM	XI	TIW.	(1.10	$CO_{\overline{M_1}}$
17h	70 <del>/</del> 00	Unimplemen	nted		N V	1001.	'OM'I'	N .	A	101.100	COM!
18h	14.	Unimplemen	nted		MM	100 X.	TM	V	MA	400	ME
19h	MATIN	Unimplemen	nted		MMM	You	COM	rW	W	444	A.C.
1Ah	N.	Unimplemen	Unimplemented								M.€Op
1Bh	= 1	Unimplemen	nplemented						7	1.V <del>+</del> V.1	-πCO
1Ch	MA,	Unimplemer	mplemented								00 = _
1Dh	WEN	Unimplemen	Unimplemented							41 1	1002/10
1Eh	ADRES	A/D Result F	Register	TV	V.	MW.	oov.CC	) IV	N	xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	$O\overline{M}_{*,*}$	ADON	0000 00-0	0000 00-0

Legend: x = unknown, u = unchanged, q = value depends on condition, -= unimplemented read as '0'. Shaded locations are unimplemented, read as '0'.

- Note 1: These registers can be addressed from either bank.
  - 2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.
  - 3: Other (non power-up) resets include external reset through MCLR and Watchdog Timer Reset.
  - 4: The IRP and RP1 bits are reserved on the PIC16C715, always maintain these bits clear.

TABLE 4-2: PIC16C715 SPECIAL FUNCTION REGISTER SUMMARY (Cont.'d)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR, PER	Value on all other resets (3)
Bank 1	•	1	N.100 x	COM	LA		WW.10	=1 CC	Mr.	sī.	•
80h <sup>(1)</sup>	INDF	Addressing	this location	l register)	0000 0000	0000 0000					
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h <sup>(1)</sup>	PCL	Program C	ounter's (PC)	Least Sign	ificant Byte		MAIN	· You	Con	0000 0000	0000 0000
83h <sup>(1)</sup>	STATUS	IRP <sup>(4)</sup>	RP1 <sup>(4)</sup>	RP0	ТО	PD	Z	DC	СС	0001 1xxx	000q quuu
84h <sup>(1)</sup>	FSR	Indirect dat	ta memory ad	xxxx xxxx	uuuu uuuu						
85h	TRISA	_	11/1	11 1111	11 1111						
86h	TRISB	PORTB Da	ata Direction R	Register	COM	TW	W	N 41.	OY.Co	1111 1111	1111 1111
87h	DMF	Unimpleme	ented	A Tan	A COM.	- N	11	MMir	any.C	W. T. W.	_
88h	ON.T	Unimpleme	ented	W.100	CON	-1		TANW.	~<1 (	OM.	_
89h		Unimpleme	ented	-XI 10	01.	V.I.M		N T	700 7.	101 <u>4</u> 17	
8Ah <sup>(1,2)</sup>	PCLATH	TVI	-01	N	Write Buffe	r for the uppe	er 5 bits of th	e PC	1100Y	0 0000	0 0000
8Bh <sup>(1)</sup>	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1		ADIE	TAN-	3100	0M.	- N	-T 1	11.70	-0	-0
8Dh	07.7	Unimpleme	ented	N T	1.100 2	COMIT	-1	1	VW.10	-1 ( <del>-</del> OM	. <del></del> .
8Eh	PCON	MPEEN	_	MA	1007	-M.	PER	POR	BOR	u1qq	u1uu
8Fh	O.Z.C	Unimpleme	ented	WW	44.	COM	TW	V	W. A.	107	W. FW
90h	<u>-</u> 57	Unimpleme	ented	TAT V	Min	A COM	WW	-	MMM.	" on t.Ct	WITT
91h	100,	Unimpleme	ented	- 1	M.100	-1 CO	VI.		WW	F C	ONF.
92h	×1 1007	Unimpleme	ented	M	W.10	001.	$M_{JJM}$		NV T	1100	·OM.
93h	400	Unimpleme	ented	1	NAME OF TAXABLE PARTY.	00 X.C.	TIME		MAA	100 Y	T.1/ <del>T</del> 0.7
94h	Min	Unimpleme	ented		WWW	any.C	On T	W	WV	T005	.CO
95h	W/# 10	Unimpleme	ented		TOWN.	Jon	$CO_{M_{Tr.}}$	- VN	W.	11115	$^{\Lambda}$ $C_{\overline{O}_{M_{r}}}$
96h	- <del> </del>	Unimpleme	ented	- 7		N.100	COM.	, <b>1</b> '		TON INTERNA	A CON
97h	111	Unimpleme	ented	N	MA	3X 1003		LTV.	7	1.W	-CO
98h	WAN	Unimpleme	ented	N	WW	100	N.Co.	TW		WW 1	007-
99h	TANK T	Unimpleme	ented	TW	W	MAN	NY.CO	W		MAN	100\$ Ct
9Ah	= 41	Unimpleme	ented	I V		WW.M	ost C	Divi	N	WFW	7 V C
9Bh	A A	Unimpleme	ented	[.1.4.		TIN!	00 -	OM.	-=T	= 11	1.700
9Ch	<u> </u>	Unimpleme	ented	WILL	4	MAN	100 X.F	-ovi.	44	W.	W. 100 Y
9Dh	-41	Unimpleme	ented	TV	N .	MMM	-100Y	Co	TW	411	700
9Eh	_	Unimpleme	ented	)Nr.,	CN .	WW	N.100	1.COM	TV	-01	144-
9Fh	ADCON1		1007	ONT			1/ 700	PCFG1	PCFG0	00	00

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented read as '0'. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

- 2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.
- 3: Other (non power-up) resets include external reset through MCLR and Watchdog Timer Reset.
- 4: The IRP and RP1 bits are reserved on the PIC16C715, always maintain these bits clear.

#### 4.2.2.1 STATUS REGISTER

### **Applicable Devices** 710 71 711 715

The STATUS register, shown in Figure 4-7, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper-three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

- Note 1: For those devices that do not use bits IRP and RP1 (STATUS<7:6>), maintain these bits clear to ensure upward compatibility with future products.
- Note 2: The C and DC bits operate as a borrow and digit borrow bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

#### FIGURE 4-7: STATUS REGISTER (ADDRESS 03h, 83h)

IRP	RP1		R-1	R-1	R/W-x	R/W-x	R/W-x	CONT.
	KEI	RP0	TO	PD	Z	DC	C	R = Readable bit
oit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
101	= Bank 2	ster Bank 2, 3 (100h 0, 1 (00h -	- 1FFh)	(used for	indirect add	dressing)		MMM.100X.COW.

11 = Bank 3 (180h - 1FFh)

10 = Bank 2 (100h - 17Fh)

01 = Bank 1 (80h - FFh)

00 = Bank 0 (00h - 7Fh)

Each bank is 128 bytes

bit 4: TO: Time-out bit

1 = After power-up, CLRWDT instruction, or SLEEP instruction

0 = A WDT time-out occurred

PD: Power-down bit bit 3:

1 = After power-up or by the CLRWDT instruction

0 = By execution of the SLEEP instruction

bit 2: Z: Zero bit

1 = The result of an arithmetic or logic operation is zero

0 = The result of an arithmetic or logic operation is not zero

bit 1: DC: Digit carry/borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)(for borrow the polarity is reversed)

1 = A carry-out from the 4th low order bit of the result occurred

0 = No carry-out from the 4th low order bit of the result

C: Carry/borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions) bit 0:

1 = A carry-out from the most significant bit of the result occurred

0 = No carry-out from the most significant bit of the result occurred

Note: For borrow the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low order bit of the source register.

### 4.2.2.2 OPTION REGISTER

Applicable Devices 710 71 711 715

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the External INT Interrupt, TMR0, and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer by setting bit PSA (OPTION<3>).

# FIGURE 4-8: OPTION REGISTER (ADDRESS 81h, 181h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	R = Readable bit
oit7	M.TW	,	WWW.	100 <sup>X</sup> .C	OM.TY		bit0	W = Writable bit U = Unimplemented bi read as '0' - n = Value at POR rese
oit 7:		B pull-up	s are disal	oled	ividual port	latch valu	es W	
bit 6:	INTEDG: 1 = Interru 0 = Interru	upt on risi	ng edge o	RB0/INT				
bit 5:	TOCS: TM 1 = Transi 0 = Intern	tion on R	A4/T0CKI	pin	(OUT)			
bit 4:		nent on h	igh-to-low	transition	on RA4/T00 on RA4/T00			
bit 3:	PSA: Pres	scaler Ass	signment k	oit 🕠				

. – . rescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module
bit 2-0: **PS2:PS0:** Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1:2	4:1
001	1:4	1:2
010	1:8	1:4
011	1:16	1:8
100	1:32	1:16
101	1:64	1:32
110	1:128	1:64
111	1:256	1:128

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### 4.2.2.3 INTCON REGISTER

# Applicable Devices 710 71 711 715

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and External RB0/INT pin interrupts.

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

Note:

# FIGURE 4-9: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

GIE it7	ADIE	TOIE	INTE	KDIE	TUIF	IINTE	bit0
CIE	ADIE	TOIE	INTE	RBIE	TOIF	INTE	RBIF
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x

R = Readable bit W = Writable bit

U = Unimplemented bit, read as '0' - n = Value at POR reset

bit 7: GIE:<sup>(1)</sup> Global Interrupt Enable bit

1 = Enables all un-masked interrupts

0 = Disables all interrupts

bit 6: ADIE: A/D Converter Interrupt Enable bit

1 = Enables A/D interrupt 0 = Disables A/D interrupt

bit 5: T0IE: TMR0 Overflow Interrupt Enable bit

1 = Enables the TMR0 interrupt

0 = Disables the TMR0 interrupt

bit 4: INTE: RB0/INT External Interrupt Enable bit

1 = Enables the RB0/INT external interrupt

0 = Disables the RB0/INT external interrupt

bit 3: RBIE: RB Port Change Interrupt Enable bit

1 = Enables the RB port change interrupt

0 = Disables the RB port change interrupt

bit 2: T0IF: TMR0 Overflow Interrupt Flag bit

1 = TMR0 register has overflowed (must be cleared in software)

0 = TMR0 register did not overflow

bit 1: INTF: RB0/INT External Interrupt Flag bit

1 = The RB0/INT external interrupt occurred (must be cleared in software)

0 = The RB0/INT external interrupt did not occur

bit 0: RBIF: RB Port Change Interrupt Flag bit

1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)

0 = None of the RB7:RB4 pins have changed state

Note 1: For the PIC16C71, if an interrupt occurs while the GIE bit is being cleared, the GIE bit may be unintentionally re-enabled by the RETFIE instruction in the user's Interrupt Service Routine. Refer to Section 8.5 for a detailed description.

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

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#### 4.2.2.4 PIE1 REGISTER

710 71 711 715 Applicable Devices

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

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This register contains the individual enable bits for the Peripheral interrupts.

# FIGURE 4-10: PIE1 REGISTER (ADDRESS 8Ch)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
bit7	ADIE	<del></del>	WW-	ON CON			bit0

= Readable bit = Writable bit W

= Unimplemented bit, read as '0'

n = Value at POR reset

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bit 7: Unimplemented: Read as '0'

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bit 6: ADIE: A/D Converter Interrupt Enable bit

1 = Enables the A/D interrupt 0 = Disables the A/D interrupt bit 5-0: Unimplemented: Read as '0'

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#### 4.2.2.5 PIR1 REGISTER

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### **Applicable Devices** 710 71 711 715

This register contains the individual flag bits for the Peripheral interrupts.

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

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# FIGURE 4-11: PIR1 REGISTER (ADDRESS 0Ch)

100X.COM	IGURE 4	1-11: PIR	1 REGIS	TER (AI	DDRESS	6 0Ch)	MMM.	100 Y.C	CONTW
1.TOO Y.CC	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	
W.100	$ON\overline{r}_{r}$	ADIF	TW	1.17	$^{L}C_{\overline{O}_{Mr}}$		<del>-</del> 111	M. P.	R = Readable bit
MM.1002.	bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
WW.100	bit 7:	Unimplen	nented: Re	ead as '0'					ON.COM TW
MMM.100	bit 6:	<b>ADIF:</b> A/D 1 = An A/D 0 = The A	onversi	on compl	eted	COWIL			
11	bit 5-0:	Unimplen	nented: Re	ead as '0'					

Note:

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### 4.2.2.6 PCON REGISTER

# Applicable Devices 710 71 711 715

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external MCLR Reset or WDT Reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset (BOR) condition from a Power-on Reset condition. For the PIC16C715 the PCON register also contains status bits MPEEN and PER. MPEEN reflects the value of the MPEEN bit in the configuration word. PER indicates a parity error reset has occurred.

BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if BOR is clear, indicating a brown-out has occurred. The BOR status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

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# FIGURE 4-12: PCON REGISTER (ADDRESS 8Eh), PIC16C710/711

1. 11.7	-7		-31		110			1.10
100	7.	- 1 A	_	<u> </u>	20 Ti)0 ,	M <sub>=</sub>	POR	BOR
U	-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

n = Value at POR reset

bit 7-2: Unimplemented: Read as '0'

bit 1: **POR:** Power-on Reset Status bit 1 = No Power-on Reset occurred

0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

Note:

bit 0: BOR: Brown-out Reset Status bit

1 = No Brown-out Reset occurred

0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

# FIGURE 4-13: PCON REGISTER (ADDRESS 8Eh), PIC16C715

R-U	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-q	
MPEEN	$\sqrt{N_{N+2}}$	~~ <del>~</del> .C	) In = -	V —	PER	POR	BOR <sup>(1)</sup>	R :
bit7	-111	100	OMIL	- 4		1.100	bit0	W :
								U :

R = Readable bit
W = Writable bit

U = Unimplemented bit, read as '0'n = Value at POR reset

bit 7: MPEEN: Memory Parity Error Circuitry Status bit
Reflects the value of configuration word bit, MPEEN

bit 6-3: Unimplemented: Read as '0'

bit 2: **PER:** Memory Parity Error Reset Status bit

1 = No Error occurred

0 = Program Memory Fetch Parity Error occurred (must be set in software after a Parity Error Reset)

bit 1: **POR:** Power-on Reset Status bit 1 = No Power-on Reset occurred

0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

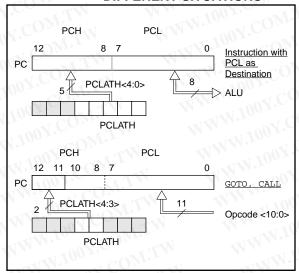
bit 0: **BOR:** Brown-out Reset Status bit 1 = No Brown-out Reset occurred

0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

## 4.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The upper bits (PC<12:8>) are not readable, but are indirectly writable through the PCLATH register. On any reset, the upper bits of the PC will be cleared. Figure 4-14 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0>  $\rightarrow$  PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3>  $\rightarrow$  PCH).

FIGURE 4-14: LOADING OF PC IN
DIFFERENT SITUATIONS



## 4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note "Implementing a Table Read" (AN556).

### 4.3.2 STACK

The PIC16CXX family has an 8 level deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

- Note 1: There are no status bits to indicate stack overflow or stack underflow conditions.
- Note 2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW, and RETFIE instructions, or the vectoring to an interrupt address.

# 4.4 Program Memory Paging

The PIC16C71X devices ignore both paging bits (PCLATH<4:3>, which are used to access program memory when more than one page is available. The use of PCLATH<4:3> as general purpose read/write bits for the PIC16C71X is not recommended since this may affect upward compatibility with future products.

Example 4-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that PCLATH is saved and restored by the interrupt service routine (if interrupts are used).

# EXAMPLE 4-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

```
ORG 0x500
BSF
       PCLATH, 3
                  ;Select page 1 (800h-FFFh)
BCF
       PCLATH, 4
                  ;Only on >4K devices
                  ;Call subroutine in
CALL
       SUB1_P1
                  ;page 1 (800h-FFFh)
ORG 0x900
SUB1 P1:
                  ; called subroutine
                  ;page 1 (800h-FFFh)
RETURN
                  return to Call subroutine
                  in page 0 (000h-7FFh)
```

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# 4.5 <u>Indirect Addressing, INDF and FSR</u> <u>Registers</u>

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

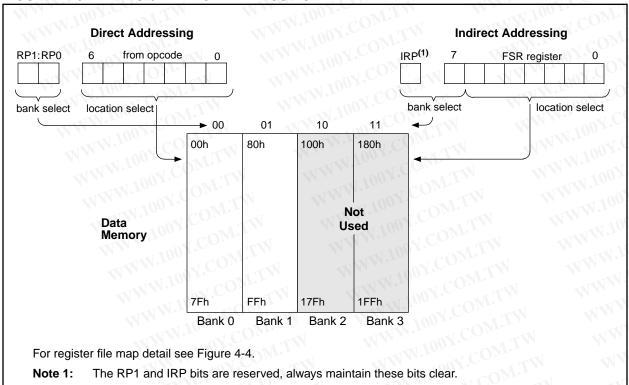
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself indirectly (FSR = '0') will read 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-15. However, IRP is not used in the PIC16C71X devices.

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 4-2.

# **EXAMPLE 4-2: INDIRECT ADDRESSING**

```
movlw
                 0 \times 20
                         ;initialize pointer
                         ito RAM
          movwf
                 FSR
NEXT
                         ;clear INDF register
          clrf
                 INDF
          incf
                 FSR,F
                         ;inc pointer
          btfss
                 FSR,4
                        ;all done?
          goto
                 NEXT
                         ino clear next
CONTINUE
                           ;yes continue
```

## FIGURE 4-15: DIRECT/INDIRECT ADDRESSING



# **5.0 I/O PORTS**

# **Applicable Devices** | 710 | 71 | 711 | 715

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

# 5.1 PORTA and TRISA Registers

PORTA is a 5-bit latch.

The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers) which can configure these pins as output or input.

Setting a TRISA register bit puts the corresponding output driver in a hi-impedance mode. Clearing a bit in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore a write to a port implies that the port pins are read, this value is modified, and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin.

Other PORTA pins are multiplexed with analog inputs and analog VREF input. The operation of each pin is selected by clearing/setting the control bits in the ADCON1 register (A/D Control Register1).

**Note:** On a Power-on Reset, these pins are configured as analog inputs and read as '0'.

The TRISA register controls the direction of the RA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

# **EXAMPLE 5-1: INITIALIZING PORTA**

BCF STATUS, RPO ; Initialize PORTA by PORTA CLRF ; clearing output ; data latches ; Select Bank 1 BSF STATUS, RPO 0xCFMOVLW ; Value used to ; initialize data ; direction MOVWF TRISA ; Set RA<3:0> as inputs ; RA<4> as outputs ; TRISA<7:5> are always ; read as '0'.

FIGURE 5-1: BLOCK DIAGRAM OF RA3:RA0 PINS

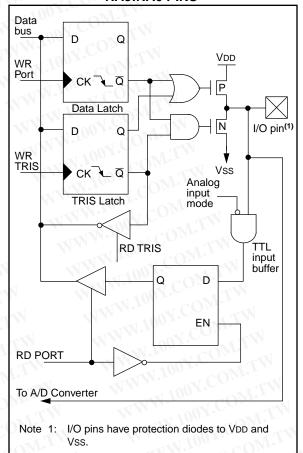
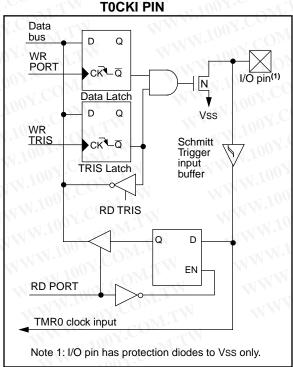


FIGURE 5-2: BLOCK DIAGRAM OF RA4/



**TABLE 5-1: PORTA FUNCTIONS** 

Name	Bit#	Buffer	Function
RA0/AN0	bit0	TTL	Input/output or analog input
RA1/AN1	bit1	TTL	Input/output or analog input
RA2/AN2	bit2	TITE 00	Input/output or analog input
RA3/AN3/VREF	bit3	TTL	Input/output or analog input/VREF
RA4/T0CKI	bit4	ST	Input/output or external clock input for Timer0 Output is open drain type

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TABLE :	J-2. SC	JIVIIVIAI	XI OF	KEGIS	TERS AS	SOCIA	ED WIII	n POKI.	40 -		
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
05h	PORTA	_	-1/1		RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
85h	TRISA	V -	- 1	111	PORTA I	Data Direct	ion Regist	er	10	1 1111	1 1111
9Fh	ADCON1			M TI W	· Vrno.			PCFG1	PCFG0	00	00

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# 5.2 PORTB and TRISB Registers

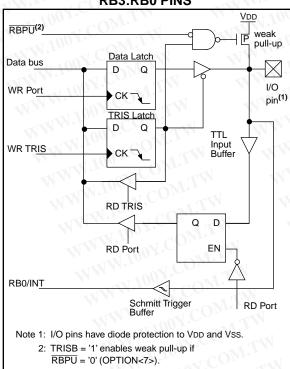
PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a bit in the TRISB register puts the corresponding output driver in a hi-impedance input mode. Clearing a bit in the TRISB register puts the contents of the output latch on the selected pin(s).

## **EXAMPLE 5-2: INITIALIZING PORTB**

```
BCF
       STATUS, RPO
                     ; Initialize PORTB by
CLRF
       PORTB
                     ; clearing output
                     ; data latches
BSF
       STATUS, RP0
                     ; Select Bank 1
MOVLW
      0xCF
                     ; Value used to
                     ; initialize data
                       direction
MOVWF
       TRISB
                       Set RB<3:0> as inputs
                      RB<5:4> as outputs
                     ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit RBPU (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

FIGURE 5-3: BLOCK DIAGRAM OF RB3:RB0 PINS



Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e. any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

- a) Any read or write of PORTB. This will end the mismatch condition.
- b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a keypad and make it possible for wake-up on key-depression. Refer to the Embedded Control Handbook, "Implementing Wake-Up on Key Stroke" (AN552).

Note: For the PIC16C71
if a change on the I/O pin should occur
when the read operation is being executed
(start of the Q2 cycle), then interrupt flag bit
RBIF may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-4: BLOCK DIAGRAM OF RB7:RB4 PINS (PIC16C71)

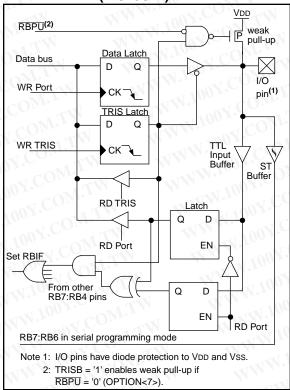


FIGURE 5-5: BLOCK DIAGRAM OF RB7:RB4 PINS (PIC16C710/711/715)

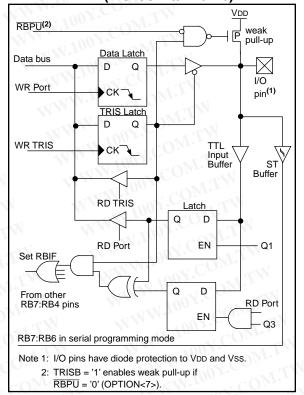


TABLE 5-3: PORTB FUNCTIONS

Name	Bit#	Buffer	Function
RB0/INT	bit0	TTL/ST <sup>(1)</sup>	Input/output pin or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	CITL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	OOY TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TOOLLIS	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB5	bit5	V.100TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST <sup>(2)</sup>	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming clock.
RB7	bit7	TTL/ST <sup>(2)</sup>	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in serial programming mode.

SUMMARY OF REGISTERS ASSOCIATED WITH PORTB **TABLE 5-4:** 

W	11/11/1	11200	- 601			- 200	1100	7.0	oM. <sup>7</sup>	BOR
06h, 106h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	XXXX XXX
86h, 186h	TRISB	PORTB	Data Direction	on Regist	er	W	111.	OOY.	Cor	1111 1111
81h, 181h	OPTION	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111

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# 5.3 **I/O Programming Considerations**

## 5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched to an output, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-3 shows the effect of two sequential readmodify-write instructions on an I/O port.

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# EXAMPLE 5-3: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial PORT settings: PORTB<7:4> Inputs
                        PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
                     PORT latch PORT pins
 BCF PORTB,
                    01pp pppp
 BCF PORTB, 6
                     10pp pppp
                                  11pp pppp
 BSF STATUS, RPO
 BCF TRISB, 7
                   ; 10pp pppp
                                  11pp pppp
                   ; 10pp pppp
 BCF TRISB, 6
                                  10pp pppp
```

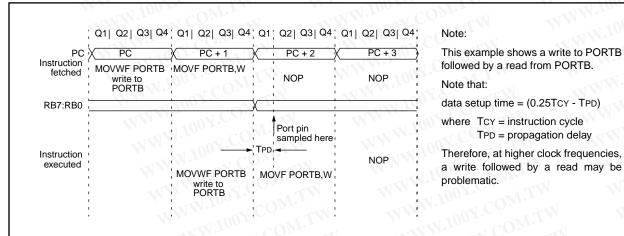
;Note that the user may have expected the ;pin values to be 00pp ppp. The 2nd BCF ;caused RB7 to be latched as the pin value ;(high).

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

## 5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-6). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

## FIGURE 5-6: SUCCESSIVE I/O OPERATION



# 6.0 TIMERO MODULE

# **Applicable Devices** | 710 | 71 | 711 | 715

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- · Readable and writable
- 8-bit software programmable prescaler
- · Internal or external clock select
- · Interrupt on overflow from FFh to 00h
- · Edge select for external clock

Figure 6-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing bit T0CS (OPTION<5>). In timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If the TMR0 register is written, the increment is inhibited for the following two instruction cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting bit T0CS (OPTION<5>). In counter mode, Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the Timer0 Source Edge Select bit T0SE (OPTION<4>). Clearing

bit TOSE selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.2.

The prescaler is mutually exclusively shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by control bit PSA (OPTION<3>). Clearing bit PSA will assign the prescaler to the Timer0 module. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4, ..., 1:256 are selectable. Section 6.3 details the operation of the prescaler.

# 6.1 Timer0 Interrupt

The TMR0 interrupt is generated when the TMR0 register overflows from FFh to 00h. This overflow sets bit T0IF (INTCON<2>). The interrupt can be masked by clearing bit T0IE (INTCON<5>). Bit T0IF must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The TMR0 interrupt cannot awaken the processor from SLEEP since the timer is shut off during SLEEP. See Figure 6-4 for Timer0 interrupt timing.

FIGURE 6-1: TIMERO BLOCK DIAGRAM

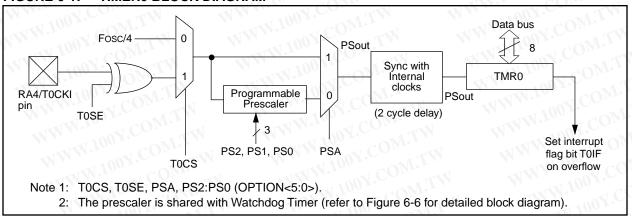


FIGURE 6-2: TIMERO TIMING: INTERNAL CLOCK/NO PRESCALE

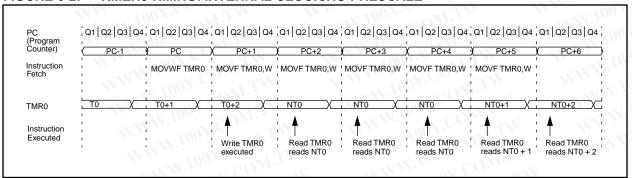
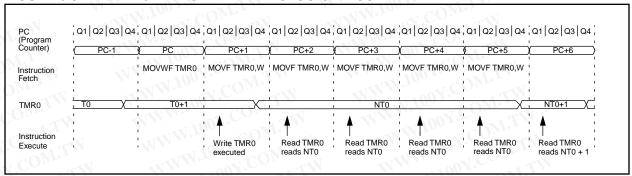
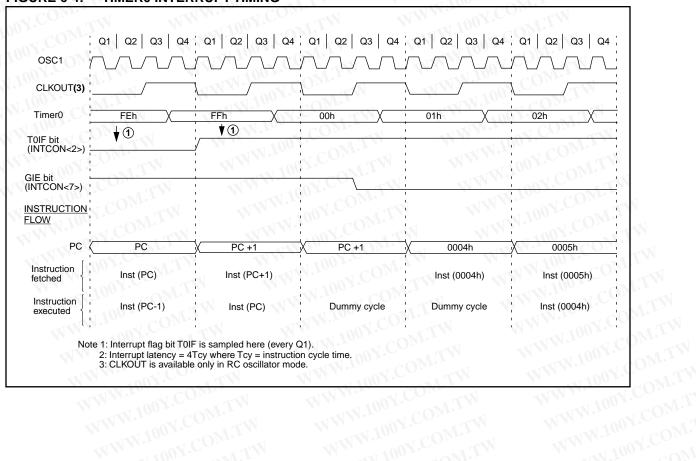


FIGURE 6-3: TIMERO TIMING: INTERNAL CLOCK/PRESCALE 1:2



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# FIGURE 6-4: TIMERO INTERRUPT TIMING



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# 6.2 <u>Using Timer0 with an External Clock</u>

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (Tosc). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

### 6.2.1 EXTERNAL CLOCK SYNCHRONIZATION

When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

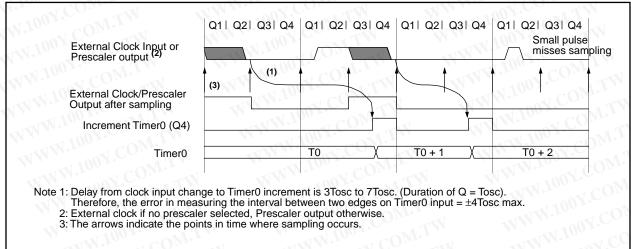
When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type pres-

caler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

### 6.2.2 TMR0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 6-5 shows the delay from the external clock edge to the timer incrementing.





# 6.3 Prescaler

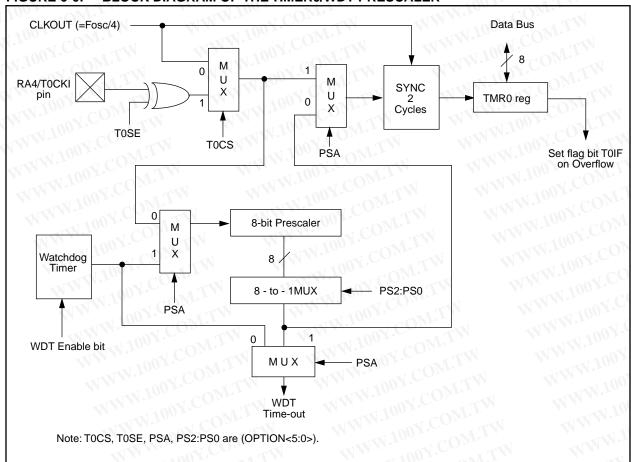
An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 6-6). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that there is only one prescaler available which is mutually exclusively shared between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer, and vice-versa.

The PSA and PS2:PS0 bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g. CLRF 1, MOVWF 1, BSF 1, x....etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.

**Note:** Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count, but will not change the prescaler assignment.

FIGURE 6-6: BLOCK DIAGRAM OF THE TIMERO/WDT PRESCALER



#### 6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control, i.e., it can be changed "on the fly" during program execution.

To avoid an unintended device RESET, the following instruction sequence (shown in Example 6-1) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

Note:

### **CHANGING PRESCALER (TIMER0→WDT) EXAMPLE 6-1:**

STATUS, RP0 ;Bank 0 CLRF TMR0 ;Clear TMR0 & Prescaler BSF STATUS, RPO ;Bank 1 CLRWDT :Clears WDT MOVLW ; Selects new prescale value b'xxxx1xxx MOVWF OPTION\_REG ; and assigns the prescaler to the WDT BCF STATUS, RPO ;Bank 0

To change prescaler from the WDT to the Timer0 module use the sequence shown in Example 6-2.

#### **EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)**

;Clear WDT and prescaler CLRWDT BSF STATUS, RP0 ; Bank 1 MOVLW b'xxxx0xxx' ;Select TMRO, new prescale value and MOVWF OPTION\_REG ; clock source BCF STATUS, RPO ; Bank 0

#### **TABLE 6-1:** REGISTERS ASSOCIATED WITH TIMERO

BCF TABLE 6-	STATUS		Bank 0	OCIATE	D WITH	TIMER	OTW OTW				
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
0Bh,8Bh,	INTCON	GIE	ADIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	RBPU	INTEDG	T0CS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	V.CO	W.	_	PORTA Data Direction Register					1 1111	1 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

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# 7.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

Applicable Devices 710 71 711 715

The analog-to-digital (A/D) converter module has four analog inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (VDD) or the voltage level on the RA3/AN3/VREF pin.

The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode. To operate in sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

The ADCON0 register, shown in Figure 7-1 and Figure 7-2, controls the operation of the A/D module. The ADCON1 register, shown in Figure 7-3 configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

# FIGURE 7-1: ADCONO REGISTER (ADDRESS 08h), PIC16C710/71/711

R/W-0 R/W-0 U-0 **R/W-0** R/W-0 R/W-0 R/W-0 R/W-0 ADCS1 ADCS0 \_\_\_(1) CHS<sub>1</sub> CHS<sub>0</sub> **GO/DONE ADIF ADON** R = Readable bit W = Writable bit bit7 bit0 U = Unimplemented bit, read as '0' n =Value at POR reset ADCS1:ADCS0: A/D Conversion Clock Select bits 00 = Fosc/201 = Fosc/8特力材料886-3-5753170 10 = Fosc/32胜特力电子(上海) 86-21-54151736 11 = FRC (clock derived from an RC oscillation) bit 5: Unimplemented: Read as '0'. 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw bit 4-3: CHS1:CHS0: Analog Channel Select bits 00 = channel 0, (RA0/AN0) 01 = channel 1, (RA1/AN1)

10 = channel 2, (RA2/AN2) 11 = channel 3, (RA3/AN3)

bit 2: GO/DONE: A/D Conversion Status bit

If ADON = 1:

1 = A/D conversion in progress (setting this bit starts the A/D conversion)

0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1: ADIF: A/D Conversion Complete Interrupt Flag bit

1 = conversion is complete (must be cleared in software)

0 = conversion is not complete

bit 0: ADON: A/D On bit

1 = A/D converter module is operating

0 = A/D converter module is shutoff and consumes no operating current

Note 1: Bit5 of ADCON0 is a General Purpose R/W bit for the PIC16C710/711 only. For the PIC16C71, this bit is unimplemented, read as '0'.

#### ADCONO REGISTER (ADDRESS 1Fh), PIC16C715 **FIGURE 7-2:**

R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 R/W-0 U-0 R/W-0 ADCS1 ADCS0 **ADON** CHS<sub>1</sub> CHS<sub>0</sub> **GO/DONE** R = Readable bit W = Writable bit bit0 bit7 U = Unimplemented bit, read as '0' - n = Value at POR reset bit 7-6: ADCS1:ADCS0: A/D Conversion Clock Select bits 00 = Fosc/201 = Fosc/8 10 = Fosc/3211 = FRC (clock derived from an RC oscillation) bit 5: Unused 勝 特 力 材 料 886-3-5753170 bit 6-3: CHS1:CHS0: Analog Channel Select bits 胜特力电子(上海) 86-21-54151736 000 = channel 0, (RA0/AN0) 胜特力电子(深圳) 86-755-83298787 001 = channel 1, (RA1/AN1) Http://www. 100y. com. tw 010 = channel 2, (RA2/AN2) 011 = channel 3, (RA3/AN3) 100 = channel 0, (RA0/AN0) 101 = channel 1, (RA1/AN1) 110 = channel 2, (RA2/AN2) 111 = channel 3, (RA3/AN3) GO/DONE: A/D Conversion Status bit bit 2: If ADON = 11 = A/D conversion in progress (setting this bit starts the A/D conversion)

0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conver-

FIGURE 7-3: ADCON1 REGISTER, PIC16C710/71/711 (ADDRESS 88h), PIC16C715 (ADDRESS 9Fh)

0 = A/D converter module is shutoff and consumes no operating current

FIGURE 7		CON1 RE 16C715 (			10/71/711	(ADDRES	S 88h),	M.M.W.100X.C
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	D. Doodoblo bis 100
bit7		W.100Y	COM	I.M.	WW	PCFG1	PCFG0 bit0	R = Readable bit W = Writable bit U = Unimplemented
bit 7-2:	Unimplen	nented: Re	ead as '0'					bit, read as '0' - n =Value at POR reset

sion is complete)

ADON: A/D On bit

bit 1: bit 0:

Unimplemented: Read as '0'

1 = A/D converter module is operating

bit 1-0: PCFG1:PCFG0: A/D Port Configuration Control bits

PCFG1:PCFG0	RA1 & RA0	RA2	RA3	VREF
00	A	Α	Α	VDD
01	A	A COM.	VREF	RA3
10	Α 10	D	D	VDD
11	D	D	D	VDD
A = Analog input	WWW.I	COM	TW	
D: :: 11/0				

D = Digital I/O

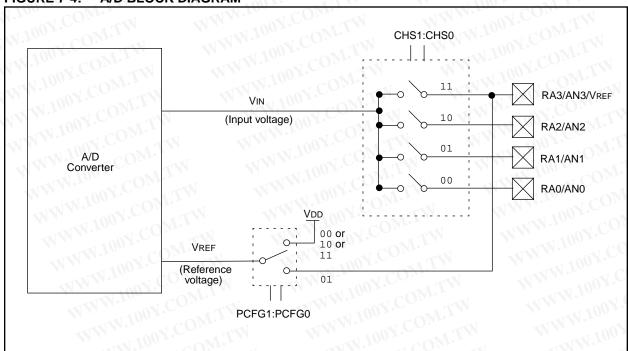
The ADRES register contains the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRES register, the GO/DONE bit (ADCON0<2>) is cleared, and A/D interrupt flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 7-4.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see Section 7.1. After this acquisition time has elapsed the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

- 1. Configure the A/D module:
  - Configure analog pins / voltage reference / and digital I/O (ADCON1)
  - Select A/D input channel (ADCON0)
  - Select A/D conversion clock (ADCON0)
  - Turn on A/D module (ADCON0)

- 2. Configure A/D interrupt (if desired):
  - · Clear ADIF bit
  - Set ADIE bit
  - · Set GIE bit
- 3. Wait the required acquisition time.
- 4. Start conversion:
  - Set GO/DONE bit (ADCON0)
- 5. Wait for A/D conversion to complete, by either:
  - Polling for the GO/DONE bit to be cleared OR
  - · Waiting for the A/D interrupt
- Read A/D Result register (ADRES), clear bit ADIF if required.
- For next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before next acquisition starts.

FIGURE 7-4: A/D BLOCK DIAGRAM



## 7.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-5. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD), Figure 7-5. The source impedance affects the offset voltage at the analog input (due to pin leakage current). The maximum recommended impedance for analog sources is  $10~\text{k}\Omega$ . After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation calculates the acquisition time to within 1/2 LSb error is used (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

# EQUATION 7-1: A/D MINIMUM CHARGING TIME

 $VHOLD = (VREF - (VREF/512)) \bullet (1 - e^{(-TCAP/CHOLD(RIC + RSS + RS))})$ 

Given: VHOLD = (VREF/512), for 1/2 LSb resolution

The above equation reduces to:

 $TCAP = -(51.2 pF)(1 k\Omega + Rss + Rs) ln(1/511)$ 

Example 7-1 shows the calculation of the minimum required acquisition time TACQ. This calculation is based on the following system assumptions.

CHOLD = 51.2 pF

 $Rs = 10 k\Omega$ 

1/2 LSb error

 $V\text{DD} = 5V \rightarrow Rss = 7 \; k\Omega$ 

Temp (application system max.) = 50°C

VHOLD = 0 @ t = 0

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Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

**Note 2:** The charge holding capacitor (CHOLD) is not discharged after each conversion.

Note 3: The maximum recommended impedance for analog sources is 10 k $\Omega$ . This is required to meet the pin leakage specification.

Note 4: After a conversion has completed, a 2.0TAD delay must complete before acquisition can begin again. During this time the holding capacitor is not connected to the selected A/D input channel.

# EXAMPLE 7-1: CALCULATING THE MINIMUM REQUIRED AQUISITION TIME

TACQ = Amplifier Settling Time +

Holding Capacitor Charging Time +

Temperature Coefficient

TACQ =  $5 \mu s + TCAP + [(Temp - 25°C)(0.05 \mu s/°C)]$ 

TCAP = -CHOLD (RIC + RSS + RS) In(1/511)

-51.2 pF (1 kΩ + 7 kΩ + 10 kΩ) ln(0.0020)

-51.2 pF (18 kΩ) ln(0.0020)

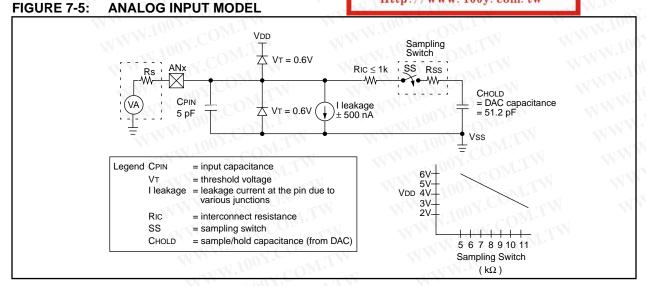
-0.921 µs (-6.2364)

5.747 µs

TACQ =  $5 \mu s + 5.747 \mu s + [(50^{\circ}C - 25^{\circ}C)(0.05 \mu s/^{\circ}C)]$ 

 $10.747 \,\mu s + 1.25 \,\mu s$ 

11.997 μs



# 7.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2Tosc
- 8Tosc
- 32Tosc
- · Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of:

2.0 us for the PIC16C71

1.6 µs for all other PIC16C71X devices

Table 7-1 and Table 7-2 and show the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

## 7.3 Configuring Analog Port Pins

The ADCON1 and TRISA registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

Note 2: Analog levels on any pin that is defined as a digital input (including the AN7:AN0 pins), may cause the input buffer to consume current that is out of the devices specification.

TABLE 7-1: TAD vs. DEVICE OPERATING FREQUENCIES, PIC16C71

AD Clock Source (TAD)		W.10	COM	evice Frequenc	M. To OX.C	
Operation	ADCS1:ADCS0	20 MHz	16 MHz	4 MHz	1 MHz	333.33 kHz
2Tosc	00	100 ns <sup>(2)</sup>	125 ns <sup>(2)</sup>	500 ns <sup>(2)</sup>	2.0 μs	6 μs
8Tosc	01	400 ns <sup>(2)</sup>	500 ns <sup>(2)</sup>	2.0 μs	8.0 µs	24 μs <sup>(3)</sup>
32Tosc	10	1.6 μs <sup>(2)</sup>	2.0 μs	8.0 μs	32.0 μs <sup>(3)</sup>	96 μs <sup>(3)</sup>
RC <sup>(5)</sup>	(11	2 - 6 μs <sup>(1,4)</sup>	2 - 6 μs <sup>(1,4)</sup>	2 - 6 μs <sup>(1,4)</sup>	2 - 6 μs <sup>(1)</sup>	2 - 6 µs <sup>(1)</sup>

Legend: Shaded cells are outside of recommended range.

- Note 1: The RC source has a typical TAD time of 4  $\mu$ s.
  - 2: These values violate the minimum required TAD time.
  - 3: For faster conversion times, the selection of another clock source is recommended.
  - 4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for sleep operation only.
  - 5: For extended voltage devices (LC), please refer to Electrical Specifications section.

TABLE 7-2: TAD vs. DEVICE OPERATING FREQUENCIES, PIC16C710/711, PIC16C715

AD Clock S	Source (TAD)	Device Frequency					
Operation (	ADCS1:ADCS0	20 MHz	5 MHz	1.25 MHz	333.33 kHz		
2Tosc	00	100 ns <sup>(2)</sup>	400 ns <sup>(2)</sup>	1.6 µs	6 μs		
8Tosc	01 (0)	400 ns <sup>(2)</sup>	1.6 μs	6.4 μs	24 μs <sup>(3)</sup>		
32Tosc	10	1.6 μs	6.4 μs	25.6 μs <sup>(3)</sup>	96 μs <sup>(3)</sup>		
RC <sup>(5)</sup>	11	2 - 6 μs <sup>(1,4)</sup>	2 - 6 μs <sup>(1,4)</sup>	2 - 6 μs <sup>(1,4)</sup>	2 - 6 μs <sup>(1)</sup>		

Legend: Shaded cells are outside of recommended range.

- Note 1: The RC source has a typical TAD time of 4 µs.
  - 2: These values violate the minimum required TAD time.
  - 3: For faster conversion times, the selection of another clock source is recommended.
  - 4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for sleep operation only.
  - 5: For extended voltage devices (LC), please refer to Electrical Specifications section.

## 7.4 A/D Conversions

Example 7-2 shows how to perform an A/D conversion. The RA pins are configured as analog inputs. The analog reference (VREF) is the device VDD. The A/D interrupt is enabled, and the A/D conversion clock is FRC. The conversion is performed on the RA0 pin (channel 0).

**Note:** The GO/DONE bit should **NOT** be set in the same instruction that turns on the A/D.

Clearing the GO/DONE bit during a conversion will abort the current conversion. The ADRES register will NOT be updated with the partially completed A/D conversion sample. That is, the ADRES register will continue to contain the value of the last completed conversion (or the last value written to the ADRES register). After the A/D conversion is aborted, a 2TAD wait is required before the next acquisition is started. After this 2TAD wait, an acquisition is automatically started on the selected channel.

## **EXAMPLE 7-2: A/D CONVERSION**

```
BSF
          STATUS, RP0
                               ; Select Bank 1
                               ; Configure A/D inputs
  CLRF
          ADCON1
  BCF
          STATUS, RPO
                               ; Select Bank 0
  MOVLW
                               ; RC Clock, A/D is on, Channel 0 is selected
  MOVWF
          ADCON0
          INTCON, ADIE
  BSF
                               ; Enable A/D Interrupt
                               ; Enable all interrupts
  BSF
          INTCON, GIE
Ensure that the required sampling time for the selected input channel has elapsed.
Then the conversion may be started.
          ADCONO, GO
  BSF
                               ; Start A/D Conversion
                                The ADIF bit will be set and the GO/DONE bit
                                  is cleared upon completion of the A/D Conversion.
```

# 7.4.1 FASTER CONVERSION - LOWER RESOLUTION TRADE-OFF

Not all applications require a result with 8-bits of resolution, but may instead require a faster conversion time. The A/D module allows users to make the trade-off of conversion speed to resolution. Regardless of the resolution required, the acquisition time is the same. To speed up the conversion, the clock source of the A/D module may be switched so that the TAD time violates the minimum specified time (see the applicable electrical specification). Once the TAD time violates the minimum specified time, all the following A/D result bits are not valid (see A/D Conversion Timing in the Electrical Specifications section.) The clock sources may only be switched between the three oscillator versions (cannot be switched from/to RC). The equation to determine the time before the oscillator can be switched is as follows:

Conversion time =  $2TAD + N \cdot TAD + (8 - N)(2TOSC)$ Where: N = number of bits of resolution required. Since the TAD is based from the device oscillator, the user must use some method (a timer, software loop, etc.) to determine when the A/D oscillator may be changed. Example 7-3 shows a comparison of time required for a conversion with 4-bits of resolution, versus the 8-bit resolution conversion. The example is for devices operating at 20 MHz and 16 MHz (The A/D clock is programmed for 32Tosc), and assumes that immediately after 6TAD, the A/D clock is programmed for 2Tosc.

The 2Tosc violates the minimum TAD time since the last 4-bits will not be converted to correct values.

**EXAMPLE 7-3: 4-BIT vs. 8-BIT CONVERSION TIMES** 

I. TOO Y COM.	CONTRACTOR	Resolution		
	Freq. (MHz) <sup>(1)</sup>	4-bit	8-bit	
TAD	20	1.6 µs	1.6 μs	
	16	2.0 μs	2.0 μs	
Tosc	20	50 ns	50 ns	
	16	62.5 ns	62.5 ns	
2TAD + N • TAD + (8 - N)(2TOSC)	20	10 μs	16 μs	
	16	12.5 μs	20 μs	

Note 1: The PIC16C71 has a minimum TAD time of 2.0  $\mu$ s. All other PIC16C71X devices have a minimum TAD time of 1.6  $\mu$ s.

# 7.5 A/D Operation During Sleep

The A/D module can operate during SLEEP mode. This requires that the A/D clock source be set to RC (ADCS1:ADCS0 = 11). When the RC clock source is selected, the A/D module waits one instruction cycle before starting the conversion. This allows the SLEEP instruction to be executed, which eliminates all digital switching noise from the conversion. When the conversion is completed the GO/DONE bit will be cleared, and the result loaded into the ADRES register. If the A/D interrupt is enabled, the device will wake-up from SLEEP. If the A/D interrupt is not enabled, the A/D module will then be turned off, although the ADON bit will remain set.

When the A/D clock source is another clock option (not RC), a SLEEP instruction will cause the present conversion to be aborted and the A/D module to be turned off, though the ADON bit will remain set.

Turning off the A/D places the A/D module in its lowest current consumption state.

Note

For the A/D module to operate in SLEEP, the A/D clock source must be set to RC (ADCS1:ADCS0 = 11). To perform an A/D conversion in SLEEP, ensure the SLEEP instruction immediately follows the instruction that sets the GO/DONE bit.

# 7.6 A/D Accuracy/Error

The absolute accuracy specified for the A/D converter includes the sum of all contributions for quantization error, integral error, differential error, full scale error, offset error, and monotonicity. It is defined as the maximum deviation from an actual transition versus an ideal transition for any code. The absolute error of the A/D converter is specified at <  $\pm 1$  LSb for VDD = VREF (over the device's specified operating range). However, the accuracy of the A/D converter will degrade as VDD diverges from VREF.

For a given range of analog inputs, the output digital code will be the same. This is due to the quantization of the analog input to a digital code. Quantization error is typically  $\pm$  1/2 LSb and is inherent in the analog to digital conversion process. The only way to reduce quantization error is to increase the resolution of the A/D converter.

Offset error measures the first actual transition of a code versus the first ideal transition of a code. Offset error shifts the entire transfer function. Offset error can be calibrated out of a system or introduced into a system through the interaction of the total leakage current and source impedance at the analog input.

Gain error measures the maximum deviation of the last actual transition and the last ideal transition adjusted for offset error. This error appears as a change in slope of the transfer function. The difference in gain error to full scale error is that full scale does not take offset error into account. Gain error can be calibrated out in software.

Linearity error refers to the uniformity of the code changes. Linearity errors cannot be calibrated out of the system. Integral non-linearity error measures the actual code transition versus the ideal code transition adjusted by the gain error for each code.

Differential non-linearity measures the maximum actual code width versus the ideal code width. This measure is unadjusted.

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator. TAD must not violate the minimum and should be  $\leq 8~\mu s$  for preferred operation. This is because TAD, when derived from ToSC, is kept away from on-chip phase clock transitions. This reduces, to a large extent, the effects of digital switching noise. This is not possible with the RC derived clock. The loss of accuracy due to digital switching noise can be significant if many I/O pins are active.

In systems where the device will enter SLEEP mode after the start of the A/D conversion, the RC clock source selection is required. In this mode, the digital noise from the modules in SLEEP are stopped. This method gives high accuracy.

## 7.7 Effects of a RESET

A device reset forces all registers to their reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The value that is in the ADRES register is not modified for a Power-on Reset. The ADRES register will contain unknown data after a Power-on Reset.

# 7.8 Connection Considerations

If the input voltage exceeds the rail values (VSS or VDD) by greater than 0.2V, then the accuracy of the conversion is out of specification.

**Note:** Care must be taken when using the RA0 pin in A/D conversions due to its proximity to the OSC1 pin.

An external RC filter is sometimes added for anti-aliasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 10 k $\Omega$  recommended specification. Any external components connected (via hi-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

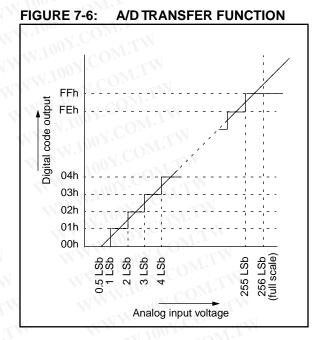
# 7.9 Transfer Function

The ideal transfer function of the A/D converter is as follows: the first transition occurs when the analog input voltage (VAIN) is Analog VREF/256 (Figure 7-6).

# 7.10 References

A very good reference for understanding A/D converters is the "Analog-Digital Conversion Handbook" third edition, published by Prentice Hall (ISBN 0-13-03-2848-0).

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# FIGURE 7-7: FLOWCHART OF A/D OPERATION

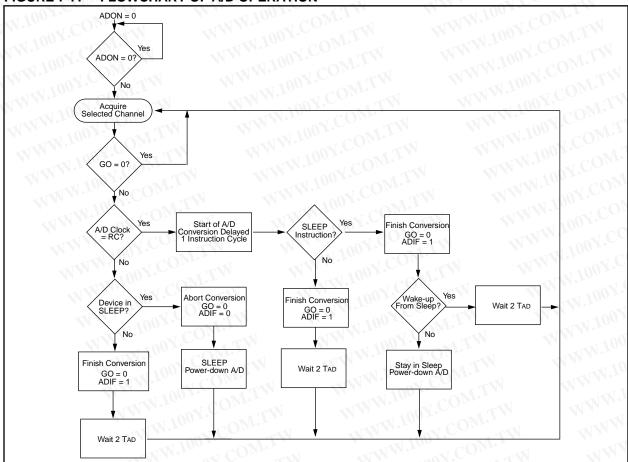


TABLE 7-3: REGISTERS/BITS ASSOCIATED WITH A/D, PIC16C710/71/711

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh,8Bh	INTCON	GIE	ADIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
89h	ADRES	A/D Res	sult Regis	ter	Mr	X		1.10	A.COM	xxxx xxxx	uuuu uuuu
08h	ADCON0	ADCS1	ADCS0		CHS1	CHS0	GO/DONE	ADIF	ADON	00-0 0000	00-0 0000
88h	ADCON1	AT M	-x-100	1	OM.	111	7/1/1	PCFG1	PCFG0	00	00
05h	PORTA	-WV	- 40	04.	RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
85h	TRISA	-N	MAI	OTT V	PORTA	Data Dire	ction Registe	er	ONY.C	1 1111	1 1111

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D conversion.

TABLE 7-4: REGISTERS/BITS ASSOCIATED WITH A/D, PIC16C715

									4 1 1 1 1 1 1		
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh/8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	3.77	ADIF	- XIX	N.100 1.	COM.			W 1.1	-0	-0
8Ch	PIE1	TIN	ADIE	1 TAIL	-X 100X	- N	I.A.	-W	-7XN	-0	-0
1Eh	ADRES	A/D Re	sult Regis	ster	100	Y.Co.	WILL	1	MM	xxxx xxxx	uuuu uuuu
1Fh	ADCON 0	ADCS 1	ADCS 0	CHS2	CHS1	CHS0	GO/ DONE	_	ADON	0000 00-0	0000 00-0
9Fh	ADCON 1	·OM.		- 4	W T.	00 TC	ONT.TV	PCFG1	PCFG0	00	00
05h	PORTA	- <del>-</del> M	II		RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
85h	TRISA		L'EN	_	TRISA4	TRISA 3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D conversion.

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# 8.0 SPECIAL FEATURES OF THE CPU

# Applicable Devices 710 71 711 715

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real-time applications. The PIC16CXX family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These are:

- Oscillator selection
- Reset
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR) (PIC16C710/711/715)
  - Parity Error Reset (PER) (PIC16C715)
- Interrupts
- Watchdog Timer (WDT)
- SLEEP
- Code protection
- ID locations
- In-circuit serial programming

The PIC16CXX has a Watchdog Timer which can be shut off only through configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a

fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in reset while the power supply stabilizes. With these two timers on-chip, most applications need no external reset circuitry.

SLEEP mode is designed to offer a very low current power-down mode. The user can wake-up from SLEEP through external reset, Watchdog Timer Wake-up, or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

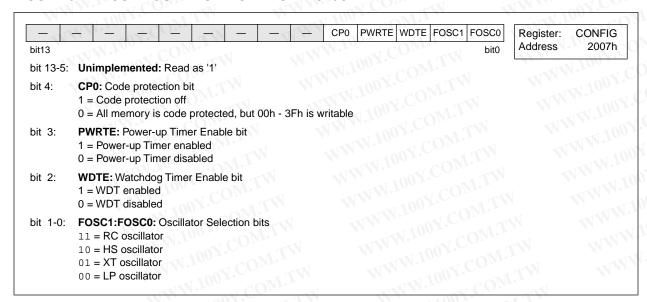
# 8.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h - 3FFFh), which can be accessed only during programming.

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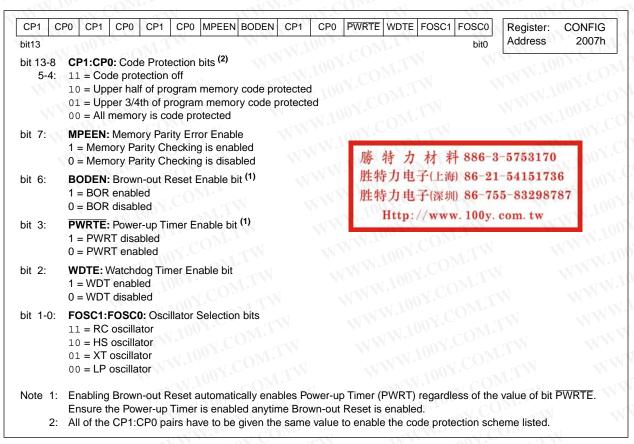
#### FIGURE 8-1: CONFIGURATION WORD FOR PIC16C71



# FIGURE 8-2: CONFIGURATION WORD, PIC16C710/711

CP0 PWRTE WDTE FOSC1 FOSC0 CP0 CP0 BODEN Register: CONFIG Address 2007h bit13 bit 13-7 CP0: Code protection bits (2) 5-4: 1 = Code protection off 0 = All memory is code protected, but 00h - 3Fh is writable bit 6: BODEN: Brown-out Reset Enable bit (1) 1 = BOR enabled 0 = BOR disabled PWRTE: Power-up Timer Enable bit (1) bit 3: 1 = PWRT disabled 0 = PWRT enabled WDTE: Watchdog Timer Enable bit bit 2: 1 = WDT enabled 0 = WDT disabled FOSC1:FOSC0: Oscillator Selection bits 11 = RC oscillator 10 = HS oscillator 01 = XT oscillator 00 = LP oscillator Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit PWRTE Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled. All of the CP0 bits have to be given the same value to enable the code protection scheme listed.

# FIGURE 8-3: CONFIGURATION WORD, PIC16C715



# 8.2 Oscillator Configurations

# 8.2.1 OSCILLATOR TYPES

The PIC16CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

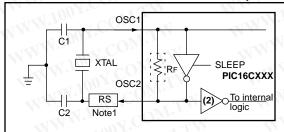
LP Low Power CrystalXT Crystal/ResonatorHS High Speed Crystal/Resonator

RC Resistor/Capacitor

# 8.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 8-4). The PIC16CXX Oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 8-5).

FIGURE 8-4: CRYSTAL/CERAMIC
RESONATOR OPERATION
(HS, XT OR LP
OSC CONFIGURATION)



See Table 8-1 and Table 8-1 for recommended values of C1 and C2.

Note 1: A series resistor may be required for AT strip cut crystals.

2: The buffer is on the OSC2 pin.

FIGURE 8-5: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

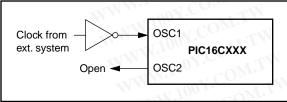


TABLE 8-1: CERAMIC RESONATORS, PIC16C71

Ranges Tested:							
Mode	Freq	OSC1	OSC2				
XT	455 kHz 2.0 MHz 4.0 MHz	47 - 100 pF 15 - 68 pF 15 - 68 pF	47 - 100 pF 15 - 68 pF 15 - 68 pF				
HS	8.0 MHz 16.0 MHz	15 - 68 pF 10 - 47 pF	15 - 68 pF 10 - 47 pF				
	ese values are tes at bottom of p	for design guida page.	nce only. See				
Resonato	ors Used:	OM.TW					
455 kHz	Panasonic E	FO-A455K04B	± 0.3%				
2.0 MHz	Murata Erie	CSA2.00MG	± 0.5%				
4.0 MHz	4.0 MHz Murata Erie CSA4.00MG ± 0.5%						
8.0 MHz	Murata Erie	Murata Erie CSA8.00MT ± 0.5%					
16.0 MHz	Hz Murata Erie CSA16.00MX ± 0.5%						
All res	onators used did	d not have built-in	capacitors.				

TABLE 8-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR, PIC16C71

Mode	Freq	OSC1	OSC2
LP	32 kHz	33 - 68 pF	33 - 68 pF
	200 kHz	15 - 47 pF	15 - 47 pF
XT	100 kHz	47 - 100 pF	47 - 100 pF
	500 kHz	20 - 68 pF	20 - 68 pF
	1 MHz	15 - 68 pF	15 - 68 pF
	2 MHz	15 - 47 pF	15 - 47 pF
	4 MHz	15 - 33 pF	15 - 33 pF
HS	8 MHz	15 - 47 pF	15 - 47 pF
	20 MHz	15 - 47 pF	15 - 47 pF

These values are for design guidance only. See notes at bottom of page.

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TABLE 8-3: CERAMIC RESONATORS, PIC16C710/711/715

Ranges T	ested:		
Mode	Freq	OSC1	OSC2
XT.	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF
not	es at bottom of	for design guida page.	nce only. See
Resonato	rs Used:	1111	100 A.
455 kHz	Panasonic I	FO-A455K04B	± 0.3%
2.0 MHz	Murata Erie	CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie	CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie	CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie	CSA16.00MX	± 0.5%
All res	onators used d	lid not have built-in	capacitors.

TABLE 8-4: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR, PIC16C710/711/715

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2		
LP	32 kHz	33 pF	33 pF		
	200 kHz	15 pF	15 pF		
XT	200 kHz	47-68 pF	47-68 pF		
	1 MHz	15 pF	15 pF		
	4 MHz	0 15 pF	15 pF		
HS	4 MHz	15 pF	15 pF		
	8 MHz	15-33 pF	15-33 pF		
	20 MHz	15-33 pF	15-33 pF		
	e values are at bottom of p	f <b>or design guida</b> page.	nce only. See		
Ń	Crys	tals Used	TW		
32 kHz	Epson C-00	1R32.768K-A	± 20 PPM		
200 kHz	STD XTL 2	00.000KHz	± 20 PPM		
1 MHz	ECS ECS-1	0-13-1	± 50 PPM		
4 MHz	ECS ECS-4	10-20-1	± 50 PPM		
8 MHz	EPSON CA	-301 8.000M-C	± 30 PPM		
20 MHz	EPSON CA	EPSON CA-301 20.000M-C			

- Note 1: Recommended values of C1 and C2 are identical to the ranges tested table.
  - 2: Higher capacitance increases the stability of oscillator but also increases the start-up time.
  - 3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
  - 4: Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification.

# 8.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance, or one with parallel resonance.

Figure 8-6 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7  $k\Omega$  resistor provides the negative feedback for stability. The 10  $k\Omega$  potentiometer biases the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 8-6: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

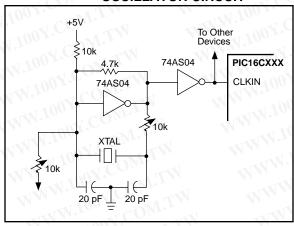
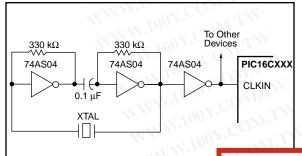


Figure 8-7 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 k $\Omega$  resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 8-7: EXTERNAL SERIES
RESONANT CRYSTAL
OSCILLATOR CIRCUIT



#### 8.2.4 RC OSCILLATOR

For timing insensitive applications the "RC" device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 8-8 shows how the R/C combination is connected to the PIC16CXX. For Rext values below 2.2 k $\Omega$ , the oscillator operation may become unstable, or stop completely. For very high Rext values (e.g. 1 M $\Omega$ ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep Rext between 3 k $\Omega$  and 100 k $\Omega$ .

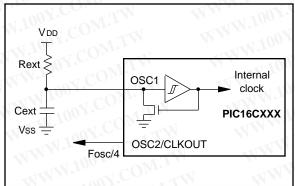
Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See characterization data for desired device for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See characterization data for desired device for variation of oscillator frequency due to VDD for given Rext/Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (see Figure 3-2 for waveform).

FIGURE 8-8: RC OSCILLATOR MODE



#### 8.3 Reset

# Applicable Devices 710 71 711 715

The PIC16CXX differentiates between various kinds of reset:

- Power-on Reset (POR)
- MCLR reset during normal operation
- MCLR reset during SLEEP
- · WDT Reset (normal operation)
- Brown-out Reset (BOR) (PIC16C710/711/715)
- Parity Error Reset (PIC16C715)

Some registers are not affected in any reset condition; their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a "reset state" on Power-on Reset (POR), on the  $\overline{\text{MCLR}}$  and

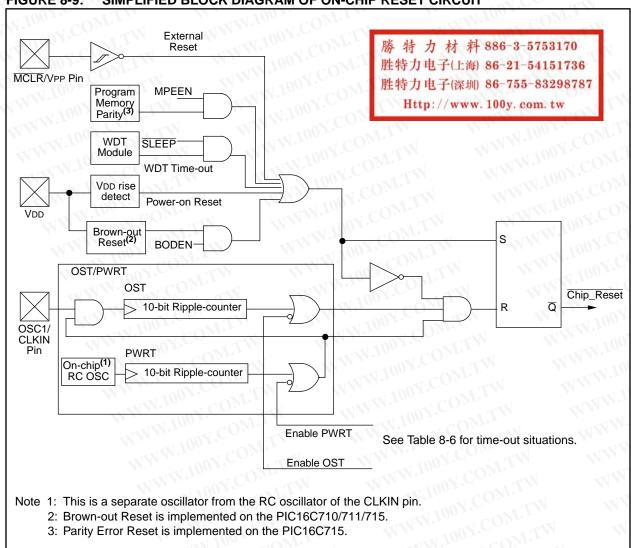
WDT Reset, on MCLR reset during SLEEP, and Brownout Reset (BOR). They are not affected by a WDT Wake-up, which is viewed as the resumption of normal operation. The TO and PD bits are set or cleared differently in different reset situations as indicated in Table 8-7, Table 8-8 and Table 8-9. These bits are used in software to determine the nature of the reset. See Table 8-10 and Table 8-11 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 8-9.

The PIC16C710/711/715 have a  $\overline{\text{MCLR}}$  noise filter in the  $\overline{\text{MCLR}}$  reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive  $\overline{\text{MCLR}}$  pin low.

FIGURE 8-9: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



# 8.4 Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST), and Brown-out Reset (BOR)

## 8.4.1 POWER-ON RESET (POR)

# Applicable Devices 710 71 711 715

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the  $\overline{\text{MCLR}}$  pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

For additional information, refer to Application Note AN607, "Power-up Trouble Shooting."

## 8.4.2 POWER-UP TIMER (PWRT)

# Applicable Devices 710 71 711 715

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

## 8.4.3 OSCILLATOR START-UP TIMER (OST)

# Applicable Devices 710 71 711 715

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

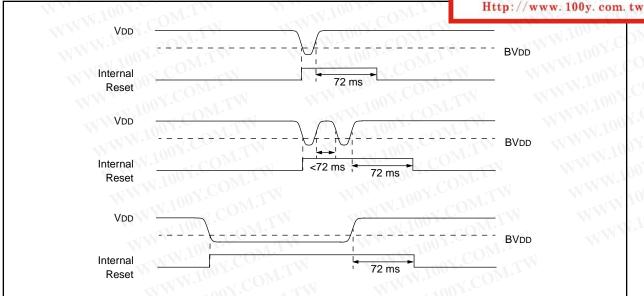
# 8.4.4 BROWN-OUT RESET (BOR)

# **Applicable Devices** | 710 | 71 | 711 | 715 |

A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (3.8V - 4.2V range) for greater than parameter #35, the brown-out situation will reset the chip. A reset may not occur if VDD falls below 4.0V for less than parameter #35. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms. If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms time delay. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 8-10 shows typical brown-out situations

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#### 8.4.5 TIME-OUT SEQUENCE

# Applicable Devices 710 71 711 715

On power-up the time-out sequence is as follows: First PWRT time-out is invoked after the POR time delay has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 8-11, Figure 8-12, and Figure 8-13 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if MCLR is kept low long enough, the time-outs will expire. Then bringing MCLR high will begin execution immediately (Figure 8-12). This is useful for testing purposes or to synchronize more than one PIC16CXX device operating in parallel.

Table 8-10 and Table 8-11 show the reset conditions for some special function registers, while Table 8-12 and Table 8-13 show the reset conditions for all the registers.

# 8.4.6 POWER CONTROL/STATUS REGISTER (PCON)

# **Applicable Devices** | 710 | 71 | 711 | 715

The Power Control/Status Register, PCON has up to two bits, depending upon the device.

Bit0 is Brown-out Reset Status bit,  $\overline{BOR}$ . Bit  $\overline{BOR}$  is unknown on a Power-on Reset. It must then be set by the user and checked on subsequent resets to see if bit  $\overline{BOR}$  cleared, indicating a BOR occurred. The  $\overline{BOR}$  bit is a "Don't Care" bit and is not necessarily predictable if the Brown-out Reset circuitry is disabled (by clearing bit BODEN in the Configuration Word).

Bit1 is POR (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

For the PIC16C715, bit2 is  $\overline{\text{PER}}$  (Parity Error Reset). It is cleared on a Parity Error Reset and must be set by user software. It will also be set on a Power-on Reset.

For the PIC16C715, bit7 is MPEEN (Memory Parity Error Enable). This bit reflects the status of the MPEEN bit in configuration word. It is unaffected by any reset of interrupt.

## 8.4.7 PARITY ERROR RESET (PER)

# Applicable Devices 710 71 711 715

The PIC16C715 has on-chip parity bits that can be used to verify the contents of program memory. Parity bits may be useful in applications in order to increase overall reliability of a system.

There are two parity bits for each word of Program Memory. The parity bits are computed on alternating bits of the program word. One computation is performed using even parity, the other using odd parity. As a program executes, the parity is verified. The even parity bit is XOR'd with the even bits in the program memory word. The odd parity bit is negated and XOR'd with the odd bits in the program memory word. When an error is detected, a reset is generated and the PER flag bit 2 in the PCON register is cleared (logic '0'). This indication can allow software to act on a failure. However, there is no indication of the program memory location of the failure in Program Memory. This flag can only be set (logic '1') by software.

The parity array is user selectable during programming. Bit 7 of the configuration word located at address 2007h can be programmed (read as '0') to disable parity. If left unprogrammed (read as '1'), parity is enabled.

TABLE 8-5: TIME-OUT IN VARIOUS SITUATIONS, PIC16C71

Oscillator Configuration	Power-	Wake-up from SLEEP	
WWW.T OV.C	PWRTE = 1	PWRTE = 0	W WWW
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	1024 Tosc
RC 1003	72 ms	100	

## TABLE 8-6: TIME-OUT IN VARIOUS SITUATIONS, PIC16C710/711/715

Oscillator Configuration	Power	-up	W.100 COM.	Wake-up from SLEEP
WW	PWRTE = 0	PWRTE = 1	Brown-out	In M.
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	72 ms + 1024Tosc	1024Tosc
RC	72 ms	1.1	72 ms	TIN - TIN

STATUS BITS AND THEIR SIGNIFICANCE, PIC16C71 **TABLE 8-7:** 

N TO	PD.	CONTRACTOR WINNINGY.COM.TW
1	1	Power-on Reset
0	х	Illegal, TO is set on POR
x	0_100	Illegal, PD is set on POR
0	1/1	WDT Reset
0	0	WDT Wake-up
u	u	MCLR Reset during normal operation
11	0	MCLR Reset during SLEEP or interrupt wake-up from SLEEP

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**TABLE 8-8:** STATUS BITS AND THEIR SIGNIFICANCE, PIC16C710/711

POR	BOR	TO	PD	W.100X.COW.TW
0	x	1	1	Power-on Reset
V 0	x	0	х	Illegal, TO is set on POR
0.0	х	х	0	Illegal, PD is set on POR
1001	0	х	х	Brown-out Reset
1.	1 1	0	1	WDT Reset
1	01	0	0	WDT Wake-up
101	_ 1	u	u	MCLR Reset during normal operation
110	1	1	0	MCLR Reset during SLEEP or interrupt wake-up from SLEEP

**TABLE 8-9:** STATUS BITS AND THEIR SIGNIFICANCE, PIC16C715

PER	POR	BOR	TO	PD	N. T. COM. AND MAN. M. CO.
1 10	0	x	1	1	Power-on Reset
x	0	x	0	x	Illegal, TO is set on POR
x	0	x	x	0	Illegal, PD is set on POR
1	1	0	x	х	Brown-out Reset
1	1	11	0	1	WDT Reset
1	1	Cui	0	0	WDT Wake-up
1	1		u	u	MCLR Reset during normal operation
1	100	1	1	0	MCLR Reset during SLEEP or interrupt wake-up from SLEEP
0	1	1	1	1	Parity Error Reset
0	0	$\mathbf{x}^{\cup}$	х	x	Illegal, PER is set on POR
0	x	0 (	x	x	Illegal, PER is set on BOR

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TABLE 8-10: RESET CONDITION FOR SPECIAL REGISTERS, PIC16C710/71/711

Condition	Program Counter	STATUS Register	PCON Register PIC16C710/711	
Power-on Reset	000h	0001 1xxx	0x	
MCLR Reset during normal operation	000h	000u uuuu	uu	
MCLR Reset during SLEEP	000h	0001 0uuu	uu	
WDT Reset	000h	0000 1uuu	uu	
WDT Wake-up	PC + 1	uuu0 0uuu	uu	
Brown-out Reset (PIC16C710/711)	000h	0001 1uuu	u0	
Interrupt wake-up from SLEEP	PC + 1 <sup>(1)</sup>	uuu1 0uuu	uu	

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

TABLE 8-11: RESET CONDITION FOR SPECIAL REGISTERS, PIC16C715

Condition	Program Counter	STATUS Register	PCON Register	
Power-on Reset	000h	0001 1xxx	u10x	
MCLR Reset during normal operation	000h	000u uuuu	uuuu	
MCLR Reset during SLEEP	000h	0001 0uuu	uuuu	
WDT Reset	000h	0000 1uuu	uuuu	
WDT Wake-up	PC + 1	uuu0 0uuu	uuuu	
Brown-out Reset	000h	0001 1uuu	uuu0	
Parity Error Reset	000h	uuu1 0uuu	u0uu	
Interrupt wake-up from SLEEP	PC + 1 <sup>(1)</sup>	uuu1 0uuu	uuuu	

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

TABLE 8-12: INITIALIZATION CONDITIONS FOR ALL REGISTERS, PIC16C710/71/711

Register	Power-on Reset, Brown-out Reset <sup>(5)</sup>	MCLR Resets WDT Reset	Wake-up via WDT or Interrupt
W	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	N/A	N/A	N/A
TMR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000h	0000h	PC + 1(2)
STATUS	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	x 0000	u 0000	u uuuu
PORTB	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCLATH	0 0000	0 0000	u uuuu
INTCON	0000 000x	0000 000u	uuuu uuuu(1)
ADRES	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	00-0 0000	00-0 0000	uu-u uuuu
OPTION	1111 1111	1111 1111	uuuu uuuu
TRISA	1 1111	1 1111	u uuuu
TRISB	1111 1111	1111 1111	uuuu uuuu
PCON <sup>(4)</sup>	0u	uu	uu
ADCON1	00	00	uu

Legend: u = unchanged, x = unknown, -= unimplemented bit, read as '0', <math>q = value depends on condition Note 1: One or more bits in INTCON will be affected (to cause wake-up).

- 2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).
- 3: See Table 8-10 for reset value for specific condition.
- 4: The PCON register is not implemented on the PIC16C71.
- 5: Brown-out reset is not implemented on the PIC16C71.

# PIC16C71X

TABLE 8-13: INITIALIZATION CONDITIONS FOR ALL REGISTERS, PIC16C715

Register	Power-on Reset, Brown-out Reset Parity Error Reset	MCLR Resets WDT Reset	Wake-up via WDT or Interrupt
W	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	N/A	N/A	N/A
TMR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	PC + 1(2)
STATUS	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	x 0000	u 0000	u uuuu
PORTB	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCLATH	0 0000	0 0000	u uuuu
INTCON	0000 000x	0000 000u	uuuu uuuu(1)
PIR1	-0	-0	-u (1)
ADCON0	0000 00-0	0000 00-0	uuuu uu-u
OPTION	1111 1111	1111 1111	uuuu uuuu
TRISA	1 1111	1 1111	u uuuu
TRISB	1111 1111	1111 1111	uuuu uuuu
PIE1	T+0 WW	-0	-u
PCON	qqq	1uu	1uu
ADCON1	00		uu

Legend: u = unchanged, x = unknown, -= unimplemented bit, read as '0', <math>q = value depends on condition Note 1: One or more bits in INTCON and PIR1 will be affected (to cause wake-up).

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<sup>2:</sup> When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

<sup>3:</sup> See Table 8-11 for reset value for specific condition.



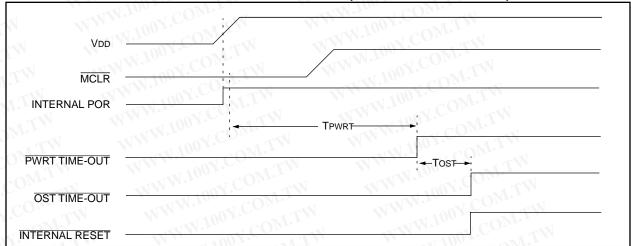


FIGURE 8-12: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2

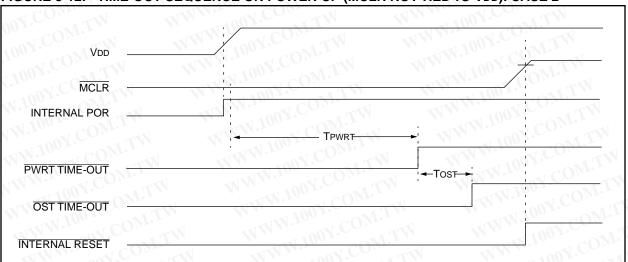


FIGURE 8-13: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)

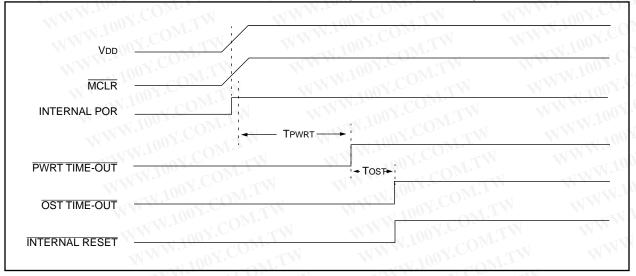
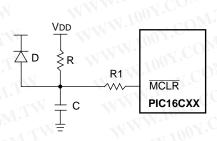


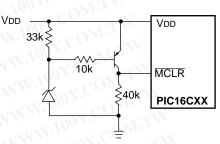
FIGURE 8-14: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- Note 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
  - R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.
  - 3:  $R1 = 100\Omega$  to 1 k $\Omega$  will limit any current flowing into  $\overline{MCLR}$  from external capacitor C in the event of  $\overline{MCLR}/VPP$  pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

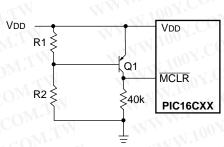
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# FIGURE 8-15: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1



- Note 1: This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.
  - Internal brown-out detection on the PIC16C710/711/715 should be disabled when using this circuit.
  - Resistors should be adjusted for the characteristics of the transistor.

# FIGURE 8-16: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



Note 1: This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \cdot \frac{R1}{R1 + R2} = 0.7V$$

- 2: Internal brown-out detection on the PIC16C710/711/715 should be disabled when using this circuit.
- 3: Resistors should be adjusted for the characteristics of the transistor.

## 8.5 Interrupts

# Applicable Devices 710 71 711 715

The PIC16C71X family has 4 sources of interrupt.

Interrupt Sources	
External interrupt RB0/INT	
TMR0 overflow interrupt	XI
PORTB change interrupts (pins RB7:RB4)	
A/D Interrupt	11/

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 8-19). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

#### Note: For the PIC16C71

If an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the RETFIE instruction). The events that would cause this to occur are:

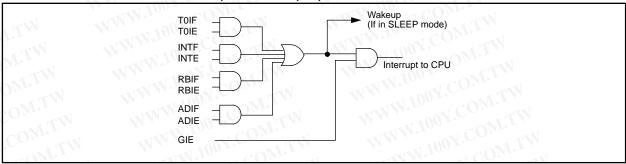
- An instruction clears the GIE bit while an interrupt is acknowledged.
- The program branches to the Interrupt vector and executes the Interrupt Service Routine.
- The Interrupt Service Routine completes with the execution of the RET-FIE instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.

Perform the following to ensure that interrupts are globally disabled:

```
LOOP BCF INTCON, GIE ; Disable global ; interrupt bit BTFSC INTCON, GIE ; Global interrupt ; disabled?

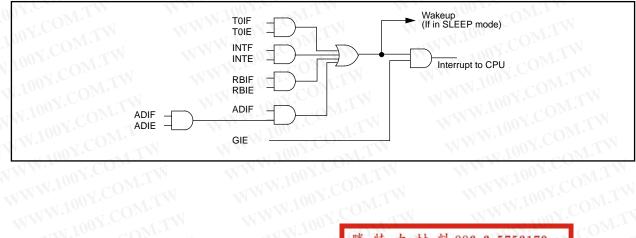
GOTO LOOP ; NO, try again ; Yes, continue ; with program
```

FIGURE 8-17: INTERRUPT LOGIC, PIC16C710, 71, 711



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# FIGURE 8-18: INTERRUPT LOGIC, PIC16C715



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#### 8.5.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if bit INTEDG (OPTION<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 8.8 for details on SLEEP mode.

#### 8.5.2 TMR0 INTERRUPT

An overflow (FFh  $\rightarrow$  00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 6.0)

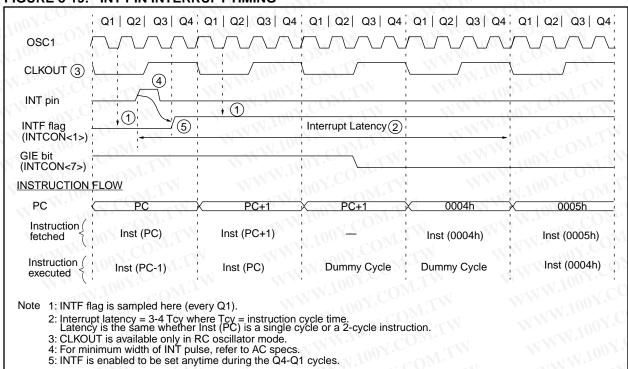
#### 8.5.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 5.2)

Note: For the PIC16C71

if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

# FIGURE 8-19: INT PIN INTERRUPT TIMING



## 8.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt i.e., W register and STATUS register. This will have to be implemented in software.

Example 8-1 stores and restores the STATUS and W registers. The user register, STATUS\_TEMP, must be defined in bank 0.

## The example:

- a) Stores the W register.
- b) Stores the STATUS register in bank 0.
- c) Executes the ISR code.
- d) Restores the STATUS register (and bank select bit).
- e) Restores the W register.

# **EXAMPLE 8-1: SAVING STATUS AND W REGISTERS IN RAM**

```
MOVWF
         W_TEMP
                           ;Copy W to TEMP register, could be bank one or zero
SWAPF
         STATUS, W
                           ; Swap status to be saved into W
                           ;Save status to bank zero STATUS_TEMP register
MOVWF
         STATUS_TEMP
:(ISR)
SWAPF
         STATUS_TEMP, W
                           ;Swap STATUS_TEMP register into W
                           ; (sets bank to original state)
MOVWF
         STATUS
                           ; Move W into STATUS register
SWAPF
         W_TEMP, F
                           ;Swap W_TEMP
         W_TEMP,W
                           ;Swap W_TEMP into W
SWAPF
```

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# 8.7 Watchdog Timer (WDT)

# Applicable Devices 710 71 711 715

The Watchdog Timer is as a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device RESET (Watchdog Timer Reset). If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation (Watchdog Timer Wake-up). The WDT can be permanently disabled by clearing configuration bit WDTE (Section 8.1).

#### 8.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be

assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET condition

The  $\overline{\text{TO}}$  bit in the STATUS register will be cleared upon a Watchdog Timer time-out.

#### 8.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken into account that under worst case conditions (VDD = Min., Temperature = Max., and max. WDT prescaler) it may take several seconds before a WDT time-out occurs.

When a CLRWDT instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

prescaler with a division ratio of up to 1:128 can be

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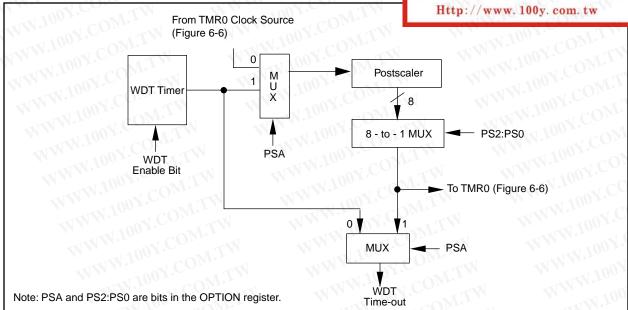


FIGURE 8-21: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	(1)	BODEN <sup>(1)</sup>	CP1	CP0	PWRTE <sup>(1)</sup>	WDTE	FOSC1	FOSC0
81h,181h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer.

Note 1: See Figure 8-1, Figure 8-2 and Figure 8-3 for operation of these bits.

# 8.8 Power-down Mode (SLEEP)

Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the  $\overline{PD}$  bit (STATUS<3>) is cleared, the  $\overline{TO}$  (STATUS<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD, or Vss, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D, disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or Vss for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

#### 8.8.1 WAKE-UP FROM SLEEP

The device can wake up from SLEEP through one of the following events:

- External reset input on MCLR pin.
- Watchdog Timer Wake-up (if WDT was enabled).
- Interrupt from INT pin, RB port change, or some Peripheral Interrupts.

External  $\overline{MCLR}$  Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The  $\overline{TO}$  and  $\overline{PD}$  bits in the STATUS register can be used to determine the cause of device reset. The  $\overline{PD}$  bit, which is set on power-up, is cleared when SLEEP is invoked. The  $\overline{TO}$  bit is cleared if a WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

- TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
- 2. A/D conversion (when A/D clock source is RC).

Other peripherals cannot generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

#### 8.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs before the the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the TO bit will not be set and PD bits will not be cleared.
- If the interrupt occurs during or after the execution of a SLEEP instruction, the device will immediately wake up from sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the TO bit will be set and the PD bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the  $\overline{PD}$  bit. If the  $\overline{PD}$  bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

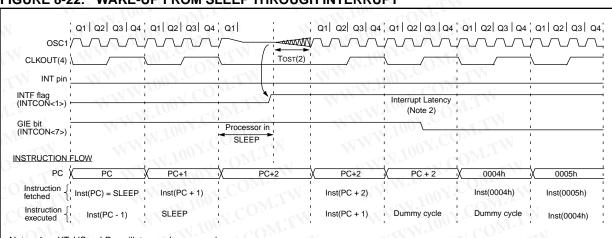


FIGURE 8-22: WAKE-UP FROM SLEEP THROUGH INTERRUPT

Note 1: XT, HS or LP oscillator mode assumed.

- 2: Tost = 1024Tosc (drawing not to scale) This delay will not be there for RC osc mode.
- 3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
- 4: CLKOUT is not available in these osc modes, but shown here for timing reference.

## 8.9 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

**Note:** Microchip does not recommend code protecting windowed devices.

## 8.10 ID Locations

Four memory locations (2000h - 2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the 4 least significant bits of the ID location are used.

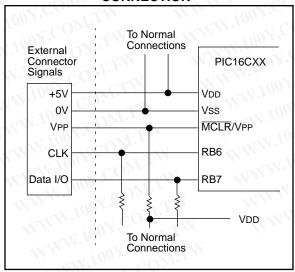
# 8.11 <u>In-Circuit Serial Programming</u>

PIC16CXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

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After reset, to place the device into programming/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X Programming Specifications (Literature #DS30228).

FIGURE 8-23: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



# PIC16C71X

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## 9.0 INSTRUCTION SET SUMMARY

Each PIC16CXX instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXX instruction set summary in Table 9-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 9-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 9-1: OPCODE FIELD DESCRIPTIONS

f W b	Register file address (0x00 to 0x7F) Working register (accumulator) Bit address within an 8-bit file register Literal field, constant data or label Don't care location (= 0 or 1)
b k	Bit address within an 8-bit file register Literal field, constant data or label
k	Literal field, constant data or label
< 2/ A 4	Don't care location (= 0 or 1)
x	The assembler will generate code with $x=0$ . It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination either the W register or the specified register file location
[]	Options
( )	Contents
$\rightarrow$	Assigned to
<>	Register bit field
€	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- · Byte-oriented operations
- · Bit-oriented operations
- · Literal and control operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1  $\mu s$ . If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2  $\mu s$ .

Table 9-2 lists the instructions recognized by the MPASM assembler.

Figure 9-1 shows the general formats that the instructions can have.

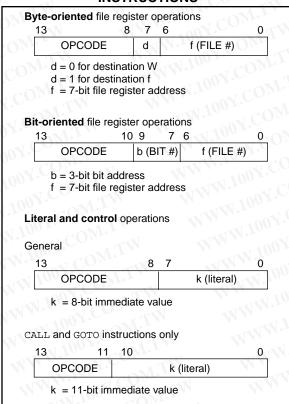
**Note:** To maintain upward compatibility with future PIC16CXX products, <u>do not use</u> the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 9-1: GENERAL FORMAT FOR INSTRUCTIONS



# PIC16C71X

**TABLE 9-2:** PIC16CXX INSTRUCTION SET

ADDWF 1 ANDWF 1 CLRF 1 CLRW - COMF 1 DECF 1 DECFSZ 1 INCF 1 INCFSZ 1	TED   f, d f, d f - f, d f, d f, d f, d f, d	FILE REGISTER OPERATIONS  Add W and f AND W with f Clear f Clear W Complement f Decrement f Decrement f, Skip if 0 Increment f, Skip if 0	1 1 1 1 1 1 1 1(2)	00 00 00 00 00 00 00	0111 0101 0001 0001 1001 0011	dfff lfff	ffff ffff ffff xxxx ffff	C,DC,Z Z Z Z Z	1,2 1,2 2
ADDWF 1 ANDWF 1 CLRF 1 CLRW - COMF 1 DECF 1 DECFSZ 1 INCF 1 INCFSZ 1	f, d f, d f - f, d f, d f, d f, d f, d	Add W and f AND W with f Clear f Clear W Complement f Decrement f Decrement f, Skip if 0 Increment f	1 1 1 1 1 1 (2)	00 00 00 00 00	0101 0001 0001 1001	dfff lfff 0xxx dfff	ffff ffff xxxx	Z Z Z	1,2 2
ANDWF 1 CLRF 1 CLRW - COMF 1 DECF 1 DECFSZ 1 INCF 1 INCFSZ 1 INCFSZ 1 INCFSZ 1 INCFSZ 1 INCFSZ 1	f, d f - f, d f, d f, d f, d f, d	AND W with f Clear f Clear W Complement f Decrement f Decrement f, Skip if 0 Increment f	1 1 1 1 1 1 (2)	00 00 00 00 00	0101 0001 0001 1001	dfff lfff 0xxx dfff	ffff ffff xxxx	Z Z Z	1,2 2
CLRF 1 CLRW - COMF 1 DECF 1 DECFSZ 1 INCF 1 INCFSZ 1 INCFSZ 1 IORWF 1 MOVF 1	f - f, d f, d f, d f, d f, d f, d	Clear f Clear W Complement f Decrement f Decrement f, Skip if 0 Increment f	1 1 1 1 1 1(2)	00 00 00 00	0001 0001 1001	lfff 0xxx dfff	ffff xxxx	Z Z	2
CLRW - COMF 1 DECF 1 DECFSZ 1 INCF 1 INCFSZ 1 INCFSZ 1 INCFSZ 1 INCFSZ 1	- f, d f, d f, d f, d f, d f, d	Clear W Complement f Decrement f Decrement f, Skip if 0 Increment f	1 1 1 1 1(2)	00 00 00	0001 1001	0xxx dfff	xxxx	Z	
COMF 1 DECF 1 DECFSZ 1 INCF 1 INCFSZ 1 IORWF 1 MOVF 1	f, d f, d f, d f, d f, d f, d	Complement f Decrement f Decrement f, Skip if 0 Increment f	1 1(2)	00	1001	dfff			
DECF 1 DECFSZ 1 INCF 1 INCFSZ 1 IORWF 1 MOVF 1	f, d f, d f, d f, d f, d f, d	Decrement f Decrement f, Skip if 0 Increment f	1 1(2)	00			ffff	7	
DECFSZ 1 INCF 1 INCFSZ 1 IORWF 1 MOVF 1	f, d f, d f, d f, d	Decrement f, Skip if 0 Increment f	1(2)		0011	4666		4	1,2
INCF 1 INCFSZ 1 IORWF 1 MOVF 1	f, d f, d f, d	Increment f		0.0		allI	ffff	Z	1,2
INCFSZ 1 IORWF 1 MOVF 1	f, d f, d		1 1	UU	1011	dfff	ffff	N.	1,2,3
IORWF 1	f, d	Increment f. Skip if 0		00	1010	dfff	ffff	Z	1,2
MOVF 1	,		1(2)	00	1111	dfff	ffff	TW	1,2,3
	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
		Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff	1.	
NOP -		No Operation	1	00	0000	0xx0	0000	TIM	
RLF 1	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	1,2
RRF 1	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	1,2
	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF 1	f, d	Swap nibbles in f	1	00	1110	dfff	ffff	JOM.	1,2
	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENTE	D FIL	E REGISTER OPERATIONS	CONTRACTO		TN T	MAG	. 001	COM	TW
BCF 1	f, b	Bit Clear f	0 1	01	00bb	bfff	ffff	COM	1,2
BSF 1	f, b	Bit Set f	11	01	01bb	bfff	ffff	1.0	1,2
BTFSC 1	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff	T COD	3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff	01.	3
LITERAL AND	D CO	NTROL OPERATIONS	W.Con	W		MW	11	001.00	Tire
ADDLW I	k	Add literal and W	×/ (101	11	111x	kkkk	kkkk	C,DC,Z	D 27
ANDLW I	k 0	AND literal with W	11	11	1001	kkkk	kkkk	Z	Mo.
CALL	k	Call subroutine	C 2	10	0kkk	kkkk	kkkk	. VOO.	05
CLRWDT -	-10	Clear Watchdog Timer	100 1 100	00	0000	0110	0100	TO,PD	CON
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk	1007	
IORLW I	k 1	Inclusive OR literal with W	1.100	11	1000	kkkk	kkkk	Z	700
	k	Move literal to W	1011	11	00xx			1100	
RETFIE -	-W.	Return from interrupt	200	00	0000	0000	1001	M. T.	J C
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk	-XXI 10	7.
	-VV	Return from Subroutine	2	00	0000	0000	1000	M.M.	N.V.C
	<u>.</u>	Go into standby mode	104	00	0000	0110	0011	TO,PD	20 2
_	k	Subtract W from literal	1	11		kkkk	kkkk	C,DC,Z	M.
	k	Exclusive OR literal with W	11190 1	11	1010		kkkk	Z Z	The

Note 1: When an I/O register is modified as a function of itself (e.g., MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned

If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

#### 9.1 **Instruction Descriptions**

ADDLW	Add Literal and W	ANDLW	AND Literal with W					
Syntax:	[label] ADDLW k	Syntax:	tax: [ <i>label</i> ] ANDLW k					
Operands:	$0 \le k \le 255$	Operands:	0 ≤ k ≤ 255					
Operation:	$(W) + k \rightarrow (W)$	Operation:	(W) .AND. (k) $\rightarrow$ (W) : Z					
Status Affected:	C, DC, Z	Status Affected:						
Encoding:	11 111x kkkk kkkk	Encoding:	11 1001 kkkk kkkk					
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.	Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.					
Words:	1 WWW.100Y.COM	Words:	OON.COM.TW					
Cycles:	1 NWW.LOOV.COM	Cycles:	oby.Come TW					
Q Cycle Activity:	Q1 Q2 Q3 Q4	Q Cycle Activity:	Q1 Q2 Q3 Q4					
	Decode Read Process Write to data W		Decode Read Process Write to data W					
Example:	ADDLW 0x15	Example	ANDLW 0x5F					
	Before Instruction  W = 0x10  After Instruction  W = 0x25		Before Instruction  W = 0xA3  After Instruction  W = 0x03					
ADDWE CO	Add Wand f	ANDWE AND W with f						

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ADDWF	Add W and f				<b>Y</b> . C	ANDWF	AND W with f				
Syntax:	[label] ADDWF f,d				OXIC	Syntax:	[label] ANDWF f,d				
Operands:	$0 \le f \le 127$ $d \in [0,1]$					Operands:	$0 \le f \le 127$ $d \in [0,1]$				
Operation:	$(W) + (f) \to (dest)$					Operation:	(W) .AND. (f) $\rightarrow$ (dest)				
Status Affected:	C, DC, Z					Status Affected:	Z W 100 2. COM.				
Encoding:	00	0111	dfff	ffff	×1 10	Encoding:	00	0101	dfff	ffff	
Description:	Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.					Description:	AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.				
Words:	1.00 L. COM. 1 V					Words:	1 NAMAN TO A COL				
Cycles:	1 100					Cycles:	1				
Q Cycle Activity:	Q1 Q2 Q3 Q4					Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process data	Write to Dest	W		Decode	Read register 'f'	Process data	Write to Dest	
Example	ADDWF	FSR,	0			Example	ANDWF	FSR,	1		
	Before Instruction					Before Instruction					
	W = 0x17 FSR = 0xC2							W = FSR =	0x17 0xC2		
	After Instruction						After Instruction				
	W = 0xD9 $FSR = 0xC2$							W =	0x17		
								FSR =	0x02		

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# PIC16C71X

BCF Bit Clear f

Syntax: [label] BCF f,b

Operands:  $0 \le f \le 127$  $0 \le b \le 7$ 

Operation:  $0 \rightarrow (f < b >)$ 

Status Affected: None

Encoding: 01 00bb bfff ffff

Description: Bit 'b' in register 'f' is cleared.

Words: 1
Cycles: 1

Q Cycle Activity: Q1 Q2 Q3 Q4

Decode Read Process Write register 'f'

Example BCF FLAG\_REG, 7

Before Instruction

 $FLAG_REG = 0xC7$ 

After Instruction

 $FLAG_REG = 0x47$ 

**BTFSC** Bit Test, Skip if Clear [label] BTFSC f,b Syntax: Operands:  $0 \le f \le 127$  $0 \le b \le 7$ Operation: skip if (f < b >) = 0Status Affected: None Encoding: 10bb bfff ffff 0.1

Description: If bit 'b' in register 'f' is '1' then the next

instruction is executed.

If bit 'b', in register 'f', is '0' then the next instruction is discarded, and a NOP is executed instead, making this a 2TCY

instruction.

Words: 1 Cycles: 1(2)

Q Cycle Activity: Q1

If Skip: (2nd Cycle)

 Q1
 Q2
 Q3
 Q4

 NOP
 NOP
 NOP
 NOP

Example HERE BTFSC FLAG,1
FALSE GOTO PROCESS\_CODE

TRUE •

Before Instruction

PC = address HERE

After Instruction

if FLAG<1> = 0, PC = address TRUE

if FLAG<1>=1,

PC = address FALSE

BSF Bit Set f

Syntax: [label] BSF f,b

 $0 \le f \le 127$  $0 \le b \le 7$ 

Operation:  $1 \rightarrow (f < b >)$ 

Status Affected: None

Operands:

Encoding: 01 01bb bfff ffff

Description: Bit 'b' in register 'f' is set.

Words: 1 Cycles: 1

Q Cycle Activity: Q1 Q2 Q3 Q4

Decode Read Process Write register 'f'

Example BSF FLAG\_REG, 7

Before Instruction

 $FLAG_REG = 0x0A$ 

After Instruction

 $FLAG_REG = 0x8A$ 

BTFSS	Bit Test	f, Skip if	Set		CALL	Call Sub	oroutine		
Syntax:	[label] B	ΓFSS f,b	M.r		Syntax:	[ label ]	CALL I	<	
Operands:	$0 \le f \le 12$				Operands:	$0 \le k \le 2$	047		
	$0 \le b < 7$				Operation:	(PC)+ 1-			
Operation:	skip if (f<	(b>) = 1				$k \rightarrow PC$		DO 40	
Status Affected:	None	To	$CO_{Mr}$	CW.	WWW.LOOY.	J. T.	1<4:3>) -	→ PC<12	.:11>
Encoding:	01	11bb	bfff	ffff	Status Affected:	None	ICAN .		
Description:		register 'f'	is '0' then t	he next	Encoding:	10	0kkk	kkkk	kkkk
	If bit 'b' is discarded	1', then the	e next instr P is execut a 2Tcy ins	ed	Description:	(PC+1) is eleven bit into PC bi	pushed or immediate ts <10:0>.	st, return a nto the sta e address i The uppe	ck. The s loaded r bits of
Words:	1							rom PCLA instruction	
Cycles:	1(2)				Words:	10Y.C	~ 1 T		
Q Cycle Activity:	Q1	Q2	Q3	Q4	Cycles:	2			
	Decode	Read register 'f'	Process data	NOP	Q Cycle Activity:	Q1	Q2	Q3	Q4
If Skip:	(2nd Cyc		W.100	COM	1st Cycle	Decode	Read	Process	Write
1007 . Or OKIP.	Q1	Q2	Q3	Q4		W.100	literal 'k', Push PC	data	PC
	NOP	NOP	NOP	NOP	and Cyala	NOP	to Stack	NOP	NOP
	TW		141	1001.C	2nd Cycle	NOP	NOP	NOP	NOF
Example	HERE	BTFSC	FLAG,1		Example	HERE	CALL	THERE	
	FALSE TRUE	GOTO •	PROCESS.	_CODE	OM	Before Ir	nstruction	COM	
		•						Address HE	ERE
	TIMO	Ν•				After Ins		Address TH	TEDE
	Before In		address I	UPDE 100				Address IF Address HE	
	After Inst		auuless i	HEKE					
		if FLAG<1		MM.To					
		PC = if FLAG<1	address F.	ALSE					
		PC =	address T	RUE					

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CLRF Clear f

Syntax: [label] CLRF f

Operands:  $0 \le f \le 127$ Operation:  $00h \rightarrow (f)$  $1 \rightarrow Z$ 

Status Affected: Z

Encoding: 00 0001 1fff ffff

Description: The contents of register 'f' are cleared

and the Z bit is set.

Words: 1 Cycles: 1

Q Cycle Activity: Q1 Q2 Q3

Decode Read Process Write register 'f'

Q4

Example CLRF FLAG\_REG

Before Instruction

 $FLAG_REG = 0x5A$ 

After Instruction

 $FLAG_REG = 0x00$ Z = 1

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-54151736 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw CLRW Clear W

Syntax: [ label ] CLRW

Status Affected: Z

Encoding: 00 0001 0xxx xxxx

Description: W register is cleared. Zero bit (Z) is

set.

Words: 1 Cycles: 1

Q Cycle Activity: Q1 Q2

 Q1
 Q2
 Q3
 Q4

 Decode
 NOP
 Process data
 Write to W

Example CLRW

Before Instruction

W = 0x5A

After Instruction

W = 0x00 Z = 1

CLRWDT Clear Watchdog Timer

Syntax: [ label ] CLRWDT

Operands: None

Operation:  $00h \rightarrow WDT$ 

 $0 \rightarrow WDT$  prescaler,

 $1 \to \overline{10}$  $1 \to \overline{PD}$ 

Status Affected: TO, PD

Encoding: 00

Description: CLRWDT instruction resets the Watch-

dog Timer. It also resets the prescaler of the WDT. Status bits TO and PD

0110

0100

0000

are set.

Words: 1 Cycles: 1

Q Cycle Activity:

 Q1
 Q2
 Q3
 Q4

 Decode
 NOP
 Process data
 Clear WDT Counter

Example CLRWDT

Before Instruction

WDT counter = ?

After Instruction

 WDT counter
 =
 0x00

 WDT prescaler
 0

 TO
 =
 1

 PD
 =
 1

Description:  The contents of register 1" are complemented. If d is 0 the result is stored in W. If d is 1 the result is stored back in register 1".  Words:  Cycles:  1  Q Cycle Activity:  Q1 Q2 Q3 Q4  Decode Read Process Write to register 1 and data Process P	OMF	Comple		17.		DECFSZ	Decreme	ent f, Sk	ip if 0	
$d \in [0,1]$ Operation: $d \in [0,1]$ Operation: $(f) \rightarrow (dest)$ Status Affected: $Z$ Encoding: $Description: The contents of register f' are complemented. If d' is 0 the result is stored in W. If d' is 1 the result is stored in W. If d' is 1 the result is stored in Register f'.  Words: 1 Oycles: 1 Q Cycle Activity: Q1  Q2  Q3  Q4 Example COMF  REG1, 0 Before Instruction REG1 = 0x13 After Instruction REG1 = 0x13 After Instruction REG1 = 0x13 W = 0xEC  DECF Decrement f Syntax: [label]  DECF f, d Operation: (f) \cdot 1 \rightarrow (dest) Status Affected: None  Encoding: Doscription: The contents of register f' are demented. If d' is 0 the result is 1, the next instruction executed. If the result is 0, then at executed in the Weighter f'. If the result is 1, the next instruction executed. If the result is 1, the next instruction executed. If the result is 1, the next instruction executed. If the result is 1, the next instruction executed. If the result is 1, the next instruction executed. If the result is 2 To instruction.  If Skip: (2nd  Cycles) Q1 Q2 Q3  \[ \begin{array}{c} Q1  Q2  Q3 \\  \end{array} \] \[ \begin{array}{c} Decode  Read  Process  register f'. If  is 1  \qu$	Syntax:	[ label ]	COMF	f,d		Syntax:	[ label ]	DECFS	Z f,d	
Status Affected: Z Encoding:	Operands:		27 V			Operands:				
Encoding:    Description:   The contents of register "f are complemented. If "d is 0 the result is stored in W. If "d is 1 the result is stored back in register "f"   The contents of register "f"   The result is place to the Wregister. If "d is 1 the result is place to the Wregister. If "d is 1 the result is place to the Wregister. If "d is 1 the result is place to the Wregister. If "d is 1 the result is place to the Wregister. If "d is 1 the result is place to the Wregister. If "d is 1 the result is place to the Wregister of the Wregister. If "d is 1 the result is place to the Wregister. If "d is 1 the result is place to the Wregister. If "d is 2 the result is place to the Wregister. If "d is 3 the result is place to the Wregister. If "d is 3 the result is place to the Wregister. If "d is 3 the result is place to the Wregister. If "d is 3 the result is place to the wregister. If "d is 3 the result is place to the wregister. If "d is 3 the result is place to the wregister. If "d is 3 the result is place to the wregister. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register. If "d is 3 the result is stored back in register	Operation:	$(\bar{f}) \rightarrow (de$	st)			Operation:	(f) - 1 $\rightarrow$	(dest);	skip if re	esult =
Description: The contents of register 'T are complemented. If 'd is 0 the result is stored in Wilf of is 1 the result is stored back in register 'F.  Words: 1  Cycles: 1  Q Cycle Activity: Q1 Q2 Q3 Q4  Decode Read Process Write to register 'F.  Example COMF REG1 , 0  Before Instruction REG1 = 0x13 After Instruction REG1 = 0x13 W = 0xEC  Decrement f  Syntax: [label] DECF f,d  Operands: 0 ≤ f ≤ 127 d ∈ [0,1]  Operation: Q1 Q2 Q3 Q4  Encoding: Decrement register 'F. If 'd is 0 the result is stored in the W register. If 'd is 1 the result is place dask in register 'T.  If the result is 1, the next instruction sevecuted. If the result is 1, the next instruction. If the result is 1, the next instruction. If the result is 1, the next instruction sevecuted instead making it a 2Tcv instruction. If Skip: Qcycle Activity: Q1 Q2 Q3  Decode Read Process register register register register register register. If a label of the very register register register register. If Continue to the process register register register register. If Continue to the process register register. If Continue to the process register register register. If the result is stored to the result is placed as a continue to the process regi	Status Affected:	Z				Status Affected:	None			
mented. If 'd' is 0 the result is stored in W. I. 'd' is 1 the result is stored in W. I. 'd' is 1 the result is stored back in register 'f'.  Words: 1  Cycles: 1  Q Cycle Activity: Q1 Q2 Q3 Q4  Decode Read register P. REG1, 0  Before Instruction  REG1 = 0x13  After Instruction  REG1 = 0x13  After Instruction  REG1 = 0x13  W = 0xEC   Decode Read register Process Write to executed. If the next instruction executed. If the next instruction executed instead making it a 2T or instruction.  If Skip: Q2 Q3  Decode Read register Process register Proc	ncoding:	00	1001	dfff	ffff	Encoding:	00	1011	dfff	ffff
Example	Vords: Cycles:	mented. If W. If 'd' is	'd' is 0 the 1 the resu	e result is s	stored in	Description:	mented. If the W regis placed bac If the resul executed. I executed in	'd' is 0 the ster. If 'd' is k in regist t is 1, the f the resul nstead ma	e result is place of the result is 0, then a	aced in ult is ction, is a NOP is
Example	Q Cycle Activity:	Q1	Q2	Q3	Q4	Words:	10Y.C			
Example $\frac{1}{\gamma}$ REG1 , 0  Before Instruction REG1 = 0x13 After Instruction REG1 = 0x13 W = 0xEC   Decode Read register right data  NOP NOP NOP NOP  REG1 = 0x13 W = 0xEC   DECF Decrement f Syntax: [/abe/] DECF f,d  Operands: $0 \le f \le 127$ $d \in [0,1]$ Operation: $(f) - 1 \rightarrow (dest)$ Status Affected: Z  Encoding: $0 = 0.011$ After ffff ffff Description: Decrement register right is stored in the W register. If right is 1 the result is stored back in register right for register right at a percent regist		Decode					1(2)			
Example				uala	uesi			Q2	Q3	Q4
Before Instruction REG1 = $0x13$ After Instruction REG1 = $0x13$ W = $0xEC$	Example	COMF	REC	G1,0		TIM MA	Decode	register	Process	Write t
After Instruction REG1 = $0x13$ W = $0xEC$					OUN.CO	Wiles William	(0.40)	1.	7177	
REG1 = 0x13 W = 0xEC         NOP NOP NOP NOP         DECF Decrement f       Example       HERE DECFSZ CNT, GOTO LOOP         Syntax: [Jabel] DECF f,d       CONTINUE •         Operands: $0 \le f \le 127$ def [0,1]       •				= UX1.	3.0° CC	If Skip:	1		OaT	W Q4
DECF Decrement f Example HERE DECFSZ CNT, GOTO LOOP CONTINUE • QOTO LOOP QOTO LO			REG1				-41\N+2		A U IV	NOP
Syntax: [label] DECF f,d			W	= 0xE	$C^{100}$		INOI	INOI	1101	1101
Operands: $0 \le f \le 127$	DECF	Decreme	ent f	MAI	W.100 Y.	Example	HERE			
Operation: $0 \le f \le 127$ $d \in [0,1]$ Operation: $(f) - 1 \to (dest)$ Status Affected: $Z$ Encoding: $0 = 0.011 = 0.0011 $	Syntax:	[label] [	DECF f,d				CONTIN		LOC	OP
Status Affected: Z  Encoding:  Description:  Description	Operands:		27					VV.10		
Status Affected: Z  Encoding: 00 0011 dfff ffff  Description: Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.  Words: 1  Cycles: 1  Q Cycle Activity: Q1 Q2 Q3 Q4  Decode Read register 'f' data dest write to dest register 'f' data dest register 'f' data register 'f' data register 'f' data dest register had a register 'f' data dest register register 'f' data register r	Operation:	(f) - 1 $\rightarrow$	(dest)							$O_{MT}$ .
Description:  Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.  Words:  1  Cycles:  1  Q Cycle Activity:  Q1  Q2  Q3  Q4  Decode Read register 'f' Read register 'f' Adata Read register 'f' Read register 'f' Read register 'f' Read register 'f' Read Read Read register 'f' Read Read Read Read Read Read Read Read	Status Affected:	Z					After Inst	ruction		COM
Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.  Words:  1 Cycles:  1 Q Cycle Activity:  Q1 Q2 Q3 Q4  Decode Read register 'f'   PC = address CONTI if CNT ≠ 0, PC = address HERE+  Write to data   Process   PC = address CONTI   PC = address	ncoding:	00	0011	dfff	ffff				IT - 10	
Words: 1  Cycles: 1  Q Cycle Activity: Q1 Q2 Q3 Q4  Decode Read register r	Description:	Decremer result is st	nt register	'f'. If 'd' is	0 the		PC	= ad	dress CONT	TINUE
Words: 1 Cycles: 1 Q Cycle Activity: Q1 Q2 Q3 Q4 Decode Read register regi		is 1 the res	sult is stor	ed back in	register				dress ਮੁਸ਼ਾਸ	E+1
Cycles: 1 Q Cycle Activity: Q1 Q2 Q3 Q4 Decode Read register 'f' Write to data Write to dest    Read register 'f'   Process data   Write to dest	Vords:	1					. U	W.	L. 555 HERRI	oy.C
Q Cycle Activity: Q1 Q2 Q3 Q4    Decode   Read register 'f'   Process data   Write to dest		1700 -								
Decode Read register 'f' Write to dest Write to dest B 特力材料 886-3-5753170		01	02	03	04	MAN.100 T. COM	17 1		WW.1	no .
register data dest <b>胜特力电子</b> (上海) <b>86-21-54151736</b>	L Cycle Activity.	- 00		40.00		勝特力	材 料 886	3-3-575	3170	003
		100	register							100
胜特力电子(深圳) 86-755-83298787		WN	N.C.	Dian.						c 10
Example DECF CNT, 1 Http://www.100y.com.tw	Example	DECF	CNT,	ONL						11.5
Before Instruction  CNT = 0x01  Z = 0  After Instruction  CNT = 0x00			CNT Z	= 0x0	ITW ITW	M.M. 100X	COM.	LM M	N	WW.

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WWW.1007.

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After Instruction

PC =

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GOTO	Uncondi	itional B	ranch	
Syntax:	[ label ]	GOTO	k .	1.44
Operands:	$0 \le k \le 2$	047		
Operation:	$k \rightarrow PC < PCLATH$		PC<12:1	1>
Status Affected:	None			
Encoding:	10	1kkk	kkkk	kkkk
Description:	GOTO is an eleven bit into PC bit PC are load GOTO is a	immediate ts <10:0>. aded from	e value is l The uppe PCLATH<	oaded r bits of 4:3>.
Words:	1			V.CO
Words: Cycles:	1 2			Y.CO
	N.	Q2	Q3	 Q4
Cycles:	2	Q2 Read literal 'k'	Q3 Process data	Q4
Cycles: Q Cycle Activity:	2 Q1	Read	Process	Q4 Write to
Cycles: Q Cycle Activity: 1st Cycle	2 Q1 Decode	Read literal 'k'	Process data	Q4 Write to PC
Cycles: Q Cycle Activity: 1st Cycle	2 Q1 Decode	Read literal 'k'	Process data	Q4 Write to PC

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Branch	INCF	Increment f
k	Syntax:	[ label ] INCF f,d
	Operands:	$0 \le f \le 127$ $d \in [0,1]$
PC<12:11>	Operation:	(f) + 1 $\rightarrow$ (dest)
	Status Affected:	z
kkkk kkkk	Encoding:	00 1010 dfff ffff
itional branch. The te value is loaded The upper bits of pCLATH<4:3>.	Description:	The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
W.Mon COM.	Words:	N1100 COM.
	Cycles:	1.100x. COM.TW
Q3 Q4	Q Cycle Activity:	Q1 Q2 Q3 Q4
Process Write to data PC		Decode Read Process Write to register data dest
NOP NOP		TAN A COM
WW 1007	Example	INCF CNT, 1
		Before Instruction
YWW.		$ \begin{array}{rcl} CNT &=& 0xFF \\ 7 &=& 0 \end{array} $
Address THERE		Z = 0 After Instruction
		CNT = 0x00

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**INCFSZ** Increment f, Skip if 0 Syntax: [ label ] INCFSZ f,d Operands:  $0 \le f \le 127$  $d \in [0,1]$ Operation: (f) + 1  $\rightarrow$  (dest), skip if result = 0 Status Affected: None Encoding: 1111 dfff ffff Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f' If the result is 1, the next instruction is executed. If the result is 0, a NOP is executed instead making it a 2Tcy instruction. Words: 1 Cycles: 1(2) Q Cycle Activity: Q1 Q2 Q3 Q4 Write to Decode Read Process register 'f' data dest If Skip: (2nd Cycle) Q1 Q2 Q3 Q4 NOP NOP NOP NOP Example HERE TNCFS7 CNT, 1 GOTO LOOP CONTINUE Before Instruction PC address HERE After Instruction CNT CNT + 1 if CNT= 0, PC address CONTINUE if CNT≠ 0, PC address HERE

**IORLW** Inclusive OR Literal with W [label] IORLW k Syntax: Operands:  $0 \le k \le 255$ Operation: (W) .OR.  $k \rightarrow (W)$ Status Affected: Z Encoding: 1000 kkkk kkkk Description: The contents of the W register is OR'ed with the eight bit literal 'k'. The result is placed in the W register. Words: Cycles: Q Cycle Activity: Q1 Q2 Q3 Q4 Read Write to Decode **Process** literal 'k' data W Example IORLW 0x35Before Instruction W 0x9A After Instruction W 0xBF Z =

IORWF	Inclusive	OR W	with f	
Syntax:	[ label ]	IORWF	f,d	-31
Operands:	$0 \le f \le 12$ $d \in [0,1]$	27100		
Operation:	(W) .OR.	$(f) \rightarrow (d$	est)	
Status Affected:	Z			
Encoding:	0.0	0100	dfff	ffff
Description:	ter 'f'. If 'd'	is 0 the r ster. If 'd'	register wi esult is pla is 1 the rester 'f'.	ced in
Words: Cycles:	N1 1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read register 'f'	Process data	Write to dest
	T. T.		WWW	· · · · · · · · · · · · · · · · · · ·
Example	IORWF		RESULT,	0
	Before In	structior RESULT W	0x13 = 0x91 = 0x91	

	After Ins	w truction RESULT W Z	= = =	0x91 0x13 0x93 1	N VV.10	
MOVF	Move f					V.100 N
Syntax:	[ label ]	MOVF	f,d		WW	W.10\s
Operands:	$0 \le f \le 12$ $d \in [0,1]$	- ( ) Y				0
Operation:	$(f) \rightarrow (d\epsilon)$	est)				S
Status Affected:	Z					E
Encoding:	00	1000	df	ff	ffff	D
Description:	a destinate tus of d. It ister. If deregister f	ents of reg tion deper f d = 0, de = 1, the de itself. $d = 0$ er since st	ndant stina estina 1 is u	upon tion is ation is seful t	the sta- W reg- s file to test a	W C Q
Words:	1					
Cycles:	1					Е
Q Cycle Activity:	Q1	Q2	0	23	Q4	
	Decode	Read register 'f'		cess ata	Write to dest	
Example	MOVF	FSR,	0			

After Instruction

Z = 1

W = value in FSR register

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MM.100X.CC	MTW			
MOVLW	Move Lit	teral to V	V	
Syntax:	[ label ]	MOVLW	/ k	
Operands:	$0 \le k \le 2$	55		
Operation:	$k\to(W)$			
Status Affected:	None			
Encoding:	11	00xx	kkkk	kkkk
Description:	110 -		k' is loaded ares will as	
Words:	1,001.			
Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read literal 'k'	Process data	Write to W
Example	MOVLW	0x5A		
M.TW	After Inst	truction W =	0x5A	IW

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MOVWF	Move W		001	
Syntax:	[ label ]	MOVWI	FV-Y	
Operands:	$0 \le f \le 12$	27		
Operation:	$(W) \rightarrow (f)$	)		
Status Affected:	None			
Encoding:	00	0000	1fff	ffff
Description:	Move data	a from W r	egister to	register
Words:	1 1			
Cycles:	1			
Cycles: Q Cycle Activity:	1 Q1	√ Q2	Q3	Q4
-x1 100	Q1 Decode	Q2 Read register 'f'	Q3 Process data	Q4 Write register 'f'
Q Cycle Activity:		Read register 'f'	Process	Write
Q Cycle Activity:	MOVWF Before In	Read register 'f'  OPTIONSTRUCTION	Process data	Write register 'f'
-11100	MOVWF Before In	Read register 'f'  OPTIC struction OPTION	Process data  ON_REG  = 0xF	Write register 'f'
Q Cycle Activity:	MOVWF Before In	Read register 'f'  OPTIC  Instruction OPTION W	Process data	Write register 'f'
Q Cycle Activity:	Decode  MOVWF  Before In	Read register 'f'  OPTIC  Instruction OPTION W	Process data  ON_REG  = 0xF	Write register 'f'

No Operation NOP Syntax: [label] NOP Operands: None Operation: No operation Status Affected: None Encoding: 00 0000 0xx00000 Description: No operation. Words: Cycles: Q2 Q Cycle Activity: Q1 Q3 Q4 Decode NOP WWW.100Y Example NOP

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OPTION	<b>Load Option Regist</b>	er	M.r.	V.CO		
Syntax:	[ label ] OPTION	- 11	11.11	~ CC	Mir	sī.
Operands:	None			00 r.	$O_{M,I}$	勝
Operation:	$\text{(W)} \rightarrow \text{OPTION}$			100 X.C	T.Mo	胜
Status Affected:	None	1	MAI	100Y.		胜
Encoding:	00 0000 01	10	0010	1.10	$(C_{O_{N_{r}}})$	
	instruction is supported patibility with PIC16C5X Since OPTION is a read register, the user can distance of the property of th	<pre>C product dable/w</pre>	cts. ritable	MM·10		
Words:	patibility with PIC16C5X	<pre>C product dable/w</pre>	cts. ritable	MMN.7		
Cycles:	patibility with PIC16C5X Since OPTION is a read register, the user can di	<pre>C product dable/w</pre>	cts. ritable	MMM MMN:1 MM:10		
ANIN.	patibility with PIC16C5X Since OPTION is a read register, the user can di it.  1	( production of the control of the c	cts. ritable ddress	MAM. MAM. MAN.TO		
Cycles:	patibility with PIC16C5X Since OPTION is a read register, the user can di	compati	cts. ritable ddress	MMM MMM MMM MMM MMM MM/TO		

RETFIE	Return f	rom Inte	rrupt	
Syntax:	[ label ]	RETFIE		
Operands:	None			
Operation:	$\begin{array}{c} TOS \to F \\ 1 \to GIE \end{array}$	PC,		
Status Affected:	None			
Encoding:	00	0000	0000	1001
	and Top of the PC. In ting Global (INTCON- instruction	terrupts a al Interrup <7>). This	re enabled	d by set- it, GIE
Words:	1 C			
Cycles:	2			
Q Cycle Activity:	Q1	Q2	Q3	Q4
1st Cycle	Decode	NOP	Set the GIE bit	Pop from the Stack
2nd Cycle	NOP	NOP	NOP	NOP

Example RETFIE

After Interrupt

PC = TOS GIE = 1

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RETLW	Return v	vith Lite	ral in W	, N	RETURN
Syntax:	[ label ]	RETLW	k	IM	Syntax:
Operands:	$0 \le k \le 2$	55			Operands:
Operation:	$k \rightarrow (W)$				Operation:
$O_{M^{**}}$	$TOS \rightarrow F$	PC			Status Affected:
Status Affected:	None	W.10	-×/ C	JWr.	Encoding:
Encoding:	11	01xx	kkkk	kkkk	Description:
	bit literal 'l loaded fro return add instruction	m the top dress). Thi	of the sta	ick (the	Words: Cycles:
Words:	1				Q Cycle Activity:
Cycles:	2				1st Cycle
Q Cycle Activity:	Q1	Q2	Q3	Q4	13t Oycle
1st Cycle	Decode	Read literal 'k'	NOP	Write to W, Pop from the Stack	2nd Cycle Example
2nd Cycle	NOP	NOP	NOP	NOP	ONEXAMPLE
Example	CALL TABL	;offse	tains tak t value ow has ta	ble ble value	CONTINUE
TABLE	ADDWF PC RETLW k1 RETLW k2	;W = of ;Begin ;			胜架
	)1. CO	$M_{i,I}$	1		IOO TOWN
	RETLW kn		f table		
	Before Ir	Struction W =	0x07		
	After Ins	truction			
		W =	value of	k8	

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_	RETURN	Return fi	rom Sub	routine	
	Syntax:	[ label ]	RETUR	:N	
	Operands:	None			
	Operation:	$TOS \to F$	C		
	Status Affected:	None			
and V	Encoding:	00	0000	0000	1000
TW LTW	Description: Words:	Return fro POPed an is loaded i This is a to	d the top nto the pi	of the star	ck (TOS) unter.
	Cycles:	2			
	Q Cycle Activity:	Q1	Q2	Q3	Q4
	1st Cycle	Decode	NOP	NOP	Pop from the Stack
OM	2nd Cycle	NOP	NOP	NOP	NOP
e COM	Example	RETURN After Inte	rrupt PC =	TOS	

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RLF	Rotate L	eft f thre	ough Car	ry	RRF	Rotate R	light f th	rough C	arry	
Syntax:	[ label ]	RLF	f,d	1	Syntax:	[ label ]	RRF f	,d		
Operands:	$0 \le f \le 12$ $d \in [0,1]$	271.CO			Operands:	$0 \le f \le 12$ $d \in [0,1]$	27			
Operation:	See desc	ription b	elow		Operation:	See desc	cription b	elow		
Status Affected:	C				Status Affected:	CM.T				
Encoding:	00	1101	dfff	ffff	Encoding:	00	1100	dfff	ffff	
Description:		the left th is 0 the re ster. If 'd' ck in regis	rough the esult is pla	Carry ced in	Description:	The conte one bit to Flag. If 'd' the W reg placed ba	the right to is 0 the resister. If 'd' ck in regis	hrough the esult is pla is 1 the re	e Carry ced in	
Words:	1				Words:	1007	OM.			
Cycles:	: CTW 1 WWW. 1007. CO.		Cycles:	V1100Y.						
Q Cycle Activity:	N Q1	Q2	Q3	Q4	Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process data	Write to dest		Decode	Read register 'f'	Process data	Write to dest	
Example	RLF	RE	G1,0	100X.CO	Example	RRF	00 Y.C	REG1,0	W	
	Before In	struction			JWI.	Before In	Before Instruction			
		REG1		0 0110			REG1		0 0110	
	C = 0  After Instruction  REG1 = 1110 0110  W = 1100 1100  C = 1			C = 0  After Instruction  REG1 = 1110 0  W = 0111 0						
						0 0110				
						1 0011				
					C	= 0				

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**SLEEP** 

Syntax: [ label ] SLEEP

Operands: None

Operation:  $00h \rightarrow WDT$ ,

0 → WDT prescaler,

 $1 \to \overline{TO}, \\ 0 \to \overline{PD}$ 

Status Affected: TO, PD

Encoding: 00 0000 0110 0011

Description: The power-down status bit, PD is cleared. Time-out status bit, TO is

set. Watchdog Timer and its pres-

caler are cleared.

The processor is put into SLEEP mode with the oscillator stopped. See Section 8.8 for more details.

Words: 1
Cycles: 1

Q Cycle Activity: Q1 Q2 Q3

Decode NOP NOP Go to Sleep

Q4

Example: SLEEP

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SUBLW Subtract W from Literal

Syntax: [ label ] SUBLW k

Operands:  $0 \le k \le 255$ Operation:  $k - (W) \rightarrow (W)$ 

Status Affected: C, DC, Z

Encoding: 11 110x kkkk kkkk

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'.

The result is placed in the W register.

Words: 1
Cycles: 1

Q Cycle Activity: Q1 Q2 Q3

Decode Read Process Write to W

Q4

Example 1: SUBLW 0x02

Before Instruction

W = 1 C = ? Z = ?

After Instruction

W = 1

C = 1; result is positive

Z = 0

Example 2: Before Instruction

W = 2 C = ?

After Instruction

W = 0

C = 1; result is zero

Z = 1

Example 3: Before Instruction

W = 3 C = ?

Z =

After Instruction

W = 0xFF

C = 0; result is nega-

tivo -

Z = 0

**SUBWF** Subtract W from f Syntax: [ label ] SUBWF  $0 \le f \le 127$ Operands:  $d \in [0,1]$ Operation: (f) - (W)  $\rightarrow$  (dest) Status Affected: C, DC, Z Encoding: 00 0010 dfff Subtract (2's complement method) W reg-Description: ister from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'. Words: Cycles: Q3 Q Cycle Activity: Q1 Q2 Q4 Decode Read Process Write to register 'f data Example 1: SUBWF REG1,1 Before Instruction REG1 W С Z After Instruction

SWAPF	Swap Ni	bbles in	f	
Syntax:	[ label ]	SWAPF	f,d	
Operands:	$0 \le f \le 12$ $d \in [0,1]$	27		
Operation:		ightarrow (dest<		
Status Affected:	None			
Encoding:	00	1110	dfff	ffff
Description:	ter 'f' are e result is p	r and lower exchanged laced in W is placed in	. If 'd' is 0 register. It	the f 'd' is 1
Words:	1 7 0			
Cycles:	1100 1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read register 'f'	Process data	Write to dest
Example	SWAPF	REG,	0	

Before Instruction

After Instruction

REG1

REG1

0xA5

0xA5

W 2 С 1; result is positive Z 0 Before Instruction Example 2: REG1 2 W 2 С ? Z After Instruction REG1 0 W 2 С 1: result is zero Z Example 3: Before Instruction REG1 W С Z After Instruction REG1 0xFF W 2 С 0; result is negative Ζ

REG1

**TRIS Load TRIS Register** Syntax: [label] **TRIS** Operands:  $5 \le f \le 7$ Operation:  $(W) \rightarrow TRIS register f;$ Status Affected: None 00 0000 Encoding: 0110 The instruction is supported for code Description: compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them. Words: Cycles: Example To maintain upward compatibility with future PIC16CXX products, do not use this instruction.

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Illeral k   data   VV	XORLW	Exclusive OR Literal with W	XORWF	Exclusiv	ve OR W	with f	
Operation: (W) .XOR. $k \rightarrow (W)$ Status Affected: Z  Encoding:	Syntax:	[ <i>label</i> ] XORLW k	Syntax:	[label]	XORWF	f,d	
Status Affected: Z  Encoding:	Operands:	0 ≤ k ≤ 255	Operands:				
Status Affected: Z  Encoding:	Operation:	(W) .XOR. $k \rightarrow (W)$	W 1, 100)				
Encoding:    11   1010   kkkk   kkkk     Description:   The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.	Status Affected:		- x1 100		$R. (f) \rightarrow ($	dest)	
Description:  The contents of the W register are XOR'ed with the eight bit literal 'k'.  The result is placed in the W register.  Words:  1  Cycles:  1  Q Cycle Activity:  Q1  Q2  Q3  Q4  Cycles:  1  Q Cycle Activity:  Q1  Q2  Q3  Q4  Cycles:  1  Q Cycle Activity:  Q1  Q2  Q3  Q4  Cycles:  Q Cycle Activity:  Example:  XORLW  0xAF  Before Instruction  W = 0xB5  After Instruction  W = 0x1A  Description:  Exclusive OR the contents of the W register 'f'. If 'd' is 0 the result is stored in the W register. If 'is 1 the result is stored back in regis 'f'.  Cycles:  1  Q Cycle Activity:  Q1  Q2  Q3  Q4  Cycles:  1  Q Cycle Activity:  Q1  Q2  Q3  Q4  Example:  XORWF  REG  1  Before Instruction  REG = 0xAF  W = 0xB5  After Instruction  REG = 0x1A	Encoding:	11 1010 kkkk kkkk		11.	TI		
XOR'ed with the eight bit literal 'k'. The result is placed in the W register.  Words:  1  Cycles:  1  Q Cycle Activity:  Q1  Q2  Q3  Q4  Cycles:  1  Q Cycle Activity:  Decode Read literal 'k' data Write to W at a literal 'k' while	Description:	The contents of the W register are				N	
Cycles: 1  Q Cycle Activity: Q1 Q2 Q3 Q4 Cycles: 1 $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Y.COM.TW	The result is placed in the W regis-	Description:	register w	vith registe stored in th	er 'f'. If 'd' is ne W regis	s 0 the ter. If 'o
Q Cycle Activity:  Q1 Q2 Q3 Q4  Cycles: 1  Q Cycle Activity:  Q1 Q2 Q3 Q  Decode Read   Process   Write to   Q Cycle Activity:  Example:  XORLW $0xAF$ Before Instruction $W = 0xB5$ After Instruction $W = 0x1A$ Example: $XORWF = REG = 0xAF$ $W = 0x1A$ After Instruction  REG = 0x1A		M. M. M. Too V. COM.		l'f'.			
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	0.	OM.	Words:	1.100			
Example: $XORLW = 0xAF$ Before Instruction $W = 0xB5$ After Instruction $W = 0x1A$ Example: $W = 0x1A$ Exam	Q Cycle Activity:	and the same of th	Cycles:	JV.100			
Example: XORLW $0xAF$ Before Instruction $W = 0xB5$ After Instruction $W = 0x1A$ Example XORWF REG 1  Before Instruction $REG = 0xAF$ $W = 0x1A$ After Instruction $REG = 0xAF$		Decode   Read   Process   Write to	Q Cycle Activity:	Q1	Q2	Q3	Q
Example: XORLW $0xAF$ Before Instruction $W = 0xB5$ After Instruction $W = 0x1A$ Example XORWF REG 1 Before Instruction $REG = 0xAF$ $W = 0xB5$ After Instruction $REG = 0x1A$		TW WWW.TOOX.CO		Decode			Writ
W = 0xB5 Example XORWF REG 1 After Instruction Before Instruction $W = 0x1A$ $REG = 0xAF$ $W = 0xB5$ After Instruction $REG = 0x1A$	Example:	XORLW 0xAF		M. M.		Op.	W
After Instruction $W = 0x1A$ $Before Instruction$ $REG = 0xAF$ $W = 0xB5$ $After Instruction$ $REG = 0x1A$			ONI.		Vac	COM.	
W = $0x1A$ $REG = 0xAF$ $W = 0xB5$ After Instruction $REG = 0x1A$			Example				
W = 0xB5 $After Instruction$ $REG = 0x1A$		After Instruction		Before II			1.7
After Instruction  REG = 0x1A		W = 0x1A					
				After Ins	truction		
W = 0xB5					REG		
					W	= 0x	:B5

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### 10.0 DEVELOPMENT SUPPORT

### 10.1 <u>Development Tools</u>

The PICmicro<sup>™</sup> microcontrollers are supported with a full range of hardware and software development tools:

- PICMASTER/PICMASTER CE Real-Time In-Circuit Emulator
- ICEPIC Low-Cost PIC16C5X and PIC16CXXX In-Circuit Emulator
- PRO MATE<sup>®</sup> II Universal Programmer
- PICSTART® Plus Entry-Level Prototype Programmer
- PICDEM-1 Low-Cost Demonstration Board
- PICDEM-2 Low-Cost Demonstration Board
- PICDEM-3 Low-Cost Demonstration Board
- MPASM Assembler
- MPLAB™ SIM Software Simulator
- MPLAB-C (C Compiler)
- Fuzzy Logic Development System (fuzzyTECH<sup>®</sup>-MP)

### 10.2 <u>PICMASTER: High Performance</u> <u>Universal In-Circuit Emulator with</u> MPLAB IDE

The PICMASTER Universal In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for all microcontrollers in the PIC12CXXX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX families. PICMASTER is supplied with the MPLAB™ Integrated Development Environment (IDE), which allows editing, "make" and download, and source debugging from a single environment.

Interchangeable target probes allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the PICMASTER allows expansion to support all new Microchip microcontrollers.

The PICMASTER Emulator System has been designed as a real-time emulation system with advanced features that are generally found on more expensive development tools. The PC compatible 386 (and higher) machine platform and Microsoft Windows® 3.x environment were chosen to best make these features available to you, the end user.

A CE compliant version of PICMASTER is available for European Union (EU) countries.

### 10.3 <u>ICEPIC: Low-Cost PIC16CXXX</u> <u>In-Circuit Emulator</u>

ICEPIC is a low-cost in-circuit emulator solution for the Microchip PIC16C5X and PIC16CXXX families of 8-bit OTP microcontrollers.

ICEPIC is designed to operate on PC-compatible machines ranging from 286-AT<sup>®</sup> through Pentium™ based machines under Windows 3.x environment. ICEPIC features real time, non-intrusive emulation.

### 10.4 PRO MATE II: Universal Programmer

The PRO MATE II Universal Programmer is a full-featured programmer capable of operating in stand-alone mode as well as PC-hosted mode.

The PRO MATE II has programmable VDD and VPP supplies which allows it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for displaying error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In standalone mode the PRO MATE II can read, verify or program PIC12CXXX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX devices. It can also set configuration and code-protect bits in this mode.

### 10.5 <u>PICSTART Plus Entry Level</u> <u>Development System</u>

The PICSTART programmer is an easy-to-use, low-cost prototype programmer. It connects to the PC via one of the COM (RS-232) ports. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. PICSTART Plus is not recommended for production programming.

PICSTART Plus supports all PIC12CXXX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX devices with up to 40 pins. Larger pin count devices such as the PIC16C923 and PIC16C924 may be supported with an adapter socket.

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# 10.6 PICDEM-1 Low-Cost PIC16/17 Demonstration Board

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-Plus programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the PICMASTER emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

# 10.7 PICDEM-2 Low-Cost PIC16CXX Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-Plus, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the I<sup>2</sup>C bus and separate headers for connection to an LCD module and a keypad.

# 10.8 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include

an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

#### 10.9 MPLAB Integrated Development Environment Software

The MPLAB IDE Software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a windows based application which contains:

- · A full featured editor
- · Three operating modes
  - editor
  - emulator
  - simulator
- A project manager
- · Customizable tool bar and key mapping
- · A status bar with project information
- · Extensive on-line help

MPLAB allows you to:

- · Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PIC16/17 tools (automatically updates all project information)
- Debug using:
  - source files
- absolute listing file
- Transfer data dynamically via DDE (soon to be replaced by OLE)
- · Run up to four emulators on the same PC

The ability to use MPLAB with Microchip's simulator allows a consistent platform and the ability to easily switch from the low cost simulator to the full featured emulator with minimal retraining due to development tools.

#### 10.10 Assembler (MPASM)

The MPASM Universal Macro Assembler is a PC-hosted symbolic assembler. It supports all microcontroller series including the PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX, and PIC17CXX families.

MPASM offers full featured Macro capabilities, conditional assembly, and several source and listing formats. It generates various object code formats to support Microchip's development tools as well as third party programmers.

MPASM allows full symbolic debugging from PICMASTER, Microchip's Universal Emulator System.

MPASM has the following features to assist in developing software for specific use applications.

- Provides translation of Assembler source code to object code for all Microchip microcontrollers.
- · Macro assembly capability.
- Produces all the files (Object, Listing, Symbol, and special) required for symbolic debug with Microchip's emulator systems.
- Supports Hex (default), Decimal and Octal source and listing formats.

MPASM provides a rich directive language to support programming of the PIC16/17. Directives are helpful in making the development of your assemble source code shorter and more maintainable.

### 10.11 Software Simulator (MPLAB-SIM)

The MPLAB-SIM Software Simulator allows code development in a PC host environment. It allows the user to simulate the PIC16/17 series microcontrollers on an instruction level. On any given instruction, the user may examine or modify any of the data areas or provide external stimulus to any of the pins. The input/output radix can be set by the user and the execution can be performed in; single step, execute until break, or in a trace mode.

MPLAB-SIM fully supports symbolic debugging using MPLAB-C and MPASM. The Software Simulator offers the low cost flexibility to develop and debug code outside of the laboratory environment making it an excellent multi-project software development tool.

## 10.12 C Compiler (MPLAB-C)

The MPLAB-C Code Development System is a complete 'C' compiler and integrated development environment for Microchip's PIC16/17 family of microcontrollers. The compiler provides powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compiler provides symbol information that is compatible with the MPLAB IDE memory display.

### 10.13 <u>Fuzzy Logic Development System</u> (<u>fuzzyTECH-MP</u>)

fuzzyTECH-MP fuzzy logic development tool is available in two versions - a low cost introductory version, MP Explorer, for designers to gain a comprehensive working knowledge of fuzzy logic system design; and a full-featured version, fuzzyTECH-MP, edition for implementing more complex systems.

Both versions include Microchip's fuzzyLAB<sup>TM</sup> demonstration board for hands-on experience with fuzzy logic systems implementation.

### 10.14 <u>MP-DriveWay™ – Application Code</u> Generator

MP-DriveWay is an easy-to-use Windows-based Application Code Generator. With MP-DriveWay you can visually configure all the peripherals in a PIC16/17 device and, with a click of the mouse, generate all the initialization and many functional code modules in C language. The output is fully compatible with Microchip's MPLAB-C C compiler. The code produced is highly modular and allows easy integration of your own code. MP-DriveWay is intelligent enough to maintain your code through subsequent code generation.

# 10.15 <u>SEEVAL® Evaluation and Programming System</u>

The SEEVAL SEEPROM Designer's Kit supports all Microchip 2-wire and 3-wire Serial EEPROMs. The kit includes everything necessary to read, write, erase or program special features of any Microchip SEEPROM product including Smart Serials™ and secure serials. The Total Endurance™ Disk is included to aid in tradeoff analysis and reliability calculations. The total kit can significantly reduce time-to-market and result in an optimized system.

### 10.16 <u>Keelog® Evaluation and</u> Programming Tools

KEELOQ evaluation and programming tools support Microchips HCS Secure Data Products. The HCS evaluation kit includes an LCD display to show changing codes, a decoder to decode transmissions, and a programming interface to program test transmitters.

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TABLE 10-1: DEVELOPMENT TOOLS FROM MICROCHIP

	PIC12C5XX	PIC14000	PIC16C5X	PIC16CXXX	PIC16C6X	PIC16C7XX	PIC16C8X	PIC16C9XX	PIC17C4X	PIC17C75X	25CXX 93CXX	HCS200 HCS300 HCS301
PICMASTER®/ PICMASTER-CE In-Circuit Emulator	>	7	171 MM	MAA MAA	14. <b>7</b> 0, 14.700	1007.	10X.C.	COZ <sub>V</sub>	OW'Z. WILM	Available 3Q97		
ICEPIC Low-Cost In-Circuit Emulator	WA WA	WWW.	M.100	100X.C	00X.COD	COM	M.TV $M.TX$ $M.TX$	TW LTW	N W	1	W	WWW
MPLAB™ Integrated Development Environment	M.10 <b>7</b> 2	100X.CC	07.CO	COMA.	M.T.N.	EM 7	7	AN A	MA	WWY!	M.100	N.100X
MPLAB™ C Compiler	.S <sup>C</sup> y.C		V.Z.	N M	>	7	W		M.70	100. 00 <sub>x</sub>	Y.C	CO
fuzzyTECH®.MP Explorer/Edition Fuzzy Logic Dev. Tool	M.TW OM.TV	TW.	N 7	2	WW	MAIA.	WW.1 <b>2</b> 0	100X.C	07.CQ	COM.	OM.TV	MIW
MP-DriveWay™ Applications Code Generator	Ī	1	11 <b>7</b>	MM.	1.10° 71.1 <b>2</b> 0 	100 <b>7</b> 001.0	07.CO	COM:	W. <b>Z</b> .	TW	i N	
Total Endurance™ Software Model	W.	NW	N.1	100 100	Y.C	.CO	M.	TW.	N		7	W
PICSTART® Lite Ultra Low-Cost Dev. Kit	WW.	N.100	<sup>700</sup> 7.	V.CO		VT.1 VE.M	TW.	N		WW	NMA	NW.1
PICSTART® Plus Low-Cost Universal Dev. Kit	100 <b>%</b> 100 <b>%</b> 1003	07. <b>6</b> 0	COM:	M.T.V M.T.V	TW	W 7	7	NAM.	WW.	MM.7	1.100 <sup>Y</sup>	OOY.C
PRO MATE <sup>®</sup> II Universal Programmer	.co.	OM.T	.TV .TV	W 7	2	17. 12.	MAY.	W.70	10 <b>2</b> )	00 X Z	Y.C.Z.	Z
KEELOQ® Programmer	TV TV TT	N			W	WW.	1.10°	07. <sup>1</sup>	CO V.C	CON	1.T 1.T	7
SEEVAL® Designers Kit			TV TV	NN	N.V.	100	04.C	CO)	OM; W:1	TW	4/1	
PICDEM-1		W	7	( ) ( ) ( ) ( ) ( ) ( ) ( ) ( ) ( ) ( )	.100	1.0 V.0	<b>3</b> 0	T.T		I M		
PICDEM-2	N.		N.I	100 100	7	50 5	M.	TV	N			
PICDEM-3	N	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	100	Y.C		V.	TY.	>				
KEELOQ® Evaluation Kit	N.1	700	N.Y.	CO	M.T		V					7

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### 11.0 ELECTRICAL CHARACTERISTICS FOR PIC16C710 AND PIC16C711

#### **Absolute Maximum Ratings †**

Ambient temperature under bias	55 to +125°C
Storage temperature	
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	
Voltage on MCLR with respect to Vss	0 to +14V
Voltage on RA4 with respect to Vss	0 to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	300 mA
Maximum current into VDD pin	
Input clamp current, Iik (Vi < 0 or Vi > VDD)	± 20 mA
Output clamp current, loκ (Vo < 0 or Vo > VDD)	± 20 mA
Maximum output current sunk by any I/O pin	
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA	200 mA
Maximum current sourced by PORTA	200 mA
Maximum current sunk by PORTB	200 mA
Maximum current sourced by PORTB	200 mA
<b>Note 1:</b> Power dissipation is calculated as follows: Pdis = VDD x {IDD - $\Sigma$ IOH} + $\Sigma$ {	

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the

device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 11-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C710-04	PIC16C710-10	PIC16C710-20	PIC16LC710-04	PIC16C710/JW
	PIC16C711-04	PIC16C711-10	PIC16C711-20	PIC16LC711-04	PIC16C711/JW
RC	VDD: 4.0V to 6.0V	VDD: 4.5V to 5.5V	VDD: 4.5V to 5.5V	VDD: 2.5V to 6.0V	VDD: 4.0V to 6.0V
	IDD: 5 mA max. at 5.5V	IDD: 2.7 mA typ. at 5.5V	IDD: 2.7 mA typ. at 5.5V	IDD: 3.8 mA typ. at 3.0V	IDD: 5 mA max. at 5.5V
	IPD: 21 µA max. at 4V	IPD: 1.5 μA typ. at 4V	IPD: 1.5 μA typ. at 4V	IPD: 5.0 μA typ. at 3V	IPD: 21 µA max. at 4V
	Freq:4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq:4 MHz max.
XT	VDD: 4.0V to 6.0V	VDD: 4.5V to 5.5V	VDD: 4.5V to 5.5V	VDD: 2.5V to 6.0V	VDD: 4.0V to 6.0V
	IDD: 5 mA max. at 5.5V	IDD: 2.7 mA typ. at 5.5V	IDD: 2.7 mA typ. at 5.5V	IDD: 3.8 mA typ. at 3.0V	IDD: 5 mA max. at 5.5V
	IPD: 21 µA max. at 4V	IPD: 1.5 μA typ. at 4V	IPD: 1.5 μA typ. at 4V	IPD: 5.0 μA typ. at 3V	IPD: 21 µA max. at 4V
	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.	Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq:20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 10 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5.0 μA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5.0 μA max. at 3.0V Freq: 200 kHz max.

DC CHARACTERISTICS

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## **Applicable Devices** | 710 | 71 | 711 | 715

PIC16C710-04 (Commercial, Industrial, Extended) 11.1 **DC Characteristics:** 

PIC16C711-04 (Commercial, Industrial, Extended)

PIC16C710-10 (Commercial, Industrial, Extended)

PIC16C711-10 (Commercial, Industrial, Extended)

PIC16C710-20 (Commercial, Industrial, Extended)

PIC16C711-20 (Commercial, Industrial, Extended)

#### Standard Operating Conditions (unless otherwise stated)

Operating temperature  $0^{\circ}C \leq TA \leq +70^{\circ}C$  (commercial) TA < 105°C (industrial)

Param. No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001 D001A	Supply Voltage	VDD	4.0 4.5	CGM	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	1002	1.5	V.7.	V	WWW.toox.com.tw
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	1.100	Vss	OM:	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	00-X.	CO	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7 3.7	4.0 4.0	4.3 4.4	<b>&gt; &gt; &gt;</b>	BODEN configuration bit is enabled Extended Range Only
D010 D013	Supply Current (Note 2)	IDD	W.A.	13.5	5 30	mA mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)  HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 5)	Δlbor	- 1	300*	500	μА	BOR enabled VDD = 5.0V
D020 D021 D021A D021B	Power-down Current (Note 3)	IPD	- - -	10.5 1.5 1.5 1.5	42 21 24 30	μΑ μΑ μΑ μΑ	VDD = 4.0V, WDT enabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -0°C to +70°C VDD = 4.0V, WDT disabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 5)	Δlbor	N _	300*	500	μА	BOR enabled VDD = 5.0V

- These parameters are characterized but not tested.
- Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.
- For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- The  $\Delta$  current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

See section on Power-on Reset for details

BODEN configuration bit is enabled

Fosc = 4 MHz, VDD = 3.0V (Note 4)

Fosc = 32 kHz, VDD = 3.0V, WDT disabled

VDD = 3.0V, WDT enabled, -40°C to +85°C

VDD = 3.0V, WDT disabled, -40°C to +85°C

VDD = 3.0V, WDT disabled, -40°C to +125°C

VDD = 3.0V. WDT disabled, 0°C to +70°C

XT, RC osc configuration

BOR enabled VDD = 5.0V

BOR enabled VDD = 5.0V

LP osc configuration

# 11.2 DC Characteristics: PIC16LC710-04 (Commercial, Industrial, Extended) PIC16LC711-04 (Commercial, Industrial, Extended)

0.05

3.7

4.0

2.0

22.5

300\*

7.5

0.9

0.9

0.9

300\*

4.3

3.8

48

500

30

5

5

10

500

SVDD

**BVDD** 

IDD

 $\Delta$ lbor

**IPD** 

ΔIBOR

DC CHAI	RACTERISTICS			ard Ope		ure 0° -4	itions (unless otherwise stated) $C \leq TA \leq +70^{\circ}C$ (commercial) $0^{\circ}C \leq TA \leq +85^{\circ}C$ (industrial) $0^{\circ}C \leq TA \leq +125^{\circ}C$ (extended)
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage Commercial/Industrial Extended	VDD VDD	2.5 3.0	LAI	6.0 6.0	V	LP, XT, RC osc configuration (DC - 4 MHz) LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	$Co_{M}$	1.5	-	V	WW.100Y.COM.3
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	V.Co.	Vss	N -	V	See section on Power-on Reset for details

V/ms

mA

μΑ

μΑ

uΑ

цΑ

μA

μΑ

μΑ

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

 $\overline{MCLR} = VDD$ ; WDT enabled/disabled as specified.

- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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D004\*

D005

D010

D010A

D015

D020

D021

D021A

D021B

D023

VDD rise rate to ensure

internal Power-on

**Brown-out Reset** 

Supply Current

Brown-out Reset

Power-down Current

Current (Note 5)

**Brown-out Reset** 

Current (Note 5)

Reset signal

Voltage

(Note 2)

(Note 3)

DC CHARACTERISTICS

## Applicable Devices 710 71 711 715

11.3 DC Characteristics: PIC16C710-04 (Commercial, Industrial, Extended)

PIC16C711-04 (Commercial, Industrial, Extended)
PIC16C710-10 (Commercial, Industrial, Extended)
PIC16C711-10 (Commercial, Industrial, Extended)
PIC16C710-20 (Commercial, Industrial, Extended)
PIC16C711-20 (Commercial, Industrial, Extended)

PIC16LC710-04 (Commercial, Industrial, Extended) PIC16LC711-04 (Commercial, Industrial, Extended)

Standard Operating Conditions (unless otherwise stated)

Operating temperature  $0^{\circ}$ C  $\leq TA \leq +70^{\circ}$ C (commercial)

 $-40^{\circ}$ C  $\leq$  TA  $\leq$  +85 $^{\circ}$ C (industrial) -40 $^{\circ}$ C  $\leq$  TA  $\leq$  +125 $^{\circ}$ C (extended)

Operating voltage VDD range as described in DC spec Section 11.1 and

Section 11.2.

Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
· covi	Input Low Voltage	oy.C			1	144	1100Y.
1.100	I/O ports	VIL	OM	«XI			N.10 COM.
D030	with TTL buffer	00x.	Vss	172	0.15VDD	V	For entire VDD range
D030A	V.COM WWW.	YOU	Vss	7-1	V8.0	V	4.5 ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer	Too	Vss	-	0.2VDD	٧	M.M. To COMP.
D032	MCLR, OSC1	a 100.	Vss	7.	0.2Vdd	V	W.100 . COM.1
MM	(in RC mode)		M.Co.	W 17	W		WY TOOY.CO TITY
D033	OSC1 (in XT, HS and LP)	W.70	Vss	NĪ.	0.3VDD	V	Note1
NAA .	Input High Voltage	-XXI 1	101.	M	7.		M. Inn. COM.
WWW	I/O ports	VIH	any.C		WT		WW 100Y.Cont.TV
D040	with TTL buffer	WW.	2.0	G	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A	W.100Y.COM.TW	WW	0.25VDD + 0.8V	CC	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	7 C	VDD	V	For entire VDD range
D042	MCLR, RB0/INT	1/1/1/	0.8VDD	-	VDD	V	W. 100 1.
D042A	OSC1 (XT, HS and LP)	WV	0.7VDD	1	VDD	V	Note1
D043	OSC1 (in RC mode)	- 1	0.9VDD	- -<1	VDD	V	MMM.IO. CO.
D070	PORTB weak pull-up current	IPURB	50	250	400	μΑ	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)		Man	00	Y.Co.		M. 100 Y.C.
D060	I/O ports	lıL	MAN.	10	±10	μΑ	Vss ≤ VPIN ≤ VDD, Pin at hi- impedance
D061	MCLR, RA4/T0CKI		W-W	-	±5	μΑ	Vss ≤ VPIN ≤ VDD
D063	OSC1		WW		±5	μΑ	$\label{eq:VSS} VSS \leq VPIN \leq VDD, \ XT, \ HS \ and \ LP \\ osc \ configuration$

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.
  - 2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
  - 3: Negative current is defined as current sourced by the pin.

Standard Operating Conditions (unless otherwise stated)

Operating temperature  $0^{\circ}$ C  $\leq TA \leq +70^{\circ}$ C (commercial)

 $-40^{\circ}$ C  $\leq$  TA  $\leq$  +85 $^{\circ}$ C (industrial)

 $-40^{\circ}$ C  $\leq$  TA  $\leq$  +125 $^{\circ}$ C (extended)

Operating voltage VDD range as described in DC spec Section 11.1 and

Section 11.2.

Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
Mir	Output Low Voltage	- 41		-141	111.70	- <7 C	ON-
D080	I/O ports	Vol	-	W.	0.6	V	IOL = $8.5 \text{ mA}$ , VDD = $4.5 \text{V}$ , $-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$
D080A	W WWW.1001.CO	MIL	N -	-	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)	OM.	W -	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D083A	I.TW WWW.100Y.C	COM	TW	-	0.6	No	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C
0.	Output High Voltage	701	1.7			KIVI.	COM
D090	I/O ports (Note 3)	Voн	VDD - 0.7	-	-1/1	V	IOH = $-3.0$ mA, VDD = $4.5$ V, $-40$ °C to $+85$ °C
D090A	COM.TW WWW.100	ov.C	VDD - 0.7	- N	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)	00Y.	VDD - 0.7	N	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D092A	Y.COM.TW WWW.	100 Y	VDD - 0.7	TV	- -	V	IOH = -1.0 mA, VDD = 4.5V, -40°C to +125°C
D130*	Open-Drain High Voltage	Vod	- 01	(3)	14	V	RA4 pin
WW.	Capacitive Loading Specs on Output Pins	W.10	V.CO	M.			MAN TOOK CONTIN
D100	OSC2 pin	Cosc <sub>2</sub>	100X.C	MC	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	Cio	. Year	- ]	50	pF	WW. TIOOY.COM.T

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.
  - 2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
  - 3: Negative current is defined as current sourced by the pin.

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DC CHARACTERISTICS

### 11.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

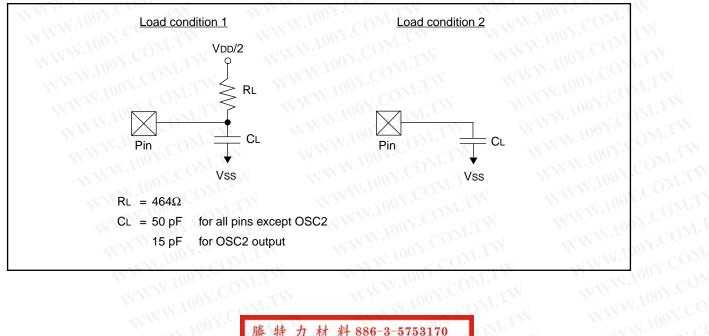
- 1. TppS2ppS
- 2. TppS

T			
COEVI.	Frequency	T	Time
Lower	case letters (pp) and their meanings:		M. M. M. COM.
рр			
СС	CCP1	osc	OSC1
ck	CLKOUT	rd	RD
cs	CS WY	rw	RD or WR
di	SDI	sc	SCK
do	SDO	SS	SS
dt	Data in	tO	TOCKI
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR

Uppercase letters and their meanings:

S 100		100 r	COM.
F	Fall	100Y. P. TW	Period
H	High	R	Rise
J.W.10	Invalid (Hi-impedance)	M. June 1	Valid
WY L	Low	Z 100 Z	Hi-impedance

#### FIGURE 11-1: LOAD CONDITIONS



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### 11.5 <u>Timing Diagrams and Specifications</u>

#### FIGURE 11-2: EXTERNAL CLOCK TIMING

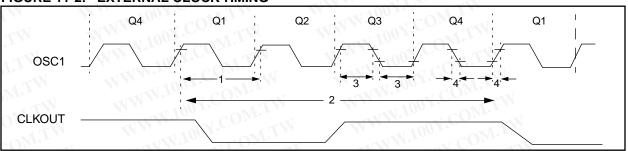


TABLE 11-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
-1 CON	Fosc	External CLKIN Frequency	DC	-37	4	MHz	XT osc mode
07.0		(Note 1)	DC		4	MHz	HS osc mode (-04)
ON CU		W WWW LOOK	DC	W.	10	MHz	HS osc mode (-10)
UU -		TWW.Io	DC	<u> </u>	20	MHz	HS osc mode (-20)
1007.		LN N. 100	DC		200	kHz	LP osc mode
· AOV		Oscillator Frequency	DC	TT	4	MHz	RC osc mode
1.100		(Note 1)	0.1	$O_{\overline{M}}$ .	4	MHz	XT osc mode
1007		WILL WILLIAM	4	1400	20	MHz	HS osc mode
11	A.Co.	WW WIT	5		200	kHz	LP osc mode
1.100	Tosc	External CLKIN Period	250	$C_{\Theta_{M_1}}$	- <del></del> -	ns	XT osc mode
× 10		(Note 1)	250	=01	7:77,	ns	HS osc mode (-04)
M.V.		OR WAY	100	Y.L	TW.	ns	HS osc mode (-10)
L.WW.		COM.	50	~ <del>-</del> CC	_	ns	HS osc mode (-20)
N N V		W.Th	5	07.	01/ <del>T</del> /7/	μs	LP osc mode
MAN		Oscillator Period	250	W. J.	7 7	ns	RC osc mode
		(Note 1)	250	<del>-</del> -/	10,000	ns	XT osc mode
1/1/1/		T. OM.TW	250	$70\overline{m}_{J}$ .	250	ns	HS osc mode (-04)
WW		N.CO. TW	100	- <del>11</del> 07	250	ns	HS osc mode (-10)
		COM	50	N.10	250	ns	HS osc mode (-20)
		OOY. OM.TW	5	100 to 1	= 0	μs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200		DC	ns	Tcy = 4/Fosc
3	TosL,	External Clock in (OSC1) High	50	N. W.	~ C(	ns	XT oscillator
	TosH	or Low Time	2.5	`. <del></del>	00 F.	μs	LP oscillator
		N. CON.CO	10	N.	1005/.C	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise	- 1	THE STATE OF THE S	25	ns	XT oscillator
	TosF	or Fall Time	-	N	50	ns	LP oscillator
		MY. COM	_	WAY!	15	ns	HS oscillator

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin.

When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C710/711.

FIGURE 11-3: CLKOUT AND I/O TIMING

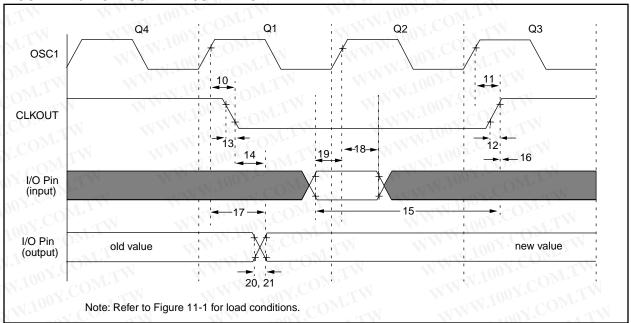


TABLE 11-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	M.M. 1007.CO	Min	Тур†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	1007.	M.TW	15	30	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	MM . 1001.	THE WAY	15	30	ns	Note 1
12*	TckR	CLKOUT rise time	WWW.	CONT	5	15	ns	Note 1
13*	TckF	CLKOUT fall time	W.100	COM.	. 5	15	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out v	alid	- TIT	<b>N</b>	0.5Tcy + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLK	OUT ↑	0.25Tcy + 25	W.	-111	ns	Note 1
16*	TckH2iol	Port in hold after CLKO	JT ↑	(0)	- T	- 11	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	MMM'T	ON COM	TW	80 - 100	ns	100 Y.C.
18*	TosH2iol	OSC1 <sup>↑</sup> (Q2 cycle) to Port input invalid (I/O in	hold time)	TBD	(T)	( <del>-</del>	ns	W.100Y.
19*	TioV2osH	Port input valid to OSC1	↑ (I/O in setup time)	TBD	7	W -	ns	1003
20*	TioR	Port output rise time	PIC16 <b>C</b> 710/711	VI. TO	10	25	ns	MAN
	M. A.	W.100Y.	PIC16 <b>LC</b> 710/711	11/100	OAA.	60	ns	11/1/1/100
21*	TioF	Port output fall time	PIC16 <b>C</b> 710/711	1 100 X .	10	25	ns	10 xx 10
	17/	M. T. OX. COM.	PIC16 <b>LC</b> 710/711	MAN 001	CA,	60	ns	NW
22††*	Tinp	INT pin high or low time		20	r eo	N	ns	TINN.
23††*	Trbp	RB7:RB4 change INT h	igh or low time	20	-	WF	ns	With

<sup>\*</sup> These parameters are characterized but not tested.

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

<sup>††</sup> These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

FIGURE 11-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP **TIMER TIMING** 

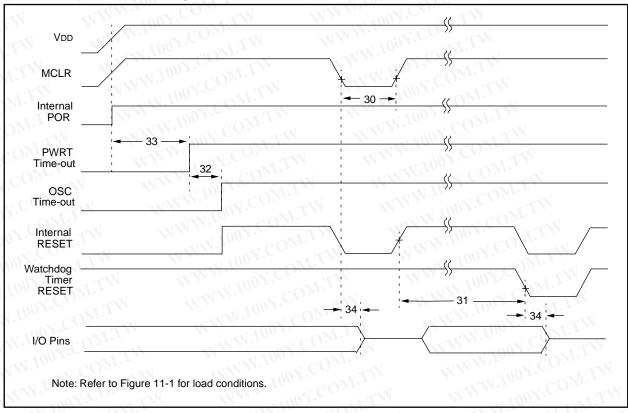
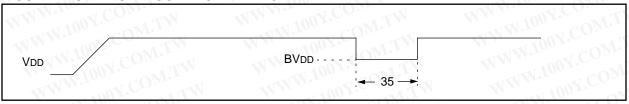


FIGURE 11-5: BROWN-OUT RESETTIMING



RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, **TABLE 11-4:** AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	W 1	1007.t	_ <del>_</del>	μs	$VDD = 5V, -40^{\circ}C \text{ to } +125^{\circ}C$
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	$VDD = 5V, -40^{\circ}C \text{ to } +125^{\circ}C$
32	Tost	Oscillation Start-up Timer Period	ZV.	1024Tosc		VII.	Tosc = OSC1 period
33	Tpwrt	Power up Timer Period	28*	72	132*	ms	$VDD = 5V, -40^{\circ}C \text{ to } +125^{\circ}C$
34	Tioz	I/O Hi-impedance from MCLR Low or Watchdog Timer Reset	_	MA.	1.10	μs	LM MM
35	TBOR	Brown-out Reset pulse width	100	MA	004.	μs	3.8V ≤ VDD ≤ 4.2V

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested. †

FIGURE 11-6: TIMERO EXTERNAL CLOCK TIMINGS

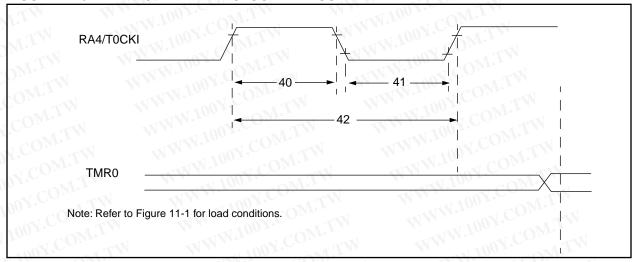


TABLE 11-5: TIMERO EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic	M.100X.COM	Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5Tcy + 20*	OT W	$A\overline{r}_{p_{i}}$	ns	Must also meet
	1001.	OM.TW	With Prescaler	10*	_	( <del>4</del> )	ns	parameter 42
41	TtOL	T0CKI Low Pulse Width	No Prescaler	0.5Tcy + 20*	7	-73	ns	Must also meet
	You.	COMP	With Prescaler	10*	-1	11.	ns	parameter 42
42	Tt0P	T0CKI Period	MMM.100X.	Greater of: 20 ns or TCY + 40* N		NW WW	4.1	N = prescale value (2, 4,, 256)
48	Tcke2tmrl	Delay from external clock ed	ge to timer increment	2Tosc	_	7Tosc	NA.	. O. COM

<sup>\*</sup> These parameters are characterized but not tested.

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<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**TABLE 11-6:** A/D CONVERTER CHARACTERISTICS:

> PIC16C710/711-04 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16C710/711-10 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16C710/711-20 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16LC710/711-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution	$OV_{T,r}$		8-bits	bit	VREF = VDD, VSS ≤ AIN ≤ VREF
A02	EABS	Absolute error	$^{-0}\overline{M}_{J}$	_	< ± 1	LSb	VREF = VDD, VSS ≤ AIN ≤ VREF
A03	EIL	Integral linearity error	- T.	M -	< ± 1	LSb	VREF = VDD, VSS ≤ AIN ≤ VREF
A04	EDL	Differential linearity error	Con	TVI	< ± 1	LSb	VREF = VDD, VSS ≤ AIN ≤ VREF
A05	EFS	Full scale error	4.CON	T	< ± 1	LSb	VREF = VDD, VSS ≤ AIN ≤ VREF
A06	Eoff	Offset error	TOD		< ± 1	LSb	VREF = VDD, VSS ≤ AIN ≤ VREF
A10	14.7	Monotonicity	<del>-</del>	guaranteed	_	T N	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage	2.5V	WH.	VDD + 0.3	V	N. 100 . COM: I.
A25	VAIN	Analog input voltage	Vss - 0.3	-11	VREF + 0.3	V	TION.COTITY
A30	ZAIN	Recommended impedance of analog voltage source	100Y.	CONT.	10.0	kΩ	W. 100X COW.TW
A40	lad	A/D conversion current (VDD)	W.1007	180	- W	μΑ	Average current consumption when A/D is on. (Note 1)
A50	IREF	VREF input current (Note 2)	10	OX.COM	1000	μА	During VAIN acquisition.  Based on differential of VHOLD to VAIN  To charge CHOLD see Section 7.1.

- These parameters are characterized but not tested.
- t Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not
- Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.
  - 2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

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### FIGURE 11-7: A/D CONVERSION TIMING

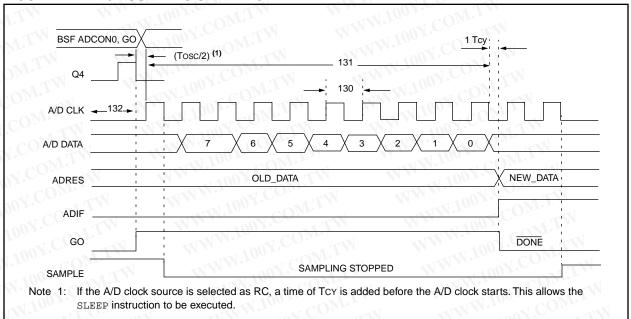


TABLE 11-7: A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic	MMA	Min	Тур†	Max	Units	Conditions
130	TAD	A/D clock period	PIC16 <b>C</b> 710/711	1.6	<u></u>	V.T.	μs	Tosc based, VREF ≥ 3.0V
WW	///	MY.COM	PIC16 <b>LC</b> 710/711	2.0	01=		μs	Tosc based, VREF full range
-31	MI.	COM.	PIC16 <b>C</b> 710/711	2.0*	4.0	6.0	μs	A/D RC mode
111	-TVV	100 r. COM	PIC16 <b>LC</b> 710/711	3.0*	6.0	9.0	μs	A/D RC mode
131	TCNV	Conversion time (not including S/H	time). (Note 1)	NWW	9.5	COM	TAD	MMM:100X:COV
132	TACQ	Acquisition time	M.TW OM.TW COM.TW	Note 2 5*	20	00Y.C	μs μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 19.5 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
134	Tgo	Q4 to AD clock sta	art N.COM.TW	_	Tosc/2§	N:100,	1.CO	If the A/D clock source is selected as RC, a time of Tcy is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	Tswc	Switching from co	nvert  o sample time	1.5§	= 1	11-10	TAD	OM. MANN.

- These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested
- § This specification ensured by design.
- Note 1: ADRES register may be read on the following TcY cycle.
  - 2: See Section 7.1 for min conditions.

# 12.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C710 AND PIC16C711

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified VDD range). This is for information only and devices are guaranteed to operate properly only within the specified range.

**Note:** The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at,  $25^{\circ}$ C, while 'max' or 'min' represents (mean +3 $\sigma$ ) and (mean -3 $\sigma$ ) respectively where  $\sigma$  is standard deviation.

FIGURE 12-1: TYPICAL IPD vs. VDD (WDT DISABLED, RC MODE)

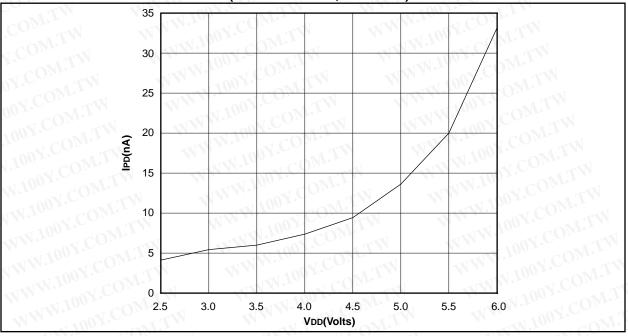


FIGURE 12-2: MAXIMUM IPD vs. VDD (WDT DISABLED, RC MODE)

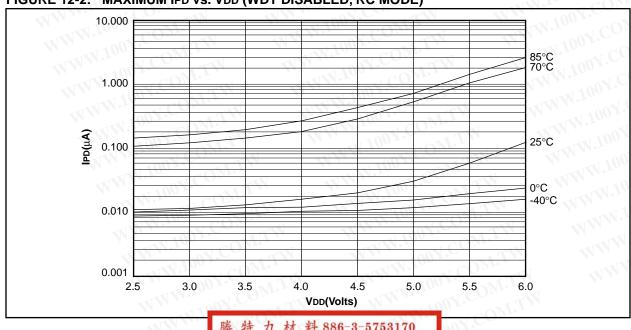


FIGURE 12-3: TYPICAL IPD vs. VDD @ 25°C (WDT ENABLED, RC MODE)

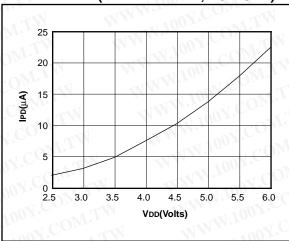


FIGURE 12-4: MAXIMUM IPD vs. VDD (WDT ENABLED, RC MODE)

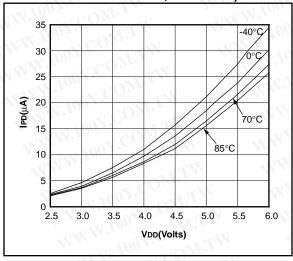


FIGURE 12-5: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

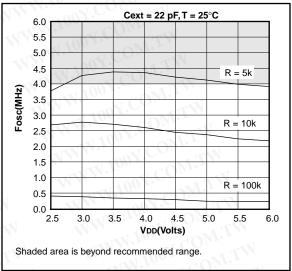


FIGURE 12-6: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

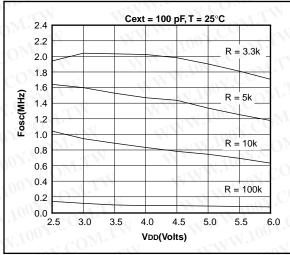


FIGURE 12-7: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

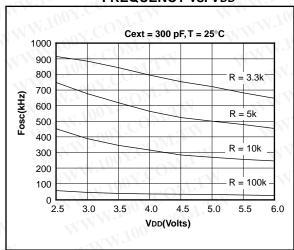


FIGURE 12-8: TYPICAL IPD vs. VDD BROWN-OUT DETECT ENABLED (RC MODE)

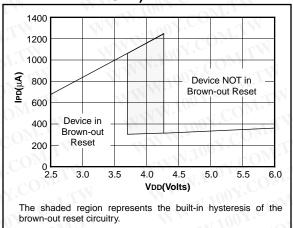


FIGURE 12-9: MAXIMUM IPD vs. VDD
BROWN-OUT DETECT
ENABLED
(85°C TO -40°C, RC MODE)

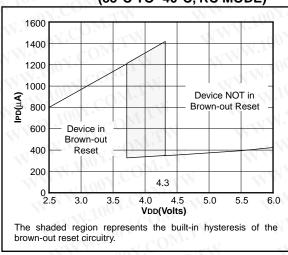


FIGURE 12-10: TYPICAL IPD vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, RC MODE)

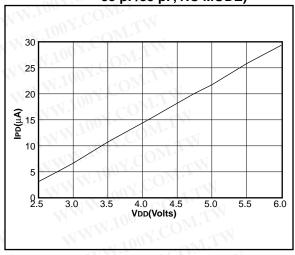
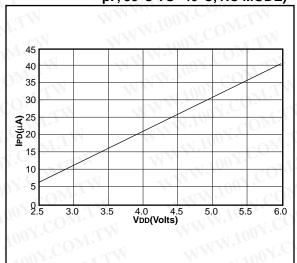


FIGURE 12-11: MAXIMUM IPD vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, 85°C TO -40°C, RC MODE)



Applicable Devices 710 71 711 715

FIGURE 12-12: TYPICAL IDD vs. FREQUENCY (RC MODE @ 22 pF, 25°C)

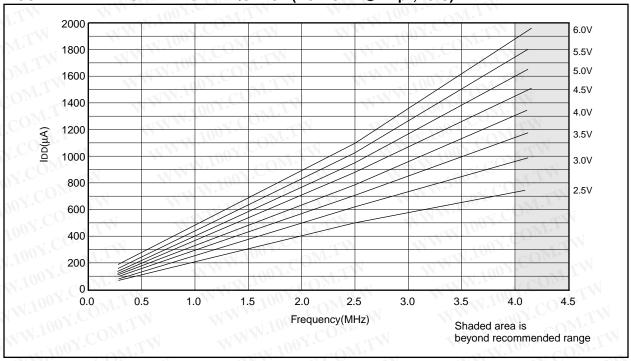


FIGURE 12-13: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 22 pF, -40°C TO 85°C)

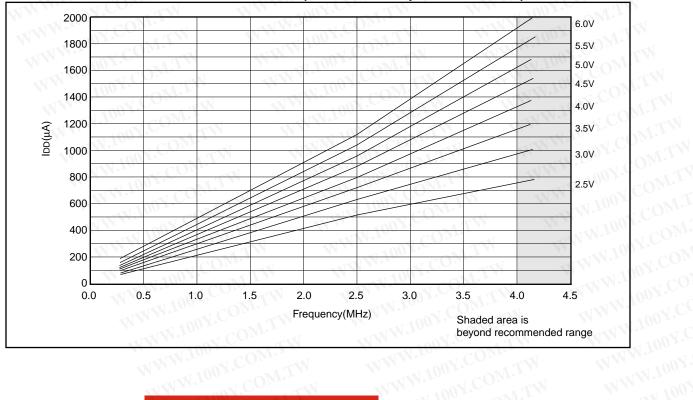


FIGURE 12-14: TYPICAL IDD vs. FREQUENCY (RC MODE @ 100 pF, 25°C)

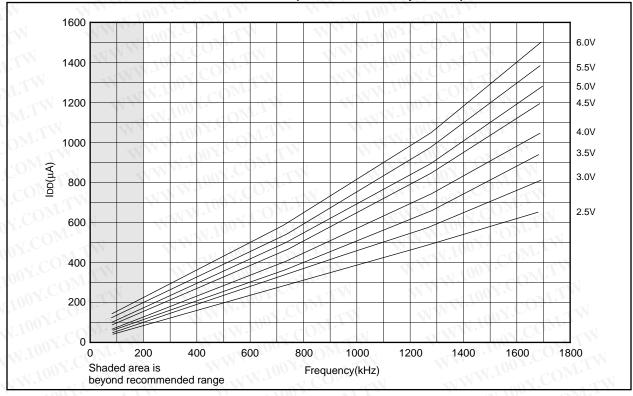
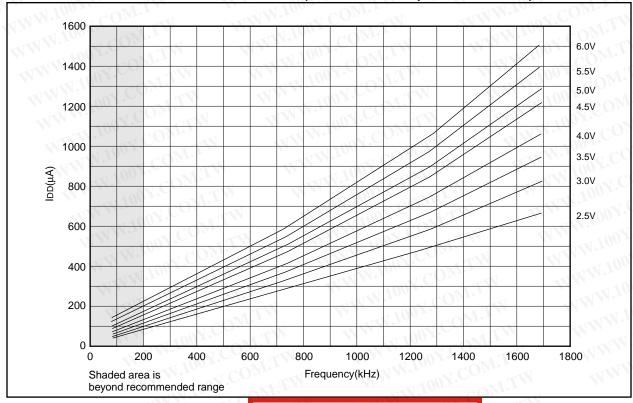


FIGURE 12-15: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO 85°C)



Applicable Devices 710 71 711 715

FIGURE 12-16: TYPICAL IDD vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

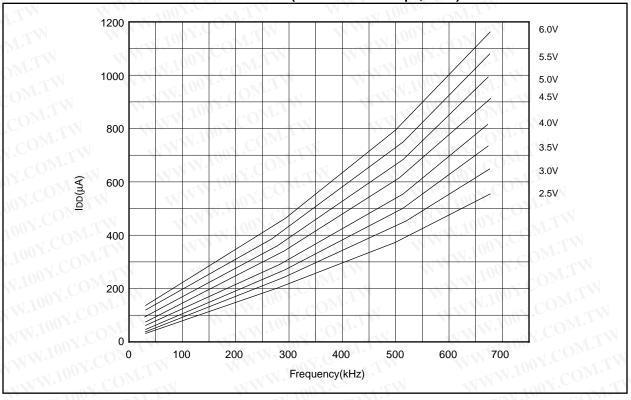


FIGURE 12-17: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)

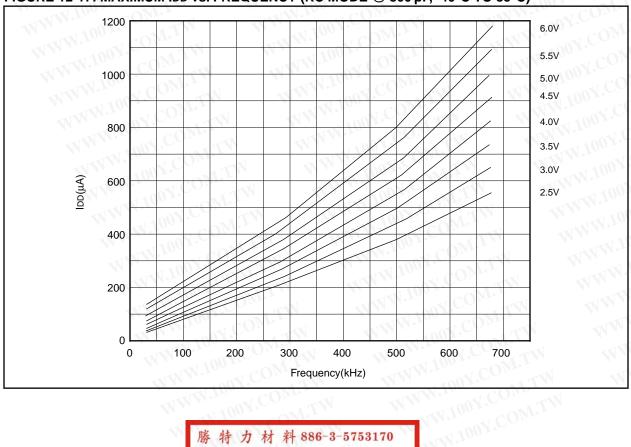


FIGURE 12-18: TYPICAL IDD vs.

CAPACITANCE @ 500 kHz

(RC MODE)

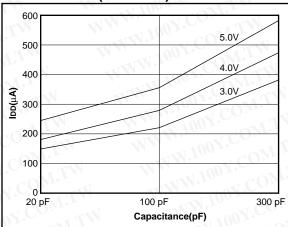


TABLE 12-1: RC OSCILLATOR FREQUENCIES

Cext	Rext	Average		
Cext	Rext	Fosc @ 5V, 25°C		
22 pF	5k	4.12 MHz	± 1.4%	
N.100	10k	2.35 MHz	± 1.4%	
$M.100^{-1}$	100k	268 kHz	± 1.1%	
100 pF	3.3k	1.80 MHz	± 1.0%	
N 11.	5k	1.27 MHz	± 1.0%	
MM·IO	10k	688 kHz	± 1.2%	
WW.1	100k	77.2 kHz	± 1.0%	
300 pF	3.3k	707 kHz	± 1.4%	
WW	5k	501 kHz	± 1.2%	
WWW	10k	269 kHz	± 1.6%	
W	100k	28.3 kHz	± 1.1%	

The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is  $\pm 3$  standard deviation from average value for VDD = 5V.

FIGURE 12-19: TRANSCONDUCTANCE(gm)
OF HS OSCILLATOR vs. VDD

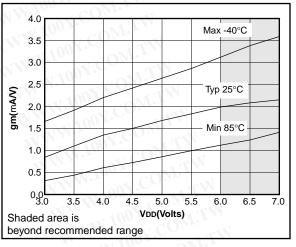


FIGURE 12-20: TRANSCONDUCTANCE(gm)
OF LP OSCILLATOR vs. VDD

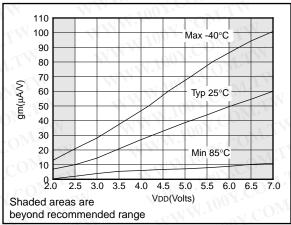


FIGURE 12-21: TRANSCONDUCTANCE(gm)
OF XT OSCILLATOR vs. VDD

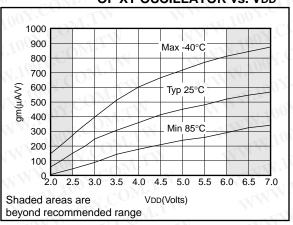


FIGURE 12-22: TYPICAL XTAL STARTUP TIME vs. VDD (LP MODE, 25°C)

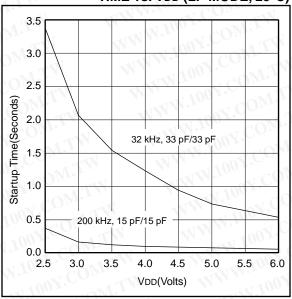
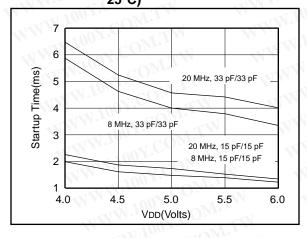


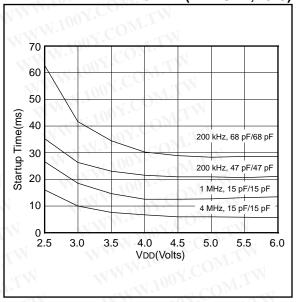
FIGURE 12-23: TYPICAL XTAL STARTUP TIME vs. VDD (HS MODE, 25°C)



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FIGURE 12-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

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**TABLE 12-2: CAPACITOR SELECTION** FOR CRYSTAL **OSCILLATORS** 

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
001.	MILIO		1007.
Crystals Used	OM.TV	M	MN.100X
32 kHz	Epson C-00	1R32.768K-A	± 20 PPM
200 kHz	STD XTL 20	00.000KHz	± 20 PPM
1 MHz	ECS ECS-1	0-13-1	± 50 PPM
4 MHz	ECS ECS-4	0-20-1	± 50 PPM
8 MHz	EPSON CA	-301 8.000M-C	± 30 PPM
20 MHz	EPSON CA	-301 20.000M-C	± 30 PPM
WWW.	100 X.C.C	OM.TW	WWW

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FIGURE 12-25: TYPICAL IDD vs. FREQUENCY (LP MODE, 25°C)

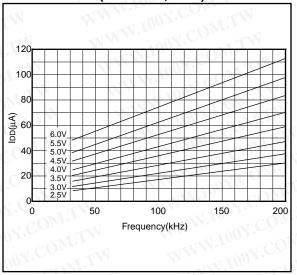


FIGURE 12-26: MAXIMUM IDD vs. **FREQUENCY** (LP MODE, 85°C TO -40°C)

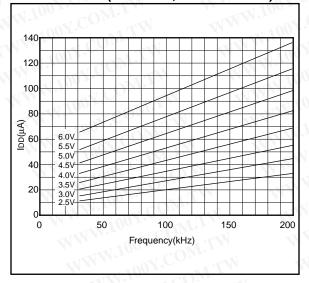


FIGURE 12-27: TYPICAL IDD vs. FREQUENCY (XT MODE, 25°C)

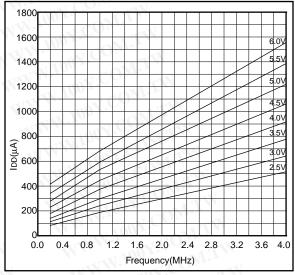
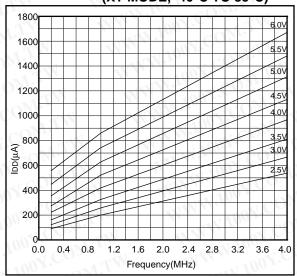


FIGURE 12-28: MAXIMUM IDD vs. **FREQUENCY** (XT MODE, -40°C TO 85°C)

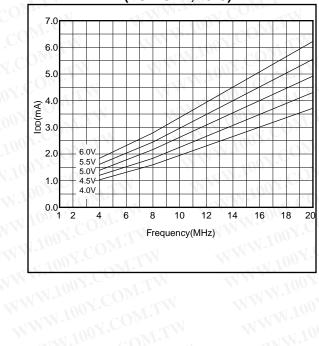


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## PIC16C71X

Applicable Devices 710 71 711 715

FIGURE 12-29: TYPICAL IDD vs. FREQUENCY (HS MODE, 25°C)



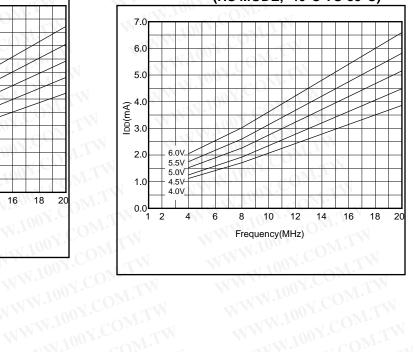
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FIGURE 12-30: MAXIMUM IDD vs. **FREQUENCY** (HS MODE, -40°C TO 85°C)

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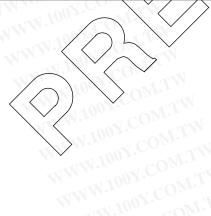
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## 13.0 ELECTRICAL CHARACTERISTICS FOR PIC16C715

Absolute Maximum Ratings †	
Ambient temperature under bias	
Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD and MCLR)	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	0 tø +7.5V
Voltage on MCLR with respect to Vss	0 to +14V
Voltage on RA4 with respect to Vss	0 to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, IIK (VI < 0 or VI > VDD)	± 20 mA
Output clamp current, loк (Vo < 0 or Vo > VDD)	± 20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA	200 mA
Maximum current sourced by PORTA	200 mA
Maximum current sunk by PORTB.	200 mA
Maximum current sourced by PORTB	200 mA
<b>Note 1:</b> Power dissipation is calculated as follows: Rdis = VDD x {IDD - $\Sigma$ IOH} + $\Sigma$ {(VD	D - VOH) x IOH} + $\Sigma$ (VOI x IOL).

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.



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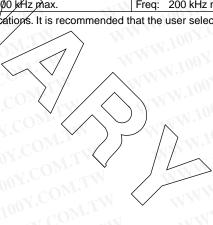
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#### PIC16LC715-04 osc PIC16C715-04 PIC16C7/15-10 PIC16C715-20 PIC16C715/JW 4.0V to 5.5V VDD: 4.5V to 5.5X 4.5V to 5.5V VDD: 2.5V to 5.5V VDD: 4.0V to 5.5V VDD: VDD: 2.7 mA typ. at 5.5) 5 mA max. at 5.5V IDD: IDD: 2.7 mA typ. at 5.5V 2.0 mA typ. at 3.0V 5 mA max. at 5.5V IDD: IDD: IDD: RC IPD: 21 µA max. at 4V IPD: 1.5 μA typ. at 4V IPD: 1.5 µA typ. at 4V 0.9 µA typ. at 3V 21 µA max. at 4V IPD: IPD: 4 MHz max. 4 MHz max. Freq: 4 MHz max. 4 MHz max. 4 MHz max. Frea: Freq: Frea: Frea: 4.5V to 5.5V 2.5V to 5.5V VDD: 4.0V to 5.5V VDD: 4.5V to 5.5V VDD: VDD: 4.0V to 5.5V 2.7 mA typ. at 5.5V 5 mA max. at 5.5V 2.7 mA typ. at 5.5V 2.0 mA typ. at 3.0V 5 mA max. at 5.5V IDD: XT 1.5 µA typ, at 4V 21 uA max, at 4V 1.5 µA typ. at 4V IPD: 0.9 µA typ. at 3V IPD: 21 uA max, at 4V IPD: 4 MHz max. Frea: 4 MHz max. Freq: 4 MHz max. Frea/ Freq: 4 MHz max. Frea: 4 MHz max. VED: 4.5V to 5.5V 4.5V to 5.5V 4.51/to 5/51/ 4.5V to 5.5V VDD: VDD: VDD: 30 mA max. at 5.51 13.5 mA typ. at 5.5V 30 mA max. at 5.5V IDD: 30 mA max. at 5.5V IDD: IDD: HS Do not use in HS mode 1.5 µA typ. at 4.5V IPD: IPD: 1.5 μA typ. at 4.5V IPD: 1.5 μA typ. at 4.5V 1.5 µA typ. at 4.5V 20 MHz max. Frea: 4 MHz max. Freq: 10 MHz max. Frea: 10 MHz max. VOD: 2.5V to 5.5V 2.5V to 5.5V VDD: 4.0V to 5.5V 48 µA max. at 32 kHz, 3.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IDD:/ 48 μA max. at 32 kHz, 3.0V LP Do not use in LP mode Do not use in LP mode /5.0 μA max. at 3.0V 5.0 μA max. at 3.0V 0.9 μA typ. at 4.0V IPD: Freq: /200 kHz max. Freq: 200 kHz max. Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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TABLE

AND FREQUENCIES

유유

DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS OPERATION (COMMERCIAL DEVICES)

**Applicable Devices** 13<u>-</u>1:

710

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13.1 DC Characteristics:

PIC16C715-04 (Commercial, Industrial, Extended) PIC16C715-10 (Commercial, Industrial, Extended) PIC16C715-20 (Commercial, Industrial, Extended))

DC CHA	RACTERISTICS	COM: OM:		lard Or		iture (	ditions (unless otherwise stated) $0^{\circ}C \leq TA \leq +70^{\circ}C$ (commercial) $-40^{\circ}C \leq TA \leq +85^{\circ}C$ (industrial) $-40^{\circ}C \leq TA \leq +125^{\circ}C$ (extended)
Param. No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001 D001A	Supply Voltage	VDD	4.0 4.5	TW	5.5 5.5	V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	CON	1.5	-	V	Device in SLEEP mode
D003	VDD start voltage to ensure internal Power- on Reset signal	VPOR	Y.CO	Vss	LM.	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	COM	TW	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2)	IDD	N.100	2.7	5	mA .	XT, RC osc configuration (PIC16C715-04) Fosc = 4-MHz, VDD = 5.5V (Note 4)
D013	DY.COM.TW	WW	VI.I	13.5	30	mA	HS øsc configuration (PIC16C715-20) Fosc = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 5)	Δlbor	-<	300*	500	hA	BOR enabled VDD = 5.0V
D020 D021 D021A D021B	Power-down Current (Note 3)	IPD '	-	10.5 1.5 1.5	42 21 24 30	μΑ μΑ μΑ μΑ	$\label{eq:decomposition} \begin{split} \text{VDD} &= 4.0\text{V}, \text{WDT enabled, } \text{-}40^{\circ}\text{C to } +85^{\circ}\text{C} \\ \text{VDD} &= 4.0\text{V}, \text{WDT disabled, } \text{-}0^{\circ}\text{C to } +70^{\circ}\text{C} \\ \text{VDD} &= 4.0\text{V}, \text{WDT disabled, } \text{-}40^{\circ}\text{C to } +85^{\circ}\text{C} \\ \text{VDD} &= 4.0\text{V}, \text{WDT disabled, } \text{-}40^{\circ}\text{C to } +125^{\circ}\text{C} \end{split}$
D023	Brown-out Reset Current (Note 5)	Albor	/-/	300*	500	μА	BOR enabled VDD = 5.0V

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 51, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which you can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
    - The test conditions for all IDD measurements in active operation mode are:
    - ම්රිර් = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
    - MCLR = VDD; WDT enabled/disabled as specified.
  - 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.
  - 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
  - 5: The  $\Delta$  current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

#### 13.2 DC Characteristics: PIC16LC715-04 (Commercial, Industrial)

DC CHAF	RACTERISTICS	ony.Co	Standard Operating Conditions (unless otherwise stated)  Operating temperature $0^{\circ}\text{C} \leq \text{TA} \leq +70^{\circ}\text{C}$ (commercial) $-40^{\circ}\text{C} \leq \text{TA} \leq +85^{\circ}\text{C}$ (industrial)									
Param Characteristic S			Min	Тур†	Max	Units	Conditions					
D001	Supply Voltage	VDD	2.5	TIN	5.5	V	LP, XT, RC osc configuration (DC - 4 MHz)					
D002*	RAM Data Retention Voltage (Note 1)	VDR	1 CC	1.5	N -	V	Device in SLEEP mode					
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	00X.C	Vss	TW	V	See section on Power-on Reset for details					
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	1.CO	M.T.	V/ms	See section on Rower-on Reset for details					
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled					
D010	Supply Current (Note 2)	IDD	MM	2.0	3.8	mA	XT, RC osc configuration Fose 4 MHz, VDD = 3.0V (Note 4)					
D010A	OOY.COM.TW		WWX	22.5	48	pLA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled					
D015	Brown-out Reset Current (Note 5)	Δlbor	M.	300*	500	μA	BOR enabled VDD = 5.0V					
D020 D021 D021A	Power-down Current (Note 3)	IPD	-	7.5 0.9 0.9	30 5	μ <i>Α</i> μΑ μΑ	VDD = 3.0V, WDT enabled, -40°C to +85°C VDD = 3.0V, WDT disabled, 0°C to +70°C VDD = 3.0V, WDT disabled, -40°C to +85°C					
D023	Brown-out Reset Current (Note 5)	Δlbor		300*	500	μА	BOR enabled VDD = 5.0V					

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which YDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
    - The test conditions for all IDD measurements in active operation mode are:
    - DSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
    - MCLR VDD; WDT enabled/disabled as specified.
  - 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.
  - 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
  - 5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

PIC16C715-04 (Commercial, Industrial, Extended) 13.3 **DC Characteristics:** 

PIC16C715-10 (Commercial, Industrial, Extended)

PIC16C715-20 (Commercial, Industrial, Extended)

PIC16LC715-04 (Commercial, Industrial))

Standard Operating Conditions (unless otherwise stated)

Operating temperature 0°C ≤ TA ≤ +70°C (commercial)

-40°C  $\leq$  TA  $\leq$  +85°C (industrial)  $\leq$  TA  $\leq$  +125°C (extended) -40°C

Operating voltage VDD range as described in DC spec Section 13.1

and Section 13.2

-24.7.			ction 13.2			00 -	
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
Mo	Input Low Voltage	M.T.			- 3137	700	
COn	I/O ports	VIL	W		MM.	-1100	
D030	with TTL buffer	OM	Vss	-	0.5V	V	
D031	with Schmitt Trigger buffer	Mos	Vss	-	0.2VDD	V	
D032	MCLR, RA4/T0CKI,OSC1 (in RC mode)	$CO_{J}$	Vss	-	0.2VDD		
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	11/	Note1
100 Y.C	Input High Voltage I/O ports	ViH	DM.TV	×1-			
D040	with TTL buffer	07.	2.0	~	VDD	V '	4,5 ≤ VDD ≤ 5.5V
D040A	COM.	OOY.	0.8VDD	4	<b>YDD</b>	N	For VDD > 5.5V or VDD < 4.5V
D041	with Schmitt Trigger buffer	VO - 1	0.8VØD	( - )	VDD	V	For entire VDD range
D042	MCLR, RA4/T0CKI RB0/INT	700 x	0.8VDD	1	) ADD	V	M.100 r. COM.1
D042A	OSC1 (XT, HS and LP)	400	0,7VDD	1	VDD	V	Note1
D043	OSC1 (in RC mode)	$\wedge$	Q.9/VDD	-	<b>₩</b> DD	V	MAN. TO ON COM.
D070	PORTB weak pull-up current	PURB	50	250	400	μΑ	VDD = 5V, VPIN = VSS
D060	Input Leakage Current (Notes 2, 3) I/O ports	IIL		OM	±1	μА	Vss ≤ VPIN ≤ VDD, Pin at hi- impedance
D061	MCLR, RA4/T0CKI		-	DŌ?	±5	μA	Vss ≤ VPIN ≤ VDD
D063	OSC1	$\rangle$	1007	.cc	±5	μΑ	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
111	Output Low Voltage	/	44.	V.C	( 1)	W	1007.00
D080	I/O ports	Vol	11/1/200	V.	0.6	V	IOL = $8.5 \text{ mA}$ , VDD = $4.5 \text{V}$ , $-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$
D080A		W	M 15.	005	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)		MAN TO THE PROPERTY OF THE PRO	700	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D083A			MMA	1.10	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.
  - 2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages. WWW.100Y.C
  - 3: Negative current is defined as coming out of the pin.

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DC CHARACTERISTICS

DC CHARACTERISTICS

## Applicable Devices 710 71 711 715

#### Standard Operating Conditions (unless otherwise stated)

Operating temperature  $0^{\circ}\text{C} \leq \text{TA} \leq +70^{\circ}\text{C} \text{ (commercial)}$ 

 $-40^{\circ}\text{C} \leq \text{Ta} \leq +85^{\circ}\text{C} \text{ (industrial)}$ 

-40°C ≤ TA ≤ +125°C (extended)

Operating voltage VDD range as described in DC spec Section 13.1 and Section 13.2.

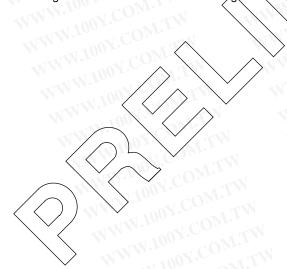
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
COM.	Output High Voltage	Mr.	- 1		TINV	. 3.00	CON-
D090	I/O ports (Note 3)	Voн	VDD - 0.7	-	MM.	N.V00	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D090A	CIW WWW.100Y.	COM	VDD - 0.7	-	W	V	IOH = -2.5 mA, VDD = 45V, -40°C to +125°C
D092	OSC2/CLKOUT (RC osc config)	CON	VDD - 0.7	-	-11	V	IOH = $-1.3$ mA, VDD = $4.5$ V, $-40$ °C to $+85$ °C
D092A	OM.TW WWW.100	Y.CO	VDD - 0.7	- N	- 1	V	IOH = -1.0 mA, VDB = 4.5V, -40°C to +(25°C
1.100 x	Capacitive Loading Specs on Output Pins	00.X°C	OM	W		1	
D100	OSC2 pin	Cosc <sub>2</sub>	$^{COM}$	ŢŢ	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	Cio	-1 CON	(-)	50	pΕ	Mary COM-

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

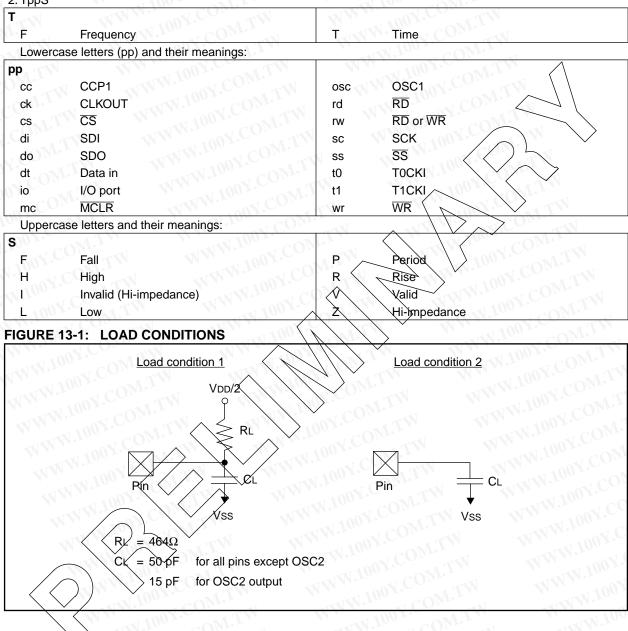


#### 13.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS



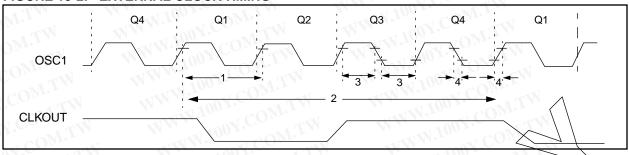


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#### 13.5 <u>Timing Diagrams and Specifications</u>

#### FIGURE 13-2: EXTERNAL CLOCK TIMING



#### **TABLE 13-2: CLOCK TIMING REQUIREMENTS**

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
100	Fos	External CLKIN Frequency	DC	) <u> </u>	<b>4</b>	MHz ,	XT osc mode
1100 X.		(Note 1)	DC	0/4/7	4	MHz	HS osc mode (PIC16C715-04)
V.		TW WWW	DC	<u> </u>	20/	MHz	HS osc mode (PIC16C715-20)
W.100		T. WWW.	DC	$C_{\overline{OZ}_{J_{J_{J_{J_{J_{J_{J_{J_{J_{J_{J_{J_{J_$	200	ķНz	LP osc mode
100		Oscillator Frequency	DC	Man	4	MHz	RC osc mode
111.		(Note 1)	0.1		A	MHz	XT osc mode
MW.In		OM.	4	$\leftarrow$	4/	MHz	HS osc mode (PIC16C715-04)
-TVV.1		ON.TV	4	$\wedge$ -\	10	MHz	HS osc mode (PIC16C715-10)
WWW.		CON TW WY	4	1	20	MHz	HS osc mode (PIC16C715-20)
TANY		COM.	18	77/	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250		COTA!	ns	XT osc mode
WW		(Note 1)	250	\ <u> </u>		ns	HS osc mode (PIC16C715-04)
-737			100	$\vee$ –	$^{1}$ $C_{O_{N_{1}}}$	ns	HS osc mode (PIC16C715-10)
		101-CM2	50	√N <del>1</del> 00	<del>-</del> 01	ns	HS osc mode (PIC16C715-20)
W			5	=10	N. L	μs	LP osc mode
		Oscillator Period	250	MAT	- CC	ns	RC osc mode
		(Note 1)	250	-x1 <del>-x</del> 1.1	10,000	ns	XT osc mode
			250	W	250	ns	HS osc mode (PIC16C715-04)
	WW		100	N N	250	ns	HS osc mode (PIC16C715-10)
			50	WANY	250	ns	HS osc mode (PIC16C715-20)
		$\langle \rangle$	5		M:700.	μs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200	M	DC	ns	Tcy = 4/Fosc
3//	TosL,	External Clock in (OSC1) High	50	-N1	V - V - V	ns	XT oscillator
	TosH	or Low Time	2.5		W.M.	μs	LP oscillator
	<	WW. TOOX.	10	_1/1	- <del></del> - 1	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise	4	- <	25	ns	XT oscillator
	TosF	or Fall Time		_	50	ns	LP oscillator
		WW. = 100X.	IM	_	15	ns	HS oscillator

Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C715.

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FIGURE 13-3: CLKOUT AND I/O TIMING

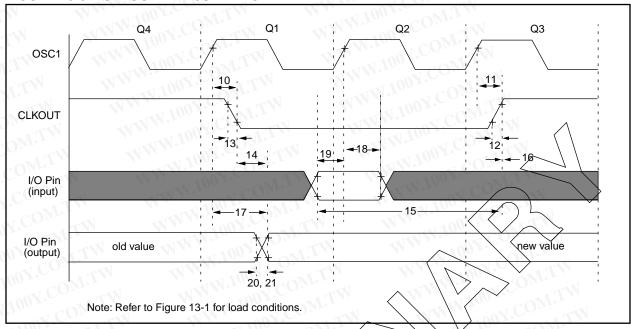


TABLE 13-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	01/100Y.CO	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	~ 100	\ <del>\</del>	15	30	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	DSC1↑ to CLKOUT↑				ns	Note 1
12*	TckR	CLKOUT rise time	1////	<u> </u>	5	15	ns	Note 1
13*	TckF	CLKOUT fall time		M	5	15	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out va	CLKOUT ↓ to Port out valid				ns	Note 1
15*	TioV2ckH	Port in valid before CLK	TUC	0.25Tcy + 25	_	1/1	ns	Note 1
16*	TckH2iol	Port in hold after CLKOL	л↑	CONO	_	THE WAY	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1) cycle) to Port out valid				80 - 100	ns	ov.con
18*	TosH2ioI	OSC11 (Q2 cycle) to Port input invalid (I/O in	hold time)	TBD	14	-444	ns	1007.CO
19*	TioV2osH	Port input valid to OSC1	↑ (I/O in setup time)	TBD	74	- 11	ns	1001
20*	TioR	Port output rise time	PIC16C715	V €ON	10	25	ns	ooy.C
			PIC16LC715	100, -00	1.7	60	ns	N.100
21* /	TioF	Port output fall time	PIC16C715	1007	10	25	ns	XX 100 X
		CONTRACT	PIC16LC715		- T	60	ns	100
22††*	Tinp	INT pin high or low time	20	$0\pi$ .		ns	MM	
23††*	Trbp	RB7:RB4 change INT hi	gh or low time	20	A.	7	ns	-11V.10

These parameters are characterized but not tested.

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

<sup>††</sup> These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

FIGURE 13-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, AND POWER-UP TIMER TIMING

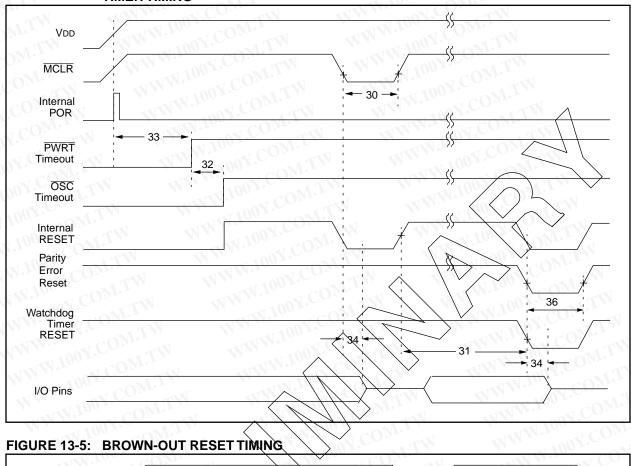


TABLE 13-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN OUT RESET REQUIREMENTS

**BV**DD

**←** 35 −

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	7mcL	MCLR Pulse Width (low)	2	T 100	1.5	μs	$VDD = 5V, -40^{\circ}C \text{ to } +125^{\circ}C$
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	$VDD = 5V, -40^{\circ}C \text{ to } +125^{\circ}C$
32	Tost	Oscillation Start-up Timer Period	_	1024Tosc	$00_{7}$ .		Tosc = OSC1 period
33*	Tpwrt	Power up Timer Period	28	72	132	ms	$VDD = 5V, -40^{\circ}C \text{ to } +125^{\circ}C$
34	Tıoz	I/O Hi-impedance from MCLR Low or Watchdog Timer Reset	_	MANN	2.1	μs	WY.IW WY
35	TBOR	Brown-out Reset pulse width	100	411	<u> </u>	μs	VDD ≤ BVDD (D005)
36	TPER	Parity Error Reset	- XX	TBD	1150	μs	OM.

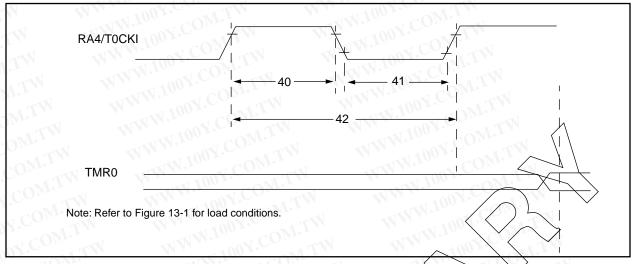
<sup>\*</sup> These parameters are characterized but not tested.

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VDD

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-6: TIMERO CLOCK TIMINGS

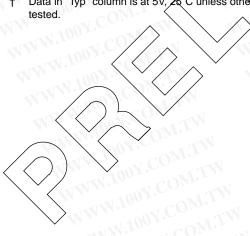


**TABLE 13-5: TIMERO CLOCK REQUIREMENTS** 

Param No.	Sym	Characteristic	OY.COM.TW	Min	Typ†	Max	Units	Conditions
40	TtOH	T0CKI High Pulse Width	No Prescaler	0.5Tc++20*	V	100	ns	DAT.
	Y.O.	TW	With Prescaler	10*	N N	1.100	ns	OM
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5TcY + 20*		N-40	ns	OMIT
	WY.CO	WW WW	With Prescaler	10*		<u>-</u> 1	ns	WILMO
42	Tt0P	T0CKI Period		Greater of: 20μs or <u>Tcy + 40</u> * N	4	MM M	A 6 1 1 1 1 1	N = prescale value (1, 2, 4,, 256)
48	Tcke2tmrl	Delay from external clock edg	e to timer increment	2Tosc		7Tosc	1.7	OV.COM

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not



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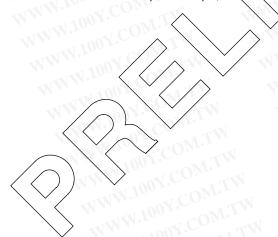
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TABLE 13-6: A/D CONVERTER CHARACTERISTICS:

PIC16C715-04 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16C715-10 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16C715-20 (COMMERCIAL, INDUSTRIAL, EXTENDED)

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
OMP	NR	Resolution	CO2	TW-	8-bits	100	VREF = VDD, VSS ≤ AIN ≤ VREF
$CO_{M-1}$	NINT	Integral error	Y.COM	LTW	less than ±1 LSb	N.E	VREF = VDD, VSS ≤ AIN ≤ VREF
I'COM	NDIF	Differential error	ON-CO	M.TH	less than ±1 LSb	VW.1	VREF = VDD, VSS ≤ AIN \$ VREF
Y.COM	NFS	Full scale error	007.C	OM. TW	less than ±1 LSb	WW	VREF = VDD, VSS ≤ AIN ≤ VREF
ON CO	Noff	Offset error	100 X .	ONLIV	less than ±1 LSb	NAN	VREF = VDØ, VSS \$AIN ≤ VREF
To CO	) <u>N</u> F.	Monotonicity	N 01	guaranteed	v —	1	VSS S AIN S VREF
100	VREF	Reference voltage	2.5V	- CO-1.	VDD + 0.3	V/	
100 Y.	VAIN	Analog input voltage	Vss - 0.3	M.7	VREF + 0.3	V\	
W.100Y.	ZAIN	Recommended impedance of analog voltage source	MM:10	ON.COM	10.0	kΩ	
NW.100	IAD	A/D conversion cur- rent (VDD)	NATA.	180		ptΑ	Average current consumption when A/D is on. (Note 1)
W.10	IREF	VREF input current (Note 2)	M.T.		1	mA μA	During sampling All other times

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.
  - 2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.



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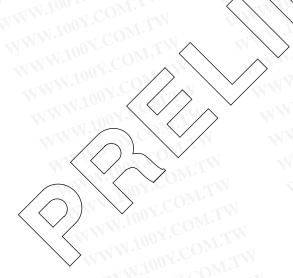
TABLE 13-7: A/D CONVERTER CHARACTERISTICS: PIC16LC715-04 (COMMERCIAL, INDUSTRIAL)

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
IN	NR	Resolution	M.F.		8-bits	<del></del>	VREF = VDD, VSS ≤ AIN ≤ VREF
TT	NINT	Integral error	M. <del>T</del> W	- 11	less than ±1 LSb	V.C	VREF = VDD, VSS ≤ AIN ≤ VREF
W.I.A.	NDIF	Differential error	ONT	v - <	less than ±1 LSb	OX.C	VREF = VDD, VSS ≤ AIN ≤ VREF
OMITW	NFS	Full scale error	$CO_{\overline{M}_{2}}$	W -	less than ±1 LSb	0 <u>07</u> .	VREF = VDD, VSS ≤ AIN ≤ VREF
COM.TY	Noff	Offset error	I.CA	IM —	less than ±1 LSb	100)	VREF = VDD, VSS ≤ AIN ≤ VREF
TIME	W _	Monotonicity	- OV	guaranteed	47	V.±OV	VSS AW VREF
(CO)	VREF	Reference voltage	2.5V	TA	VDD + 0.3	V	
ST COM	VAIN	Analog input voltage	Vss - 0.3	NY CAN	VREF + 0.3	V	
OY.COM	ZAIN	Recommended impedance of analog voltage source	100 × CO	ON.TW	10.0	kΩ	
100 X CC	IAD	A/D conversion current (VDD)	N.Tan.	CO 90		μА	Average current consumption when A/D is on. (Note 1)
1100 X C	IREF	VREF input current (Note 2)	1100	1.00	TO	mA μΑ	During sampling All other times

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- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.
  - 2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

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#### FIGURE 13-7: A/D CONVERSION TIMING

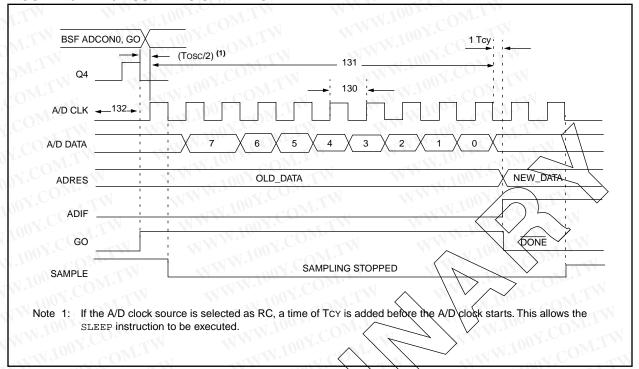


TABLE 13-8: A/D CONVERSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typt	Max	Units	Conditions
130	TAD	A/D clock period	1.6			μs μs	VREF ≥ 3.0V VREF full range
130	TAD	A/D Internal RC Oscillator source			Y.COM.	TW	ADCS1:ADCS0 = 11 (RC oscillator source)
W	N. 1.	MOX.COM	3.0	6.0	9.0 6.0	μs μs	PIC16LC715, VDD = 3.0V PIC16C715
131	TCNV	Conversion time (not including S/H time). Note 1		9.5TAD	100X-CO	MIT	M MMM.1002
132	TACQ	Acquisition time	Note 2	20	TOTAL.C	μs	THE WATER

\* These parameters are characterized but not tested.

† Data in type column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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Note 1: ADRES register may be read on the following Tcy cycle.

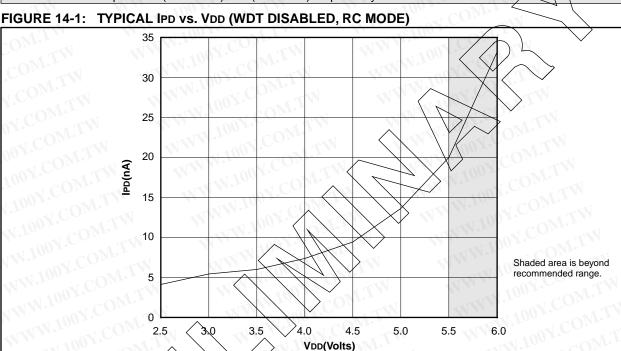
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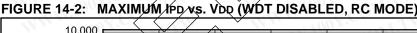
#### 14.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C715

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified VDD range). This is for information only and devices are guaranteed to operate properly only within the specified range.

**Note:** The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at,  $25^{\circ}$ C, while 'max' or 'min' represents (mean +3 $\sigma$ ) and (mean -3 $\sigma$ ) respectively where  $\sigma$  is standard deviation.





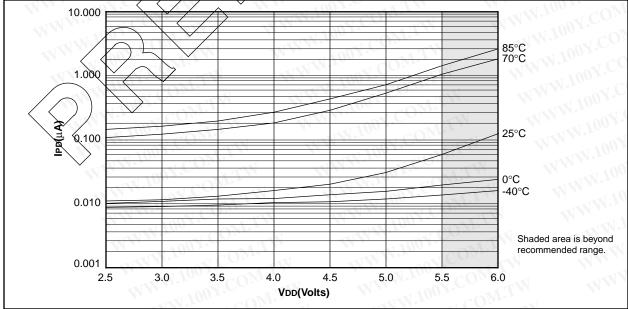


FIGURE 14-3: TYPICAL IPD vs. VDD @ 25°C (WDT ENABLED, RC MODE)

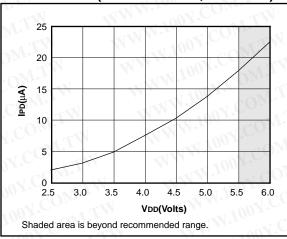
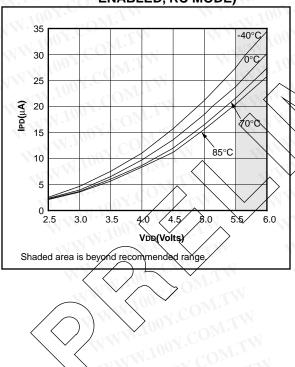


FIGURE 14-4: MAXIMUM IPD vs. VDD (WDT ENABLED, RC MODE)



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FIGURE 14-5: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

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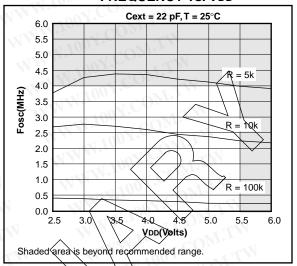


FIGURE 14-6: TYPICAL RC OSCILLATOR
FREQUENCY vs. VDD

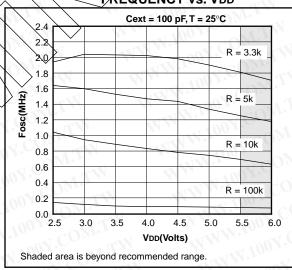


FIGURE 14-7: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

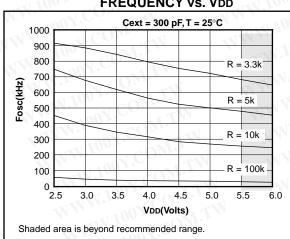


FIGURE 14-8: TYPICAL IPD vs. VDD BROWN-OUT DETECT ENABLED (RC MODE)

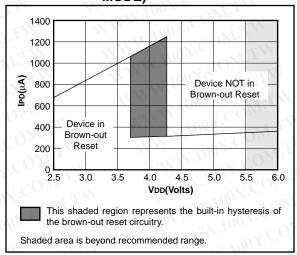


FIGURE 14-9: MAXIMUM IPD vs. VDD BROWN-OUT DETECT ENABLED (85°C TO -40°C, RC MODE)

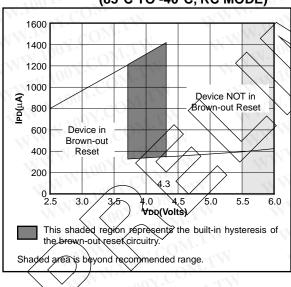


FIGURE 14-10: TYPICAL IPD vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, RC MODE)

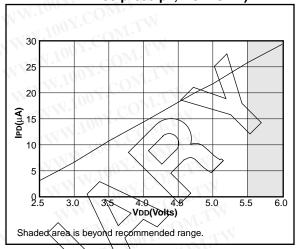
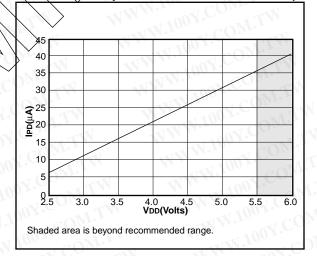


FIGURE 14-11: MAXIMUM IPD vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, 85°C TO -40°C, RC MODE)



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FIGURE 14-12: TYPICAL IDD vs. FREQUENCY (RC MODE @ 22 pF, 25°C)

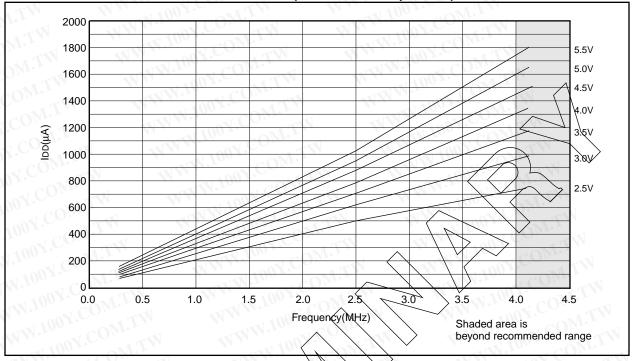


FIGURE 14-13: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 22 pF, -40°C TO 85°C)

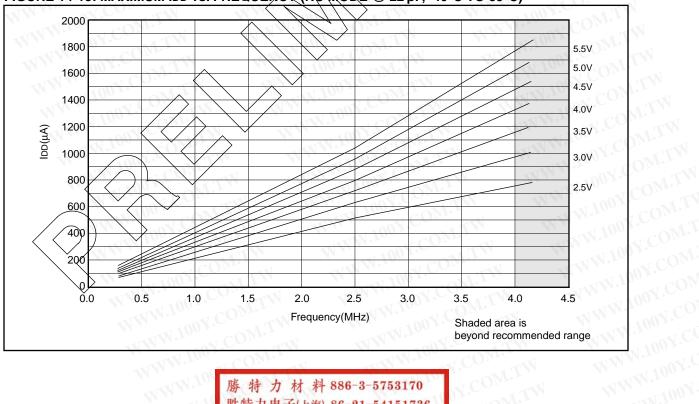


FIGURE 14-14: TYPICAL IDD vs. FREQUENCY (RC MODE @ 100 pF, 25°C)

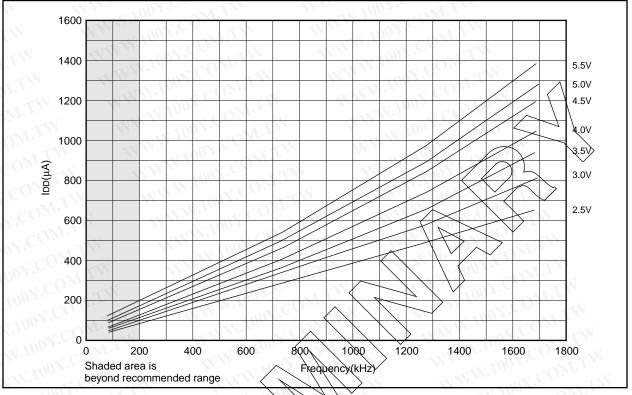
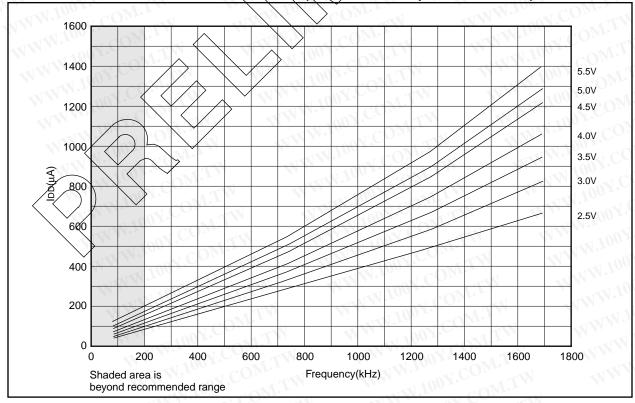


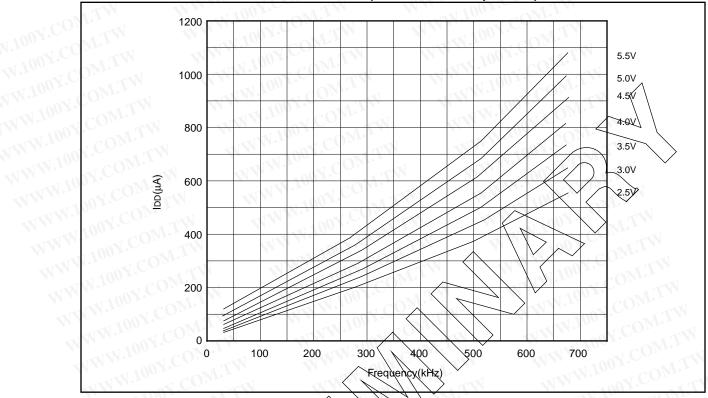
FIGURE 14-15: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO 85°C)



# **PIC16C71X**

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FIGURE 14-16: TYPICAL IDD vs. FREQUENCY (RC MODE @ 300 pF, 25°C)



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FIGURE 14-17: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)

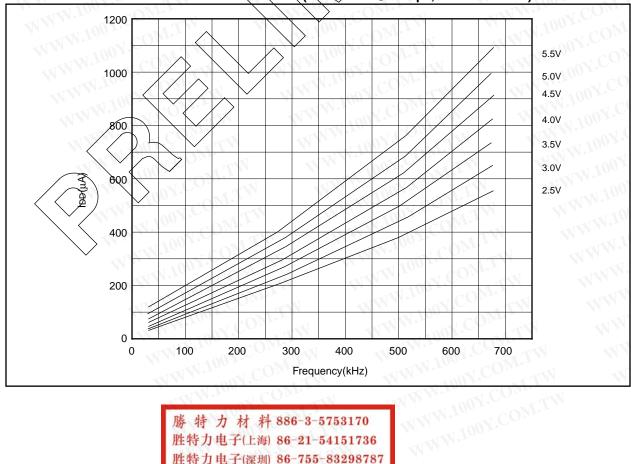


FIGURE 14-18: TYPICAL IDD vs.

CAPACITANCE @ 500 kHz

(RC MODE)

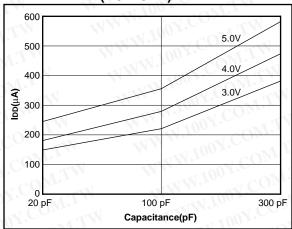


TABLE 14-1: RC OSCILLATOR FREQUENCIES

Cext	Rext	Average	
Cext	Kext	Fosc @ 5V, 2	25°C
22 pF	5k	4.12 MHz	± 1.4%
	10k	2.35 MHz	± 1.4%
	100k	268 kHz	±1,1%
100 pF	3.3k	1.80 MHz	±1.0%
	5k	1.27 MHz	± 1.0%
	10k	688 kHz	± 1.2%
	100k	77.2 kH2	± 1.0%
300 pF	3.3k	707 kHz	± 1.4%
	5k	501 kHz	± 1.2%
	10k	269 kHz	± 1.6%
	100k	28.3 kHz	± 1.1%

The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

FIGURE 14-19: TRANSCONDUCTANCE(gm)
OF HS OSCILLATOR vs. VDD

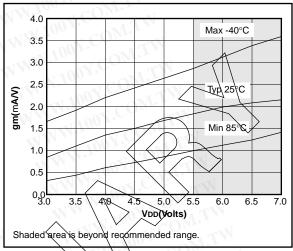


FIGURE 14-20: TRANSCONDUCTANCE(gm)

OF LP OSCILLATOR vs. VDD

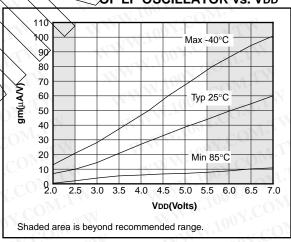


FIGURE 14-21: TRANSCONDUCTANCE(gm)
OF XT OSCILLATOR vs. VDD

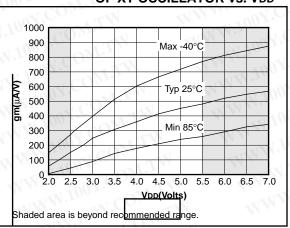


FIGURE 14-22: TYPICAL XTAL STARTUP TIME vs. VDD (LP MODE, 25°C)

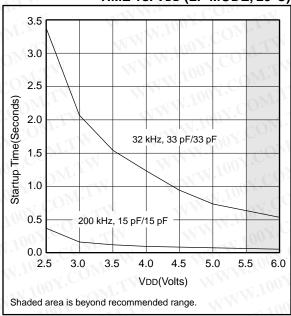


FIGURE 14-23: TYPICAL XTAL STARTUP TIME vs. VDD (HS MODE, 25°C)

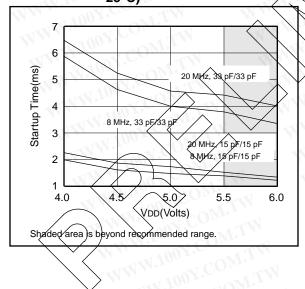


FIGURE 14-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

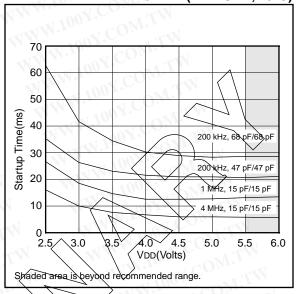


TABLE 14-2: CAPACITOR SELECTION
FOR CRYSTAL
OSCILLATORS

sc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
any CC	W	WW	You Y
Crystals Used	OM	I W	1100
32 kHz	Epson C-00	1R32.768K-A	± 20 PPM
200 kHz	STD XTL 2	00.000KHz	± 20 PPM
1 MHz	ECS ECS-1	10-13-1	± 50 PPM
4 MHz	ECS ECS-4	10-20-1	± 50 PPM
O MALL	EPSON CA	-301 8.000M-C	± 30 PPM
8 MHz		-301 20.000M-C	± 30 PPM

FIGURE 14-25: TYPICAL IDD vs. FREQUENCY (LP MODE, 25°C)

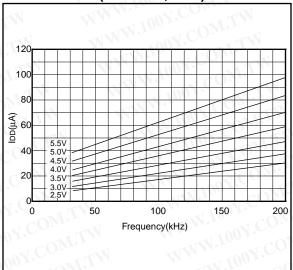


FIGURE 14-26: MAXIMUM IDD vs. FREQUENCY (LP MODE, 85°C TO -40°C)

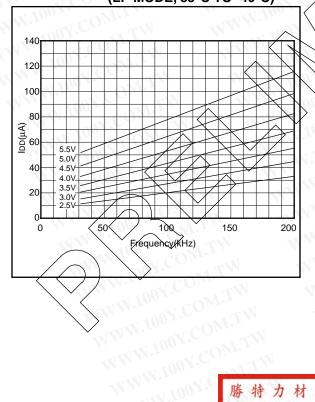


FIGURE 14-27: TYPICAL IDD vs. FREQUENCY (XT MODE, 25°C)

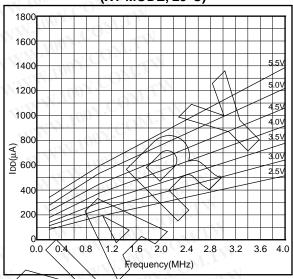
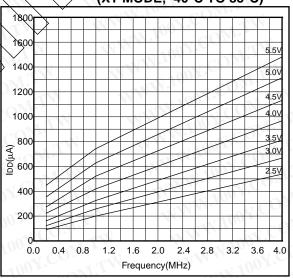


FIGURE 14-28: MAXIMUM IDD vs.
FREQUENCY
(XT MODE, -40°C TO 85°C)

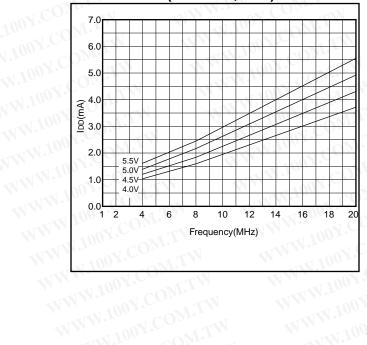


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FIGURE 14-29: TYPICAL IDD vs. FREQUENCY (HS MODE, 25°C)



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WWW.100Y.CC

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100Y.COM.TW

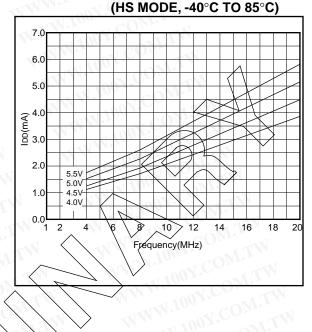
FIGURE 14-30: MAXIMUM IDD vs. **FREQUENCY** 

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#### 15.0 ELECTRICAL CHARACTERISTICS FOR PIC16C71

#### **Absolute Maximum Ratings †**

Ambient temperature under bias	MM. 2100X5 2V ZM	55 to +125°C
Storage temperature	MM TONY CO. T. T.M.	65°C to +150°C
Voltage on any pin with respect to Vss (except Vi	DD, MCLR, and RA4)	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	TOWN TO COME	-0.3 to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	COMP.	0 to +14V
Voltage on RA4 with respect to Vss	勝 符 刀 材 料 886-3-5753170 胜特力电子(上海) 86-21-54151736 胜特力电子(深圳) 86-755-83298787	000 11177
Output clamp current, lok (Vo < 0 or Vo > VDD)	ONCIAL CONTINUES	± 20 mA
Maximum output current sunk by any I/O pin Maximum output current sourced by any I/O pin .	-0W <sub>2</sub> ,	25 mA
Maximum current sunk by PORTA		
Maximum current sourced by PORTA	A CO TON ALM ALM ALM AND A CO	50 mA
Maximum current sunk by PORTB	$\leq CO_{M_{\bullet}}$ and $\sim CO_{M_{\bullet}}$	150 mA
Maximum current sourced by PORTB	COMP.	100 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD -  $\Sigma$  IOH} +  $\Sigma$  {(VDD-VOH) x IOH} +  $\Sigma$ (Vol x IOL)

Note 2: Voltage spikes below Vss at the  $\overline{MCLR}$  pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 $\Omega$  should be used when applying a "low" level to the  $\overline{MCLR}$  pin rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 15-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C71-04	PIC16C71-20	PIC16LC71-04	JW Devices	
RC	IPD: 14 μA max. at 4V   IPD: 1.0 μA typ. at 4V   Freq: 4 MHz max.   VDD: 4.0V to 6.0V   IDD: 3.3 mA max. at 5.5V   IDD: 1.8 mA typ. at 5.5V   IPD: 14 μA max. at 4V   Freq: 4 MHz max.   VDD: 4.5V to 5.5V   IDD: 4.5V to 5.5V   IDD: 4.5V to 5.5V   IDD: 3.5 mA typ. at 5.5V   IDD: 30 mA max. at 5.5V   IDD		VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 μA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq:4 MHz max.	
ХТ			VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 μA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.	
HS			Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 μA typ. at 4.5V Freq: 20 MHz max.	
LP	VDD: 4.0V to 6.0V IDD: 15 μA typ. at 32 kHz, 4.0V IPD: 0.6 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 32 μA max. at 32 kHz, 3.0V IPD: 9 μA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 32 μA max. at 32 kHz, 3.0V IPD: 9 μA max. at 3.0V Freq: 200 kHz max.	

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

# PIC16C71X

## Applicable Devices 710 71 711 715

15.1 DC Characteristics: PIC16C71-04 (Commercial, Industrial) PIC16C71-20 (Commercial, Industrial)

DC CH	ARACTERISTICS	litions (unless otherwise stated) $^{\circ}$ C $\leq$ TA $\leq$ +70 $^{\circ}$ C (commercial) $^{\circ}$ C $\leq$ TA $\leq$ +85 $^{\circ}$ C (industrial)					
Param No.	Characteristic	Sym	Min	Тур†	Мах	Units	Conditions
D001 D001A	Supply Voltage	VDD	4.0 4.5	LTW	6.0 5.5	V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	y.CO	1.5	<u>-</u>	V	WWW.100 COM.TW
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	07 <u>.</u> C	Vss	TW TW	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	CO <sub>E</sub>	T.N	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2)	IDD	W.10	1.8	3.3	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013	100X.COM.TW	W		13.5	30	mA	HS osc configuration Fosc = 20 MHz, VDD = 5.5V
D020 D021 D021A	Power-down Current (Note 3)	IPD	NAV	7 1.0 1.0	28 14 16	μΑ μΑ μΑ	VDD = 4.0V, WDT enabled, -40°C to +85°C $VDD = 4.0V$ , WDT disabled, -0°C to +70°C $VDD = 4.0V$ , WDT disabled, -40°C to +85°C

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

#### 15.2 DC Characteristics: PIC16LC71-04 (Commercial, Industrial)

DC CHA	RACTERISTICS		Standa OOper	itions (unless otherwise stated) $C \leq TA \leq +70^{\circ}C$ (commercial) $0^{\circ}C \leq TA \leq +85^{\circ}C$ (industrial)			
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	VDD	3.0	-	6.0	V	XT, RC, and LP osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	T.M	1.5	- 1	V	N.100Y.COM.TW
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	COM	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	M.T	N N	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2)	IDD	oy.C	1.4	2.5	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A	COM.TW W	WW.	007	15	32	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D020 D021 D021A	Power-down Current (Note 3)	IPD	N.100	5 0.6 0.6	20 9 12	μΑ μΑ μΑ	VDD = 3.0V, WDT enabled, -40°C to +85°C VDD = 3.0V, WDT disabled, 0°C to +70°C VDD = 3.0V, WDT disabled, -40°C to +85°C

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: This is the limit to which VDD can be lowered without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
    - The test conditions for all IDD measurements in active operation mode are:
    - OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
    - MCLR = VDD; WDT enabled/disabled as specified.
  - 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and Vss.
  - 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

# PIC16C71X

Applicable Devices 710 71 711 715

15.3 DC Characteristics: PIC16C71-04 (Commercial, Industrial)

PIC16C71-20 (Commercial, Industrial) PIC16LC71-04 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated)

OOperating temperature  $0^{\circ}C$   $\leq TA \leq +70^{\circ}C$  (commercial)

**DC CHARACTERISTICS** -40°C ≤ TA ≤ +85°C (industrial)

Operating voltage VDD range as described in DC spec Section 15.1

and Section 15.2.

Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
I.Com	Input Low Voltage	4 N			1/1/4	×110	DY.C. M.TW
	I/O ports	VIL	-TXV				OY.COM
D030	with TTL buffer		Vss	-	0.15V	V	For entire VDD range
D031	with Schmitt Trigger buffer		Vss	-	0.8V	V	4.5 ≤ VDD ≤ 5.5V
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2VDD	V	ON.COM TY
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	V	Note1
JOOY!	Input High Voltage	DA:C.	TIME				M.1001.
	I/O ports (Note 4)	VIH	Olar	ON T		WW	W. CON. CO.
D040	with TTL buffer		2.0	-	Vdd	٧	4.5 ≤ VDD ≤ 5.5V
D040A	COWIN MANA		0.25VDD + 0.8V	L31	VDD		For entire VDD range
D041	with Schmitt Trigger buffer		0.85VDD	7.7	VDD		For entire VDD range
D042	MCLR, RB0/INT		0.85VDD	<b>1-1</b>	VDD	٧	THE TANK THE
D042A	OSC1 (XT, HS and LP)		0.7VDD	17.	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	M	VDD	V	M.100 COM.
D070	PORTB weak pull-up current	IPURB	50	250	†400	μΑ	VDD = 5V, VPIN = VSS
D060	Input Leakage Current (Notes 2, 3) I/O ports	IIL	100 X.C		±1	μА	Vss ≤ VPIN ≤ VDD, Pin at hi- impedance
D061	MCLR, RA4/T0CKI		1.700	r (E)	±5	uΑ	Vss ≤ Vpin ≤ Vdd
D063	OSC1		W.100	7.0	±5	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage	-411	V. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1.	~ <b>*</b> 7	$CO_{M_{p}}$	-XXI	WWW. COV. CO
D080	I/O ports	Vol	WW.10	00. 10 <sup>-</sup> 3	0.6	V	IOL = 8.5mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		WW <del>-</del> W.	10	0.6	٧	IOL = 1.6mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage		MW	. 41	WY.C.		[N NN 100]
D090	I/O ports (Note 3)	Vон	VDD - 0.7	N-T	1001	OV.	IOH = -3.0mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	Y A	1.100Y		IOH = -1.3mA, VDD = 4.5V, -40°C to +85°C
D130*	Open-Drain High Voltage	Vod	- 11	۳-	14	V	RA4 pin

- Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC16C71 be driven with external clock in RC mode.
  - 2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
  - 3: Negative current is defined as current sourced by the pin.
  - 4: PIC16C71 Rev. "Ax" INT pin has a TTL input buffer. PIC16C71 Rev. "Bx" INT pin has a Schmitt Trigger input buffer.

DC CHAI	RACTERISTICS	OOperat	ing tem g voltag	peratu ge VDD	re 0°C -40°	°C ≤	nless otherwise stated) TA ≤ +70°C (commercial) TA ≤ +85°C (industrial) cribed in DC spec Section 15.1
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
M.TW	Capacitive Loading Specs on Output Pins	LW.			W.10	N. C	OM.TW
D100	OSC2 pin	Cosc <sub>2</sub>		W	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	Cio		1	50	pF	. TWIN

- Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC16C71 be driven with external clock in RC mode.
  - The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
  - 3: Negative current is defined as current sourced by the pin.
  - 4: PIC16C71 Rev. "Ax" INT pin has a TTL input buffer. PIC16C71 Rev. "Bx" INT pin has a Schmitt Trigger input buffer.

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### 15.4 <u>Timing Parameter Symbology</u>

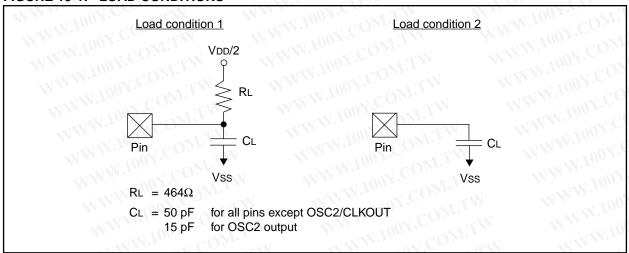
The timing parameter symbols have been created following one of the following formats:

- 1. TppS2ppS
- 2. TppS

Ē	Frequency	T	Time
Lowerd	case letters (pp) and their meanings:		MW.100 COM.
р		TW	
CC	CCP1	osc	OSC1
ck	CLKOUT	rd	RD
cs	CS WY	rw	RD or WR
di C	SDI	sc	SCK
do	SDO	SS	SS WWW.CO
dt	Data in	t0	TOCKI
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR

S 100		on . CONT.	- 1
F	Fall	P Period	In
H	High	Rise	WT
100	Invalid (Hi-impedance)	Valid	
L	Low	Z Hi-impedance	W. F.

#### FIGURE 15-1: LOAD CONDITIONS



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#### 15.5 <u>Timing Diagrams and Specifications</u>

#### FIGURE 15-2: EXTERNAL CLOCK TIMING

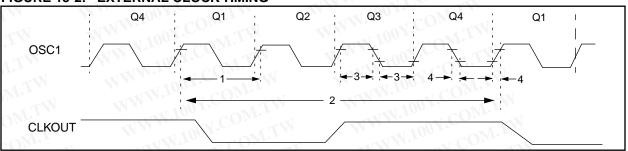


TABLE 15-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
N.CO	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT osc mode
	-33	(Note 1)	DC	<del>-</del>	4	MHz	HS osc mode (-04)
	LTW	W. 100 1.	DC	_	20	MHz	HS osc mode (-20)
	VT	WW. 1007.Co	DC	N _	200	kHz	LP osc mode
	Mr.	Oscillator Frequency	DC	CXX <del>I</del>	4	MHz	RC osc mode
	M.T.	(Note 1)	0.1	<u> </u>	4	MHz	XT osc mode
	J = 1 1	MM 100X.	1	TI	4	MHz	HS osc mode
	OM.	WWW.I	C 1	N <del>ew</del>	20	MHz	HS osc mode
N 100 1	Tosc	External CLKIN Period	250	1	_	ns	XT osc mode
	CO	(Note 1)	250	T.	_	ns	HS osc mode (-04)
	$^{1}$ CO $_{\tilde{L}}$	II. WWW.I	50		N -	ns	HS osc mode (-20)
		M.1.	5	$O_{\overline{M}^{*,r}}$		μs	LP osc mode
	M.C.	Oscillator Period	250	17		ns	RC osc mode
	N.C	(Note 1)	250	$CO_{\overline{N}_{x}}$	10,000	ns	XT osc mode
	00 7.	OW. I	250	c <del>o</del> M	1,000	ns	HS osc mode (-04)
	001.	WITH WITH	50		1,000	ns	HS osc mode (-20)
		COMP. WAY	5	V.CO.	, <del>T</del> V	μs	LP osc mode
2	Tcy	Instruction Cycle Time (Note 1)	1.0	Tcy	DC	μs	Tcy = 4/Fosc
3	TosL,	External Clock in (OSC1) High or	50	0.7-	WHI.A.	ns	XT oscillator
	TosH	Low Time	2.5	oot.C	- T	Nμs	LP oscillator
	W.10		10		$0\overline{M}$ .	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise or	25	10 <del>0</del> .	- OTA	ns	XT oscillator
	TosF	Fall Time	50	<del>m</del> y	COP	ns	LP oscillator
	-TIN	Inn COM.	15	1.700	- com	ns	HS oscillator

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C71.

FIGURE 15-3: CLKOUT AND I/O TIMING

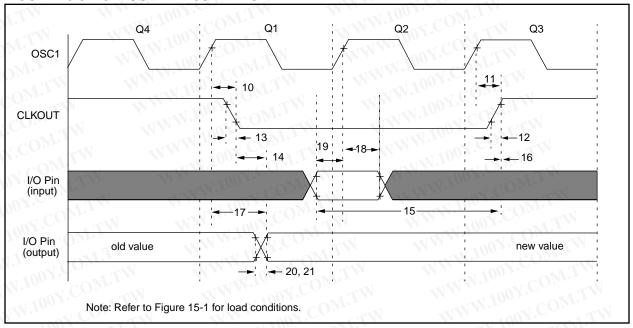


TABLE 15-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	1001.	W.T.W	15	30	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	MM 1001.	W.	15	30	ns	Note 1
12*	TckR	CLKOUT rise time	WWW.	CONT	5	15	ns	Note 1
13*	TckF	CLKOUT fall time	A. 100.	COM	5	15	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out va	id	7/17	<b>*</b>	0.5Tcy + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKO	UT 1	0.25Tcy + 25	W.	-111	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑		0	-AN	- 11	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		ON COM		80 - 100	ns	100 Y.C.
18*	TosH2iol	OSC1↑ (Q2 cycle) to	PIC16 <b>C</b> 71	100	_	( — ,	ns	V. Page 1
	NWW	Port input invalid (I/O in hold time)	PIC16 <b>LC</b> 71	200	VIT.		ns	M. Ing
19*	TioV2osH	Port input valid to OSC11	(I/O in setup time)	0	$\overline{M}$ .		ns	Mila
20*	TioR	Port output rise time	PIC16 <b>C</b> 71	1001.	10	25	ns	-XIV 100
	WW	W. T. COM.	PIC16 <b>LC</b> 71	1110X.C	_	60	ns	10
21*	TioF	Port output fall time	PIC16 <b>C</b> 71	WW. H	10	25	ns	MMM.
		W.100 Y. COM.	PIC16 <b>LC</b> 71	11/1/100	. ~0	60	ns	1.WW.1
22††*	Tinp	INT pin high or low time	TW V	20		M.TW	ns	W TAN
23††*	Trbp	RB7:RB4 change INT hig	h or low time	20	Z.C.	-W	ns	MA

<sup>\*</sup> These parameters are characterized but not tested.

<sup>†</sup>Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

<sup>††</sup> These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

FIGURE 15-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

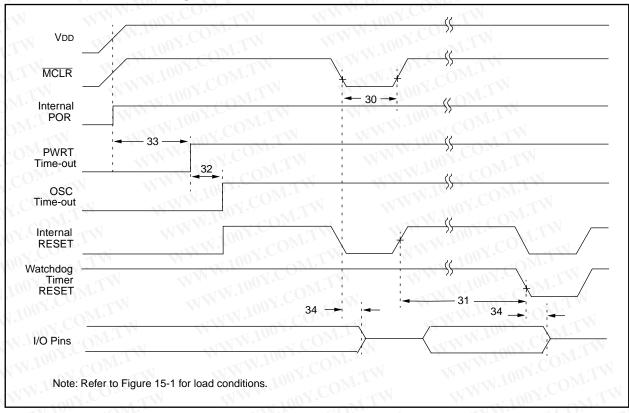


TABLE 15-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	200	1.0 = M	U	ns	$VDD = 5V, -40^{\circ}C \text{ to } +85^{\circ}C$
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	$VDD = 5V, -40^{\circ}C \text{ to } +85^{\circ}C$
32	Tost	Oscillation Start-up Timer Period	1 W.	1024 Tosc	117		Tosc = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5V, -40°C to +85°C
34	Tıoz	I/O High Impedance from MCLR Low	NI.	1.10 <del>0</del> 4.C	100	ns	WWW.1003

<sup>\*</sup> These parameters are characterized but not tested.

<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-5: TIMERO EXTERNAL CLOCK TIMINGS

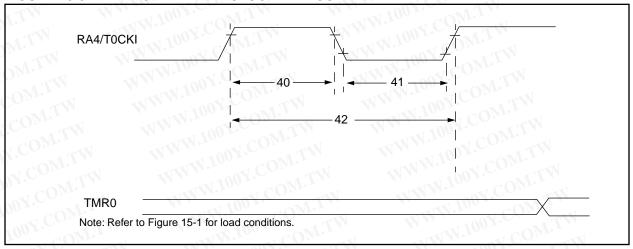


TABLE 15-5: TIMERO EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions	
40* Tt0H	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5Tcy + 20	1	= 1	ns	Must also meet
	COM	With Prescaler	10	-1	MA.	ns	parameter 42	
41* TtOL	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5Tcy + 20	_	THE	ns	Must also meet
		With Prescaler	10	_	- TXX	ns	parameter 42	
42* Tt0P	T0CKI Period	No Prescaler	Tcy + 40	_	AT.	ns	N = prescale value	
	N.10		With Prescaler	Greater of: 20 ns or TCY + 40 N		N	WW	(2, 4,, 256)

These parameters are characterized but not tested.

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<sup>†</sup> Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

### TABLE 15-6: A/D CONVERTER CHARACTERISTICS

Param No.	Sym	Characteristic	TW	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		-4	V ATT 10	8 bits	bits	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A02	EABS	Absolute error	PIC16 <b>C</b> 71	- 1	WE WAY	< ±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
		WW 1007.0	PIC16 <b>LC</b> 71	_	-	< ±2	LSb	VREF = VDD = 3.0V (Note 3)
A03	NEIL	Integral linearity error	PIC16 <b>C</b> 71	N —	NZ V	< ±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
	W	11 100	PIC16 <b>LC</b> 71	- T	<u> </u>	< ±2	LSb	VREF = VDD = 3.0V (Note 3)
A04	EDL	Differential linearity error	PIC16 <b>C</b> 71	LA-		< ±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
	LTV	W 10	PIC16 <b>LC</b> 71	1.7.7.	- "	< ±2	LSb	VREF = VDD = 3.0V (Note 3)
A05	EFS	Full scale error	PIC16 <b>C</b> 71	M.FIN	- 1	< ±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
	M	M. M.	PIC16 <b>LC</b> 71	$M_{\overline{A}}$	_	< ±2	LSb	VREF = VDD = 3.0V (Note 3)
A06	EOFF	Offset error	PIC16 <b>C</b> 71	$ON_{L,L}$		< ±1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
		TIM M.	PIC16 <b>LC</b> 71	~O <del>M</del> L.)	_	< ±2	LSb	VREF = VDD = 3.0V (Note 3)
A10	ica.	Monotonicity	Monotonicity		guaranteed	10	-XT10	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage		3.0V	114	VDD + 0.3	V	ONTO
A25	VAIN	Analog input voltage		Vss - 0.3		VREF	V	OV.COM
A30	ZAIN	Recommended impedance of analog voltage source		<sup>07</sup> . <u>C</u> 0	V. I <del>.</del>	10.0	kΩ	TOOX.COM.
A40	IAD	A/D conversion current (VDD)		007.C	180	_	μА	Average current consumption when A/D is on. (Note 1
A50	IREF	VREF input current (Note 2)	PIC16 <b>C</b> 71	10	COM.TV COM.T COM.T	1000	μΑ	During VAIN acquisition. Based on differential of VHOLD to VAIN. To charge CHOLD see Section 7.1. During A/D Conversion cycle
	NN NNN	100X.COM.TW (.100X.COM.TW W.100X.COM.TW	PIC16 <b>LC</b> 71	$N\overline{M}N$ . $MN$ .1 $N\overline{M}$ .1	100X <sup>.CO</sup>	10	mA μA	During VAIN acquisition. Based on differential of VHOLD to VAIN. To charge CHOLD see Section 7.1. During A/D Conversion cycle

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.
  - 2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.
  - 3: These specifications apply if VREF = 3.0V and if VDD ≥ 3.0V. VAIN must be between VSS and VREF.

### FIGURE 15-6: A/D CONVERSION TIMING

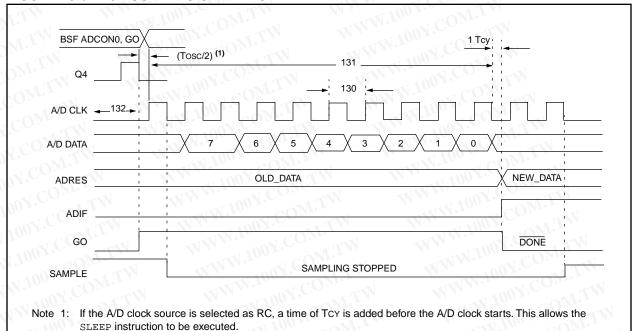


TABLE 15-7: A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic	MAIN	Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	PIC16 <b>C</b> 71	2.0		TAN	μs	Tosc based, VREF ≥ 3.0V
***	WW.	COM	PIC16 <b>LC</b> 71	2.0	$\sqrt{C_{O_B}}$	<del>π</del> 1/	μs	Tosc based, VREF full range
11	- NV	100 r. COW: 1.	PIC16 <b>C</b> 71	2.0	4.0	6.0	μs	A/D RC Mode
		100Y. ON.T	PIC16 <b>LC</b> 71	3.0	6.0	9.0	μs	A/D RC Mode
131	TCNV	Conversion time (not including S/H time) (Note 1)		W <u>-</u>	9.5	OM.T	TAD	MM.1003.
132	TACQ	Acquisition time	J.M.	Note 2	20	NEDO	μs	W.100
	W	M.M.M.100X.CO		5*	M.M.10 M.100 M.100 M.100	00Y.CO	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 19.5 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
134	Tgo	Q4 to A/D clock start	COM.TW	-	Tosc/2§	× 100 100 100 100	CON	If the A/D clock source is selected as RC, a time of Tcy is added before the A/D clock starts. This allows the SLEEP
		WW.Io.		V.			V.C	instruction to be executed.

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- § These specifications ensured by design.
- Note 1: ADRES register may be read on the following TcY cycle.
  - 2: See Section 7.1 for min conditions.

# 16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C71

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed. In some graphs or tables the data presented are outside specified operating range (e.g. outside specified VDD range). This is for information only and devices are guaranteed to operate properly only within the specified range.

Note: The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution while 'max' or 'min' represents (mean + 3σ) and (mean - 3σ) respectively where σ is standard deviation.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs.
TEMPERATURE

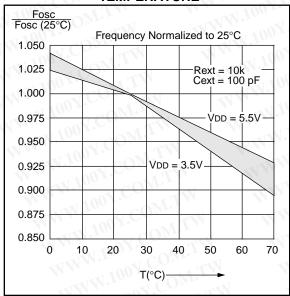


FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

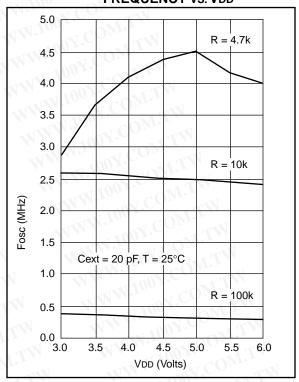


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

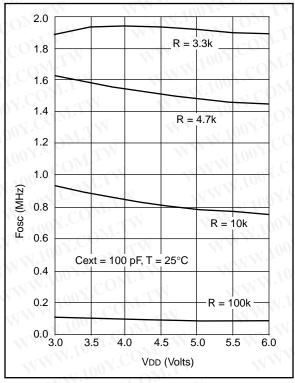


FIGURE 16-4: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

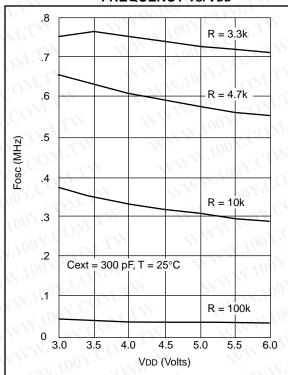
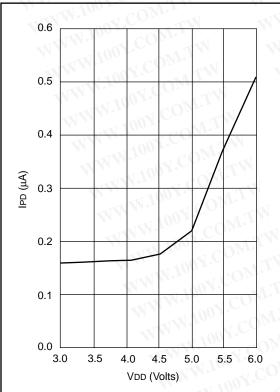


FIGURE 16-5: TYPICAL IPD VS. VDD **WATCHDOG TIMER DISABLED 25°C** 



**TABLE 16-1: RC OSCILLATOR FREQUENCIES** 

0.01	ODY	Average				
Cext	Rext	Fosc @ 5V, 25°C				
20 pF	4.7k	4.52 MHz	±17.35%			
	10k	2.47 MHz	±10.10%			
	100k	290.86 kHz	±11.90%			
100 pF	3.3k	1.92 MHz	±9.43%			
	4.7k	1.49 MHz	±9.83%			
	10k	788.77 kHz	±10.92%			
	100k	88.11 kHz	±16.03%			
300 pF	3.3k	726.89 kHz	±10.97%			
	4.7k	573.95 kHz	±10.14%			
	10k	307.31 kHz	±10.43%			
	100k	33.82 kHz	±11.24%			

The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

FIGURE 16-6: TYPICAL IPD vs. VDD **WATCHDOGTIMER ENABLED** 25°C

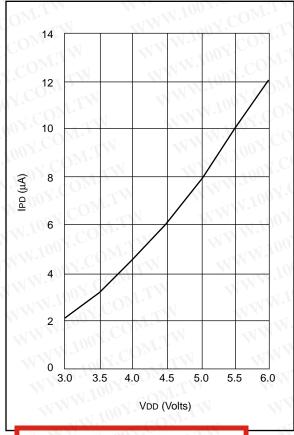


FIGURE 16-7: MAXIMUM IPD VS. VDD WATCHDOG DISABLED

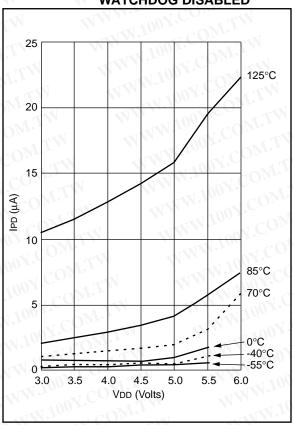
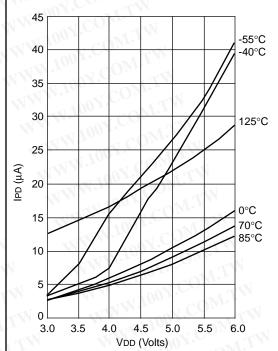


FIGURE 16-8: MAXIMUM IPD vs. VDD WATCHDOG ENABLED



IPD, with Watchdog Timer enabled, has two components: The leakage current which increases with higher temperature and the operating current of the Watchdog Timer logic which increases with lower temperature. At -40°C, the latter dominates explaining the apparently anomalous behavior.

FIGURE 16-9: VTH (INPUT THRESHOLD VOLTAGE) OF I/O PINS vs. VDD

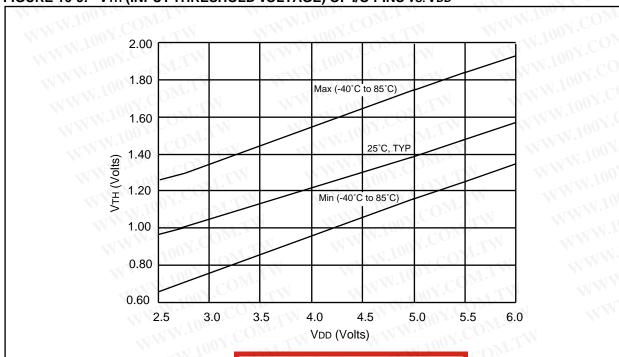


FIGURE 16-10: VIH, VIL OF MCLR, TOCKI AND OSC1 (IN RC MODE) vs. VDD

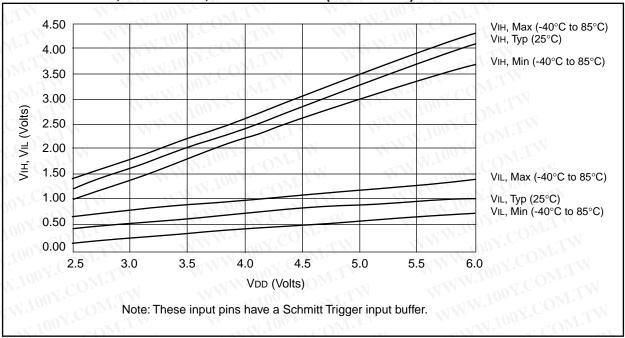


FIGURE 16-11: VTH (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (IN XT, HS, AND LP MODES) VS. VDD

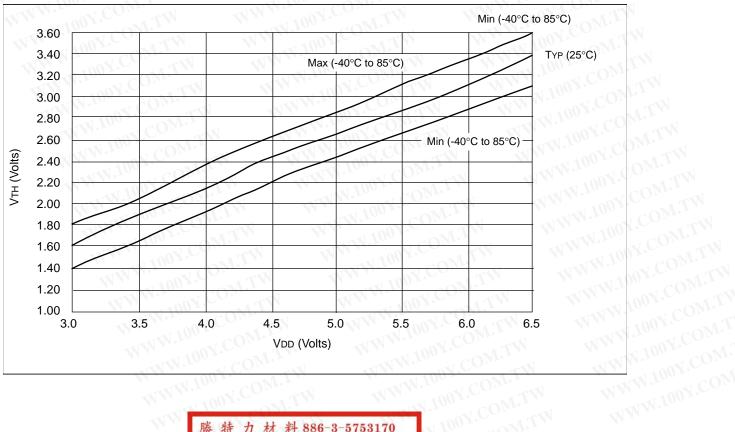
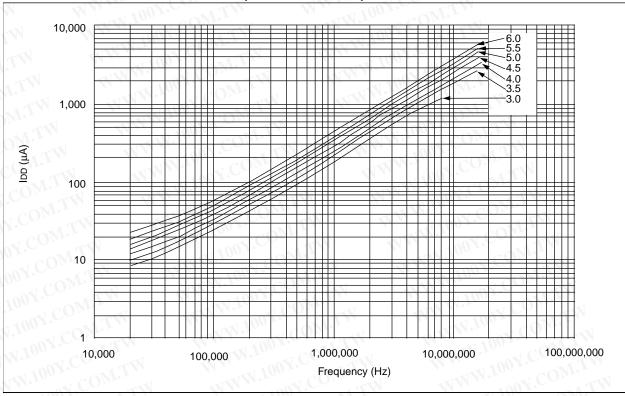


FIGURE 16-12: TYPICAL IDD vs. FREQ (EXT CLOCK, 25°C)





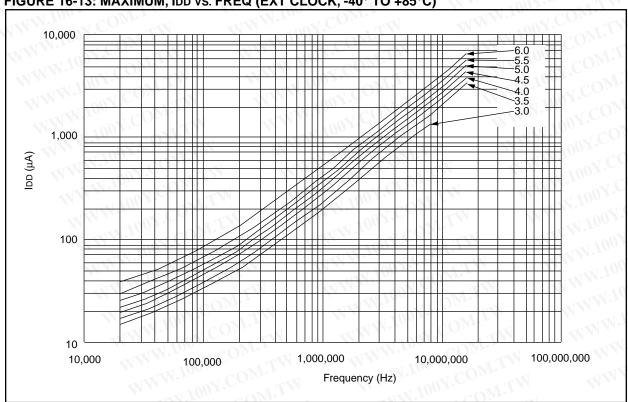


FIGURE 16-14: MAXIMUM IDD vs. FREQ WITH A/D OFF (EXT CLOCK, -55° TO +125°C)

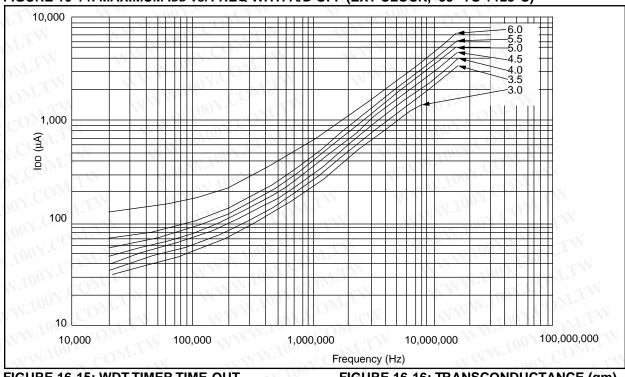


FIGURE 16-15: WDT TIMER TIME-OUT PERIOD vs. VDD

50 45 40 35 Max, 85°C WDT Period (ms) Max, 70°C 30 25 20 Typ, 25°C Min, 0°C 15 10 Min, -40°C 5 2 3 VDD (Volts)

FIGURE 16-16: TRANSCONDUCTANCE (gm)
OF HS OSCILLATOR vs. VDD

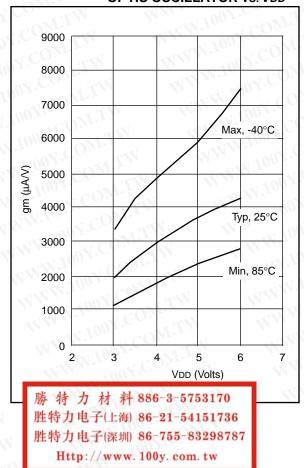


FIGURE 16-17: TRANSCONDUCTANCE (gm)
OF LP OSCILLATOR vs. VDD

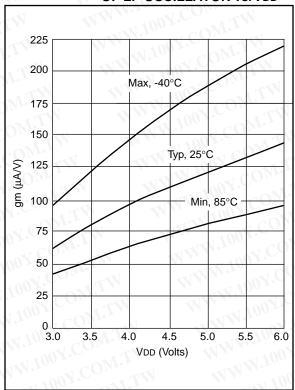


FIGURE 16-18: TRANSCONDUCTANCE (gm)
OF XT OSCILLATOR vs. VdD

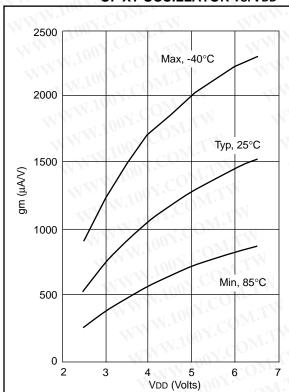


FIGURE 16-19: IOH VS. VOH, VDD = 3V

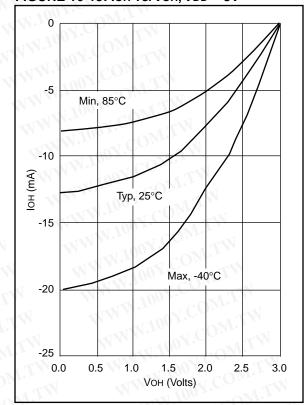


FIGURE 16-20: IOH VS. VOH, VDD = 5V

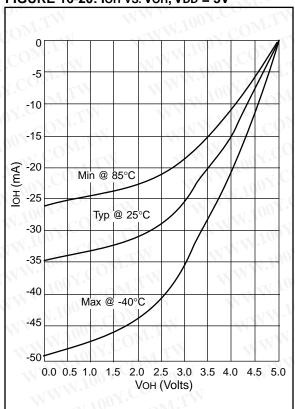


FIGURE 16-21: IOL VS. VOL, VDD = 3V

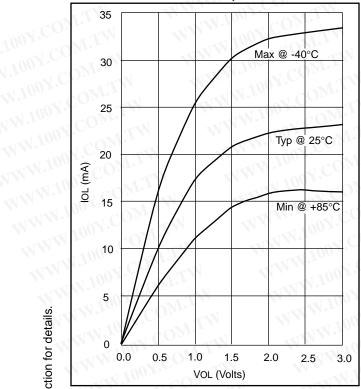
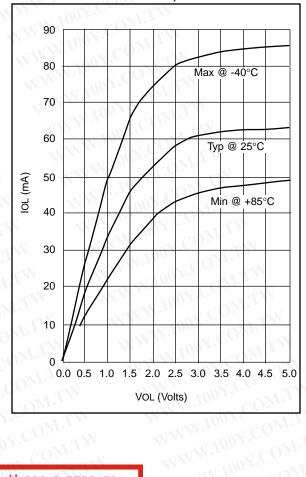


FIGURE 16-22: IOL VS. VOL, VDD = 5V

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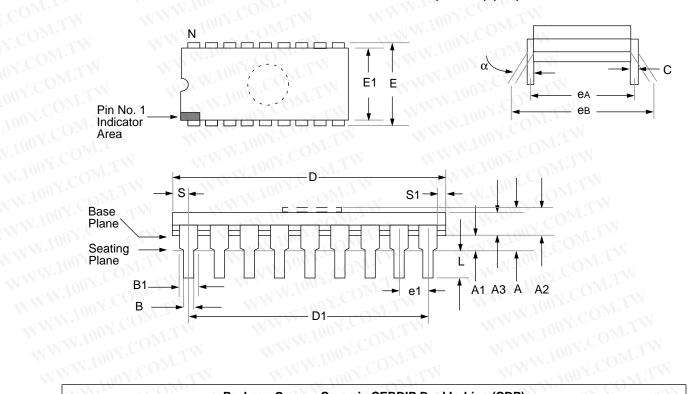
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### 17.0 PACKAGING INFORMATION

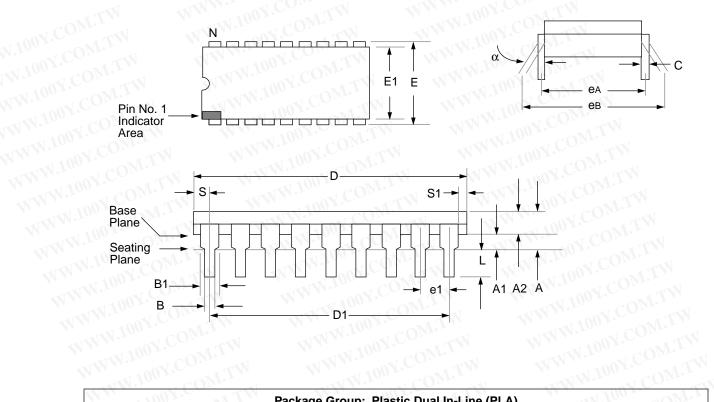
### 17.1 18-Lead Ceramic CERDIP Dual In-line with Window (300 mil) (JW)



	Pa	ckage Group:	Ceramic CERDIP	Dual In-Line (C	DP)	
W.Io	COM	Millimeters	N. T. CO.	Inches		
Symbol	CoMin	Max	Notes	Min	Max	Notes
α	0°	10°	W. M. CC	0°	10°	John Com
A 1.10	W.I	5.080	TOWN TOW	OM.	0.200	· COM
A1	0.381	1.7780	1007.	0.015	0.070	1.100
A2	3.810	4.699	MM 1007	0.150	0.185	11007.
A3	3.810	4.445	WWW.I	0.150	0.175	M. Ce
В	0.355	0.585	W.100	0.014	0.023	M.In. C
B1	1.270	1.651	Typical	0.050	0.065	Typical
C	0.203	0.381	Typical	0.008	0.015	Typical
D	22.352	23.622	T.WW.L	0.880	0.930	WW.
D1	20.320	20.320	Reference	0.800	0.800	Reference
E W	7.620	8.382	MM.	0.300	0.330	W V 100
E1	5.588	7.874	MMM	0.220	0.310	MM
e1	2.540	2.540	Reference	0.100	0.100	Reference
eA	7.366	8.128	Typical	0.290	0.320	Typical
eВ	7.620	10.160	M MM	0.300	0.400	MAL
L	3.175	3.810	NI VI	0.125	0.150	M.M.
N	18	18	1	18	18	TATE OF THE PARTY
S	0.508	1.397	1.11	0.020	0.055	1
S1	0.381	1.270	TW :	0.015	0.050	Al W

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#### 17.2 18-Lead Plastic Dual In-line (300 mil) (P)

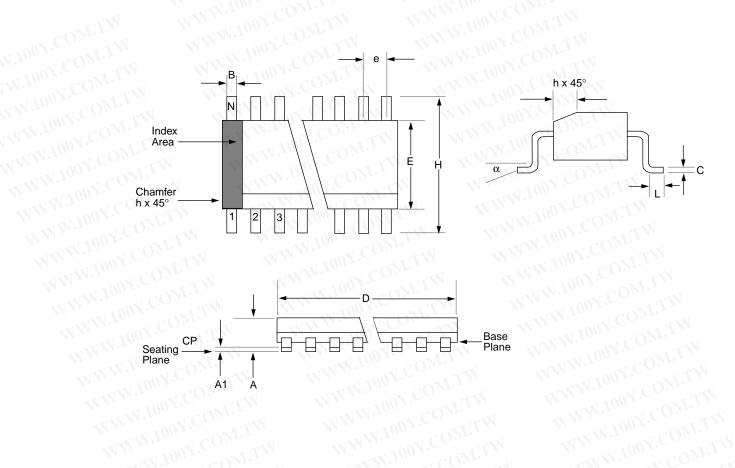


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		Package Gro	up: Plastic Dual	In-Line (PLA)		
100	N.COM.TI	Millimeters	W.1001.	OWITH	Inches	TON T. COM
ymbol	Min	Max	Notes	Min	Max	Notes
α	0° 0°	10°	1007	0°	10°	01.100 2.
Α	CO.	4.064	MAN	WT T	0.160	-1100Y.
A1	0.381		WWW.	0.015	- 111	AM. OOT.C
A2	3.048	3.810	W. 100	0.120	0.150	WW.IOO
В	0.355	0.559	77 10	0.014	0.022	TXV.100 1
B1	1.524	1.524	Reference	0.060	0.060	Reference
С	0.203	0.381	Typical	0.008	0.015	Typical
D	22.479	23.495	WITT.	0.885	0.925	JANN'IO
D1 💉	20.320	20.320	Reference	0.800	0.800	Reference
E	7.620	8.255	WWW	0.300	0.325	MM
E1	6.096	7.112		0.240	0.280	WWW.
e1	2.489	2.591	Typical	0.098	0.102	Typical
eA	7.620	7.620	Reference	0.300	0.300	Reference
eВ	7.874	9.906	W W	0.310	0.390	WW
L	3.048	3.556		0.120	0.140	
N	18	18	TIN	18	18	
S	0.889	· OUTCOR	WT	0.035	1.00 = TV	M.
S1	0.127	1.100 = CO	Mr	0.005	A COL	

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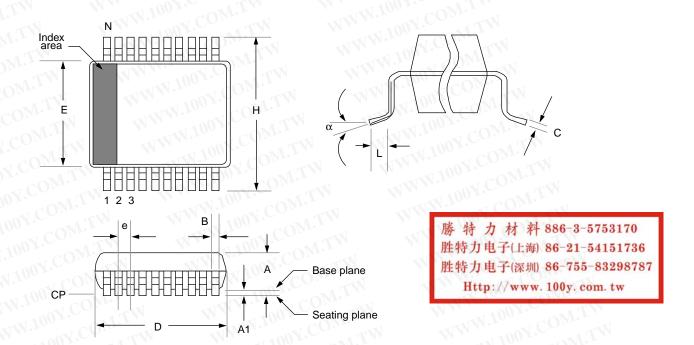
### 17.3 18-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body)(SO)



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V. 100	COM	Package	Group: Plastic So	OIC (SO)	MMM	* CONT.
MMIO	COM	Millimeters	IMM. Jan	OM.,	Inches	. 100 Y.COM
mbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°	TWW.IOU	CO 0°	8°	W. P. CO
Α	2.362	2.642	W.100	0.093	0.104	M.In
A1	0.101	0.300	100	0.004	0.012	W 1001.
В	0.355	0.483	MAIN.	0.014	0.019	100X:
С	0.241	0.318	TWW.IA	0.009	0.013	WW.
D	11.353	11.735	- TVI	0.447	0.462	INN.Inv
E W	7.416	7.595	MM	0.292	0.299	W 100
е	1.270	1.270	Reference	0.050	0.050	Reference
Н	10.007	10.643		0.394	0.419	TWW.I
h	0.381	0.762	N	0.015	0.030	W.1
L	0.406	1.143	M. M.	0.016	0.045	WW.
N	18	18	W W	18 C	18	MMA
CP	- xv.1	0.102	4.	M. 100	0.004	TXVV

### 17.4 20-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)

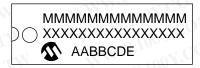


WWW.	TOO N.	Packa	ge Group: Plasti	c SSOP	MM	100 Y.C
VWW		Millimeters	WWW.100	Y.COM.	Inches	
Symbol	Min CO	Max	Notes	Min	Max Max	Notes
α	0°	8°	M.M.In	0°	8°	MMila
Α	1.730	1.990	111.1	0.068	0.078	W.100
A1 🕥	0.050	0.210	MM	0.002	0.008	10
В	0.250	0.380	MININ	0.010	0.015	M.M.
С	0.130	0.220		0.005	0.009	WWW.
D	7.070	7.330	N 1	0.278	0.289	TIW.
E	5.200	5.380	N WW	0.205	0.212	MM
е	0.650	0.650	Reference	0.026	0.026	Reference
Н	7.650	7.900		0.301	0.311	
L	0.550	0.950	In w	0.022	0.037	W.
N	20	20	TW	20	20	M
CP		0.102	-31	TINIA . IO	0.004	XX

- Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25m/m (0.010") per side. D1 and E1 dimensions including mold mismatch.
  - Dimension "b" does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08m/m (0.003")max.
  - 3: This outline conforms to JEDEC MS-026.

### 17.5 Package Marking Information

### 18-Lead PDIP



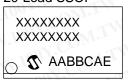
### 18-Lead SOIC



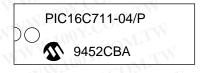
### 18-Lead CERDIP Windowed



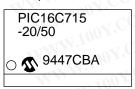
### 20-Lead SSOP



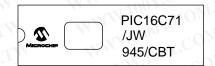
### Example



### Example



### Example



### Example



Legend:	MMM	Microchip part number information
	XXX	Customer specific information*
	AA	Year code (last 2 digits of calender year)
	BB	Week code (week of January 1 is week '01')
	100Y.CO	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A.
	D <sub>1</sub>	Mask revision number for microcontroller
	N.1607.C	Assembly code of the plant or country of origin in which part was assembled.
Note:	line, it will	nt the full Microchip part number cannot be marked on one be carried over to the next line thus limiting the number of characters for customer specific information.

<sup>\*</sup> Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

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### APPENDIX A:

The following are the list of modifications over the PIC16C5X microcontroller family:

- Instruction word length is increased to 14-bits.
   This allows larger page sizes both in program memory (1K now as opposed to 512 before) and register file (68 bytes now versus 32 bytes before).
- A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
- 3. Data memory paging is redefined slightly. STATUS register is modified.
- Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW.
   Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
- OPTION and TRIS registers are made addressable.
- Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. Reset vector is changed to 0000h.
- Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
- Wake up from SLEEP through interrupt is added.
- 11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt on change feature.
- 13. TOCKI pin is also a port pin (RA4) now.
- 14. FSR is made a full eight bit register.
- "In-circuit serial programming" is made possible.
   The user can program PIC16CXX devices using only five pins: VDD, VSS, MCLR/VPP, RB6 (clock) and RB7 (data in/out).
- 16. PCON status register is added with a Power-on Reset status bit (POR).
- Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
- 18. Brown-out protection circuitry has been added. Controlled by configuration word bit BODEN. Brown-out reset ensures the device is placed in a reset condition if VDD dips below a fixed setpoint.

### APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

- Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- Change reset vector to 0000h.

### APPENDIX C: WHAT'S NEW

Consolidated all pin compatible 18-pin A/D based devices into one data sheet. WWW.100Y.COM.TW

### APPENDIX D: WHAT'S CHANGED

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- Minor changes, spelling and grammatical changes.
- Low voltage operation on the PIC16LC710/711/ 2. 715 has been reduced from 3.0V to 2.5V.
- Part numbers of the PIC16C70 and PIC16C71A have changed to PIC16C710 and PIC16C711, respectively. WWW.100Y.COM.T

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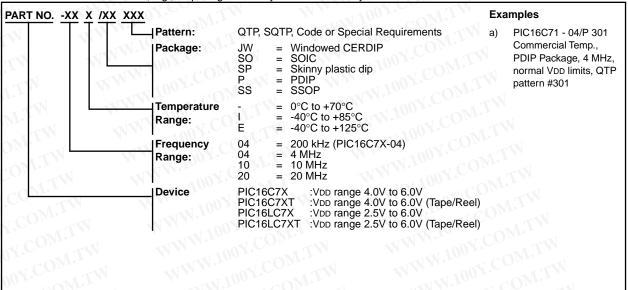
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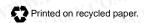
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